# CRYSTAL OSCILLATOR CIRCUITS

Revised Edition

Robert J. Matthys



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## BACKGROUND

Crystal oscillators were invented in the 1920s. Cady made one of the first ones in 1921. Miller patented both his own and Pierce's circuits in 1930 [1]. Pierce patented both his own and Miller's circuits in 1931 [2], and after some legal arguing in the courts, Pierce repatented both circuits again in 1938 [3]. Sabaroff's quartz crystal version of the Colpitts LC oscillator was published in 1937 [4], and Meacham's resistance bridge circuit was published in 1938 [5]. Butler published his article on VHF harmonic oscillators in 1946 [6]. Goldberg and Crosby published their article on cathode coupled or grounded grid oscillators in 1948 [7].

The U.S. Army Signal Corps funded an intense quartz crystal development program during and after World War II and funded a small amount of oscillator circuit development along the way. Edson did a study of VHF harmonic oscillator circuits in 1950 [8] and published his classic book on vacuum tube oscillators of all types in 1953 [9]. In 1965, Firth published his design handbook [10] on the Pierce circuit and the Butler common base harmonic circuit.

The early oscillators used vacuum tubes, which had limited life and were, therefore, high-maintenance items. Consequently, there was a considerable advantage in using a one-tube oscillator circuit, as compared with a two-tube circuit. Strong emphasis was placed on getting the maximum power out of the oscillator circuit, since this meant that fewer power amplifier tubes were required in a transmitter. Vacuum tubes operated at power supply voltages of 150-300 VDC, which permitted large voltage swings and made it extremely easy to overdrive the crystal's dissipation limit or even fracture the crystal.

With the advent of transistor and IC circuits, the emphasis was placed on performance. Transistors are very small and have indefinite life, so in many cases, the number of transistors used in an oscillator circuit is al-

1

#### BACKGROUND

most irrelevant. The lower power supply voltage used in transistor circuits has reduced the crystal overdrive problem to more manageable proportions. And to get better frequency stability, oscillator circuits are now routinely designed with low power output, since it costs so little to add an amplifier stage.

### QUARTZCRYSTALS

This chapter covers the electrical characteristics of quartz crystals from a circuit design standpoint. For information on their mechanical characteristics or on the manufacturing process, the reader is referred to any standard text on quartz crystals.

Quartz exhibits a piezoelectric effect, that is, applying a voltage to the opposing surfaces of a piece of properly oriented quartz will make it change shape mechanically (and vice versa). A quartz crystal is a small, thin piece of quartz with two opposite surfaces metallized to make electrical connections. Its physical dimensions are tightly controlled since they control oscillation frequency.

Although there are many crystal cuts, at high frequencies (1 MHz and above), the one most commonly used is the AT cut. An AT-cut crystal is a thin piece of quartz with two parallel or slightly convex surfaces, usually about the size of a nickel or less. Electrical connections are made to the crystal by metallizing the two parallel faces on opposite sides of the crystal. The crystal's resonant frequency is inversely proportional to the crystal's thickness between these two metallized surfaces. Applying a voltage between the two metallized surfaces causes the AT crystal to move sideways internally in a thickness shear movement, as shown in Fig. 2.1. The traditional equivalent circuit using lumped constant elements for the crystal is shown in Fig. 2.2. Inductance  $L_x$  and series capacitance  $C_0$  is the capacitance between the two metallized surfaces used as electrode contacts on the crystal and runs about 3-15 pF for most crystals.

The series resistance  $R_s$  of a typical crystal of any type of cut varies from about 10  $\Omega$  at 20 MHz, to a few hundred ohms at 1 MHz, up to a few thousand ohms at 100 kHz, and up to 200,000  $\Omega$  at 1 kHz. Table 2.1



Figure 2.1. Shear motion of an ATcut crystal at fundamental resonance.

shows some measured values of  $L_x$ ,  $C_x$ ,  $C_0$ , and  $R_s$  for several crystals.

The lowest fundamental frequency available in a quartz crystal is about 1 kHz. The highest fundamental frequency is about 20-25 MHz, above which the crystal becomes too thin and delicate to be handled. Oscillation can be continued to about 200 MHz by operating the crystal on its third, fifth, seventh, or ninth harmonic. A crystal's series resistance increases with the harmonic, from about 40  $\Omega$  at 20 MHz to about 200  $\Omega$  at 200 MHz.

Figure 2.3 shows the maximum series resistance of quartz crystals over a frequency range of 1 kHz-200 MHz. These data are taken from several specifications, so more than one limit is shown at some frequencies. A typical crystal will have about two-thirds the maximum resistance specified in Fig. 2.3. This wide variation in series resistance from 10 to 200,000  $\Omega$  is the largest single factor in oscillator design and dominates the design of every oscillator circuit.

Figure 2.4 shows the maximum drive power that can be put into a crystal without excessive heating and frequency shift in the crystal, Figure 2.5 shows the maximum permissible drive voltage across the crystal *at exact series resonance*. Figure 2.5 is derived from the series resistance and maximum power data given in Figs. 2.3 and 2.4. Figures 2.3-2.5 apply to crystals of all common types of cuts mounted in a gas-filled container. Note that in Fig. 2.5 the maximum crystal voltage falls off rapidly above ] MHz. This maximum voltage curve is a useful design tool.



Figure 2.2. Equivalent circuit for a quartz crystal near fundamental resonance.

Some Measu	ured Quartz C	rystal Parai	neters	
Frequency	$L_x$ (H)	$C_x (\mathrm{pF})$	$R_s(\Omega)$	$C_{\mathfrak{o}}\left(\mathbf{pF} ight)$
4 kHz 50 kHz 100 kHz 1 MHz 20 MHz (3d harmonic) 50 MHz (3d harmonic) 100 MHz (5th harmonic)	52. 4.2 0.0098 0.053	0.049 0.0060 0.026 0.0012	45,000 20,000 400 240 5	15. 9. 8. 3.4 8.5 5.6 4.2 5.7

Since crystals frequently operate slightly off resonance, measuring the voltage across the crystal is meaningless as a measure of current through the crystal. The practical solution is to measure the current through the crystal by means of the voltage drop across a series element and calculate the crystal's power dissipation by  $I^2R_s$ , where Z is the current through the crystal and  $R_s$  is the crystal's internal series resistance.

At frequencies above about 2 MHz, the AC voltage swing from an



Figure 2.3. Maximum crystal series resistance  $R_s$  as a function of frequency.



Maximum crystal power dissipation as a function of frequency. Figure 2.4.

oscillator circuit operating from a 5 V power supply can be higher than what should be put across the crystal at series resonance. An amplitude-limiting scheme is frequently needed to take care of this problem.

There is no difference in the construction of a *series-resonant crystal* and a *parallel-resonant* crystal, which are manufactured exactly alike. The only difference between them is that the series-resonant frequency of the parallel-resonant crystal is set 100 ppm or so lower than the desired operating frequency. Parallel resonance means that a small capacitance of 32 pF or so should be placed across crystal terminals to obtain the desired operating frequency. This presumes that the external load across the crystal's terminals has a high impedance. If the external load across the crystal's terminals has a low impedance, then parallel resonance means that a small capacitance of 32 pF or so should be placed



Figure 2.5. Maximum crystal-drive voltage at series resonance as а function of frequency.

in series with the crystal and its low-impedance load to obtain the desired operating frequency.

Putting an external capacitor in series with the crystal's internal motional capacitance  $C_x$  reduces the net total series capacitance of the two and thereby raises the crystal's series-resonant frequency. In practice, specifying parallel resonance simply tells the manufacturer to, set the crystal's series resonance a little lower than the frequency requested by the user, so that when the crystal is put in series with (or parallel with) a small capacitor, the crystal's resonant frequency will be what the user wants.

The AT cut offers a lot of advantages over other crystal cuts and has been brought to a high state of perfection. Warner and others at Bell Telephone Laboratories developed two outstanding AT crystal designs at 2.5 and 5 MHz for use in high-performance frequency standards. Both operate on the fifth harmonic. The 2.5-MHz crystal uses a large quartz blank 30 mm in diameter. Several papers published by the group at Bell Labs on crystal designs and the oscillator circuits used with them are listed in the reference and bibliography sections in this book.

Among many items of interest, Warner [11, 123 and Bömmel et al. [13, 14] reported the following on AT crystals:

- 1. Crystals operate differently in a vacuum than in air.
- 2. The series resistance of a crystal is 3 times lower in vacuum than in air, with a corresponding improvement in Q. Above 30 MHz, there is no measurable difference in Q between operations in air or vacuum.
- 3. The maximum attainable crystal Q is an inverse function of frequency. It is also a function of the diameter and surface curvature of the crystal blank.
- 4. Harmonic operation gives improved Q when the crystal is operated in air. In a vacuum, the crystal's Q is the same for either fundamental or harmonic operation.
- 5. A glass container for the crystal gives less long-term frequency drift than a metal container.

The internal series resistance of the large high-Q 2.5-MHz crystal was 65  $\Omega$ . Since this varies as the cube of the harmonic, the crystal's internal resistance would be  $\frac{1}{27}$  of 65 or 2.4  $\Omega$ , if it were operated in a fundamental mode at 2.5 MHz. A value of 2.4  $\Omega$  is too low a load resistance for a transistor amplifier stage to drive easily. Warner [11] points out that this is one of the main reasons for operating a high-Q crystal at a harmonic

frequency-the crystal's internal series resistance is higher and much easier for a transistor amplifier stage to drive.

If we want to electrically pull a crystal off frequency with a variable capacitance diode or other means, it should be done at the crystal's fundamental frequency. The crystal will be much harder to pull off frequency and will not pull so far (percentagewise) when operated at a harmonic frequency, because of the crystal's greater phase shift with a given change in frequency.

### FUNDAMENTALS OF CRYSTAL OSCILLATION

#### 3.1. OSCILLATION

A circuit will oscillate if it has positive feedback and a loop gain greater than 1. With a crystal as a series element in the loop and no other frequency-sensitive elements in the circuit, it will oscillate at the crystal's fundamental series-resonant frequency. A quartz crystal always wants to oscillate at its fundamental frequency and must be forced to oscillate at a harmonic.

When the oscillator circuit's feedback loop is first closed, sine wave oscillation begins, and the amplitude increases until overload occurs. The waveform at overload becomes a clipped sine wave and finally approaches a square wave at heavy overload. Crystal oscillators can usually provide either a square wave or a sine wave output. The signal driving the crystal is most often a square wave, and the signal out of the crystal is always a sine wave. Either waveform can be used for an **output** by tapping the appropriate point in the circuit.

#### 3.2. SERIES RESONANCE VERSUS PARALLEL RESONANCE

There is no such thing as a parallel-resonant crystal oscillator. All crystal oscillators operate either at or near (above or below) series resonance. What is usually meant by parallel resonance is that the crystal has a high load impedance across its terminals. This is in contrast to series resonance, which usually means that the crystal has a low load impedance across its terminals. Series resonance physically **exists** in the crystal, but

parallel resonance exists only as a crystal *measurement* phenomenon. When the impedance of a crystal is measured externally as a function of frequency, an impedance peak will be found above series resonance, where part of the crystal's motional inductance  $L_x$  parallel resonates with the crystal's shunt terminal capacitance  $C_0$ .

From a circuit viewpoint, the crystal's shunt terminal capacitance  $C_0$  should be considered as part of the external load on the crystal and not as part of its internal frequency-controlling  $L_x$  and  $C_x$  elements. Experimental data confirming this viewpoint are given later. When parallel resonance is mentioned in this book, it will have the usual meaning that the crystal has a high load impedance across its terminals, and not that the crystal is oscillating at the higher frequency where the crystal's input impedance peak occurs.

#### 3.3 BASIC CRYSTAL CIRCUIT CONNECTIONS

How should a quartz crystal be connected in an oscillator circuit? What load impedance should it see? These are key questions in the design of an oscillator circuit. For a crystal to control the frequency of an oscillator circuit, the crystal must maximize the oscillator's gain at the oscillation frequency and minimize it at all other frequencies. It is well-known that a crystal's impedance goes to a minimum at series resonance and to a maximum at parallel resonance. The design question is how best to take advantage of this and give the crystal maximum control of the oscillation frequency.

One approach is to connect the crystal as a series element in the oscillator circuit, as shown in Fig. 3.1. The crystal acts as part of a voltage divider with the resistor  $R_{\text{load}}$  and operates at series resonance with zero phase shift through the voltage divider. The gain  $E_0/E_i$  through the



Figure 3.1. Typical crystal series connection: (a) circuit and (b) circuit gain versus frequency.



Figure 3.2. Typical series oscillator circuit,

voltage divider reaches a maximum of something less than 1.0 at series resonance, as shown in Fig. 3.1.

Figure 3.2 shows a typical oscillator circuit using the crystal as a series element. To give the crystal maximum control of the loop gain, the crystal must have maximum control of the voltage divider, which means that both the source and load resistances shown in Fig. 3.2 should be small with respect to the crystal's impedance at series resonance; that is, they should be smaller than the internal series resistance  $R_s$  of the crystal.

An alternative way of looking at the series circuit in Fig. 3.2 is that the amplifier's output puts a voltage across the crystal, and the amplifier's input samples the current through the crystal, which is a maximum at series resonance. Again, the crystal will have maximum control of the loop gain when both  $R_{\text{source}}$  and  $R_{\text{load}}$  are small with respect to the crystal's internal series resistance  $R_{,.}$ 

Another design approach is to connect the crystal as a shunt element, as shown in Fig. 3.3. The crystal is again part of a voltage divider. Here, the voltage divider's series element has to be a capacitor or inductor and *cannot* be a resistor. Figure 3.3 shows a capacitor  $C_1$  as the series element of the voltage divider. Putting the capacitor  $C_1$  in series with the crystal raises the oscillation frequency slightly above the crystal's series-resonance frequency. The voltage divider's gain  $E_0/E_i$  at the oscillation frequency peaks at about 10–15X, as shown in Fig. 3.3, because the circuit resonates at this frequency. There is a 90" phase lead through the voltage divider at the oscillation frequency at the peak of the gain curve. To use this shunt network in an oscillator circuit requires adding another 90" phase-lead (or lag) network into the circuit.

Figure 3.4 shows a shunt oscillator circuit with a 90° phase-lead network, using the inductor L and the amplifier's output resistance  $R_{\text{source}}$  to provide the phase lead. This is the Miller circuit.



Figure 3.3. Typical crystal shunt connection: (a) circuit and (b) circuit gain versus frequency.

Figure 3.5 shows a shunt oscillator circuit with a 90" phase-lag network, using a shunt capacitor  $C_2$  and the amplifier's output resistance  $R_{\text{source}}$  to provide the phase lag. This is the Colpitts circuit. Note that the phase-lead network requires using an inverting amplifier, while the phase-lag network requires a noninverting amplifier. The crystal's load resistance  $R_{\text{load}}$  must be high in both Figs. 3.4 and 3.5 to give the crystal maximum control of the voltage divider's gain.

In actual practice, the phase-lead and lag networks used in shunt circuits generate a little less than 90° of phase shift. This does not matter because the circuit's oscillation frequency will simply move slightly off the amplitude peak shown in Fig. 3.3, changing the phase shift through the voltage divider enough to compensate for the less-than-90° phase shift of the lead and lag networks.

The need for low load and source resistances on the crystal for series operation and a high load resistance on the crystal for shunt operation is typical of crystal oscillator circuits. How low and how high these resistances should be to give good in-circuit Q is an important design



Figure 3.4. Typical shunt oscillator circuit, with 90" lead network (Miller).



Figure 3.5. Typical shunt oscillator circuit, with 90" lag network (Colpitts).

parameter that affects the circuits' short-term frequency stability. This subject is discussed in detail in Sections 4.2, 6.1, and 6.2.

#### 3.4. CRYSTAL RESPONSE TO A STEP INPUT

What happens to a crystal when it is driven by a square wave? Most series-resonant oscillator circuits put a square wave of voltage across the crystal and sample the current through the crystal by means of a resistor in series with it. The current signal is then fed into the amplifier input. The relationship between the voltage across the crystal and the current through it is important for understanding how the series-resonant oscillator circuit works. This can be understood by first looking at how the crystal responds to a step input and then extending this to a periodically reversing step input; that is, a square wave.

A simplified equivalent circuit for the crystal at its fundamental series resonance is the series RLC network, as shown in Fig. **3.6***a*. The crystal's shunt terminal capacitance  $C_0$  is ignored here. A current-sampling resistor  $R_{\text{ext}}$  is added in series with the crystal, and the crystal is driven by a step input of voltage  $E_i$ . For simplicity, the two series resistors  $R_s$  and  $R_{\text{ext}}$  are combined into one R. The relationship between the applied voltage and resulting crystal current is given by the Laplace transform,

$$\overline{G}(s) = \frac{\overline{e}_i(s)}{\overline{i}(s)} = \frac{Ls^2 + Rs + 1/C}{s}$$

For a voltage step input,

$$\overline{e}_i(s) = \frac{1}{s}$$

13









Figure 3.6. Crystal response to a square wave drive.

Using the inverse transform, the transient solution for the output voltage across  $R_{ext}$  is

$$E_0 (t) = i (t) R_{\text{ext}} = \frac{R_{\text{ext}} e^{-t/(2RL)} \sin \left[\sqrt{C/L - 1/(4R^2L^2)} t\right]}{\sqrt{C/L - 1/(4R^2L^2)}}$$

The significance of this equation is that the current through the crystal is a (damped) sine wave and phased so that its starting point at the  $0^{\circ}$  phase-angle position is time coincident with the start of the step input, as shown in Fig. 3.6b. If the step input is reversed (i.e., dropped back to zero) every time the current sine wave goes to zero at 180" and 360°, the exponential decay term drops out, and the transient solution becomes the steady-state solution. The phase relationship between the input square wave of voltage and the output sine wave of current then becomes as shown in Fig. 3.6c. Note that there is no phase shift between them.

If the sine wave of crystal current is fed into an amplifier with enough gain so that the amplifier output saturates and makes a square wave out of the sine wave and if this square wave is used to drive the crystal as shown in Fig. 3.6*d*, then conditions for a periodically reversed step input are obtained, and there is continuous oscillation in the crystal. If the crystal and its amplifier circuit are actually built as shown in Fig. 3.6*d*, the sine and square wave waveforms observed will be seen to have the same polarity and phasing as shown in Fig. 3.6*c*. This concept of zero phase shift between the crystal's square wave input and its sine wave output underlies the operation of the series-resonant oscillator circuit.

### CIRCUIT DESIGN CHARACTERISTICS

The most **important** parameters in designing a crystal oscillator circuit are :

- **1.** Crystal's internal series resistance  $R_s$ .
- 2. Load impedance across the crystal terminals.
- 3. Oscillator's loop gain.
- 4. Reduced crystal voltage limits above 1 MHz.
- 5. DC biasing of the transistor and IC amplifier stages.
- 6. Transistor's high-frequency gain limit  $f_T$ .

Note that three of the six circuit design parameters are crystal related. Each of these parameters is discussed in the following sections.

#### 4.1. CRYSTAL'S INTERNAL SERIES RESISTANCE R.

The design of an oscillator circuit is overwhelmingly dominated by the crystal's internal series resistance  $R_s$ —far more than by any other parameter. A crystal's series resistance  $R_s$  varies from a low of 10  $\Omega$  at 20 MHz to 200,000  $\Omega$  at 1 kHz. The problem comes in providing the wide range in load resistance required to match the wide range in the crystal's series resistance  $R_s$ . For series resonance, the crystal's load resistance is usually set equal to or somewhat less than the crystal's internal series resistance  $R_s$ , in order to get good in-circuit Q. For parallel resonance, the

load resistance has to be much higher, up to 500  $M\Omega$  at 1 kHz, to get good in-circuit Q.

Considerable variation in circuit design is required to provide such a wide variation in the crystal's load resistance. At high frequencies, emitter follower outputs will provide low-resistance sources and loads. At medium frequencies, transistor bases and collectors, FET source follower outputs, and FET drains will all provide medium-resistance sources and loads. And at low frequencies, FET gates will provide high-resistance loads. The gain of a FET amplifier stage is about an order of magnitude less than that of a bipolar transistor stage, so that a second amplifier stage is usually required whenever a FET is used.

#### 4.2. LOAD IMPEDANCE ACROSS THE CRYSTAL TERMINALS

The external load tied across the crystal terminals has a considerable effect on the crystal's frequency and its frequency stability. The oscillation current through the crystal's internal frequency-controlling elements  $L_x$  and  $C_x$  passes out of and back into the crystal through the crystal terminals. The crystal is driven by putting a voltage source in series with this current loop. The resulting current through the crystal's frequency-controlling elements is measured by sampling the voltage drop across a series element in the loop.

Ignoring the crystal's shunt terminal capacitance  $C_0$ , putting an inductor or capacitor in series with the crystal's terminals will put the inductor or capacitor in series with the current flowing through the crystal's internal frequency-controlling elements  $L_x C_x$ . This changes the total net series inductance or capacitance in the current loop and the loop's resonant frequency. Putting a small variable capacitor in series in this loop is a common method of trimming oscillator frequency. Whether or not the crystal's shunt terminal capacitance  $C_0$  can be ignored depends, of course, on the relative impedance of the series inductor or capacitor with respect to the impedance of  $C_0$ .

If a low-impedance load is used across the crystal terminals, the circuit is called series resonant. This low impedance has to include the complete external circuit impedance seen by the crystal, looking at the circuit from the crystal terminals. This includes the output resistance of the drive amplifier, the current-sampling load resistor, and the input resistance of the amplifier's input.

If a high load impedance is used across the crystal terminals, the circuit is called parallel resonant. The crystal has a shunt terminal capacitance  $C_0$  of its own, amounting to 3-15 pF. This shunt terminal capacitance  $C_0$  is part of the external load on the crystal as far as the crystal's

internal frequency-controlling elements  $L_x$  and  $C_x$  are concerned. The impedance of  $C_0$  normally defines the highest load impedance that can be put across the crystal terminals, although at high frequencies (above 50–70 MHz), it is parallel resonated with an inductor to remove it from the circuit.

Tying a resistive load  $R_{load}$  across the crystal terminals gives a total paralleled RC load of  $R_{load}$  and  $C_0$  across the crystal's frequencycontrolling elements  $L_x$  C. To determine loading effects on the crystal, it is convenient to convert this paralleled RC load combination to its equivalent series values of  $R_{series}$  and  $C_{series}$ . The load the crystal wants to see is the smallest possible equivalent series load resistance  $R_{series}$ , since this resistance reduces both the in-circuit Q and short-term frequency stability. In practice, if good oscillator performance is to be obtained, the equivalent series load resistance  $R_{series}$  should be made equal to or somewhat less than the crystal's internal series resistance  $R_s$ .

The equivalent series load capacitance  $C_{\text{series}}$  is in series with the crystal's frequency-determining motional capacitance. Like any two capacitors in series, the effect of  $C_{\text{series}}$  is to reduce the net series capacitance in the crystal circuit and raise the resonant frequency. Besides raising the resonant frequency, the crystal itself does not seem to care about this external series capacitance. If the equivalent series load is inductive rather than capacitive, the inductance is in series with the crystal's frequency-determining motional inductance. And as is the case with any two inductors in series, the total net series inductance is raised, which lowers the resonant frequency accordingly.

In a series-resonant circuit such as shown in Fig. 3.2, the crystal with its internal series resistance  $R_s$  acts as a voltage divider with the load resistance  $R_L$ . A tradeoff must be made here between maximum incircuit Q and a minimum gain loss. If the load resistance  $R_L$  is made very small for better Q, then a large gain loss is introduced by the voltage divider, which has to be compensated for by a larger amplifier gain. A good compromise is to make the load resistance  $R_L$  equal to one-half the crystal's internal series resistance  $R_s$ , and the source resistance  $R_s$ . Then, the crystal's internal Q, which is limited by its internal series resistance  $R_s$ , is only degraded in the circuit by a factor of 2 to 1. The gain loss through the crystal's voltage divider network is then only 4 to 1.

#### 4.3. OSCILLATOR LOOP GAIN

A crystal oscillator does not need much loop gain. Overall loop gain values of 2-10X are sufficient, and a gain' of 4-5X is about optimum. The



Figure 4.1. Diode amplitude clamp.

crystal and the network surrounding it usually have a gain loss of 1.5-50X, so the amplifier used has to provide a gain of 3-200X. With only a few exceptions, one or two transistors will provide more than enough gain for any oscillator circuit. A single transistor stage can provide a maximum gain of about 70X, so many oscillator circuits use only one transistor. The network around the crystal is frequently adjusted to keep its losses within the gain limits of a single transistor stage.

#### 4.4. REDUCED CRYSTAL VOLTAGE LIMITS ABOVE 1 MHz

Because of the crystal's dissipation limit, there is a maximum operating voltage that can be put across the crystal. This maximum operating voltage varies with frequency. Figure 2.5 is a graph of the maximum voltage that can be put across a crystal of any frequency at its series resonance. Assuming the usual square wave drive, a crystal-drive amplitude of 2 Vrms or 4 Vp-p can be used at all frequencies below 1 MHz. Figure 2.5 shows that from 1 to 20 MHz the maximum crystal-drive level drops from 4 Vp-p down to about 0.3 Vrms or 0.6 Vp-p and remains at that level to 100 MHz. From 100 to 200 MHz, maximum crystal-drive voltage rises again to about 1.2 Vp-p at 200 MHz.

With a 5 V power supply, about 4 Vp-p is the normal circuit signal level expected with saturated transistor operation. What this means is that in order to use a 5 V power supply at frequencies above 1 MHz, some sort of voltage limiter must be used to minimize crystal heating and prevent excessive frequency drift. With discrete transistor circuits, the

voltage swing at the collector can be limited to almost any level by adjusting the transistor's emitter resistor. Another possibility is to use ECL circuitry, where the voltage swing is limited to 0.8 Vp-p.

Amplitude-limiting schemes can be rather elaborate. A simple and effective approach is Harrison's method [15] of using two paralleled diodes in series with a capacitor (for DC voltage isolation), as shown in Fig. 4.1. Two signal diodes such as the 1N4148 will clamp the amplitude at 1.2 Vp-p. Two Schottky diodes such as the 1N5711 will clamp at 0.8 Vp-p. Both clamping levels are useful in practice.

The maximum crystal voltage curve given in Fig. 2.5 is a power dissipation limit and applies at exact series resonance only. If the crystal is operated off series resonance, then the applied voltage can be increased. Moving the crystal off series resonance by 4 ppm will increase the crystal's impedance to about four times its series resistance value and will quadruple the voltage that can be applied without exceeding the crystal's dissipation limit. In most oscillator circuits, the frequency is adjustable, so that it is difficult to tell beforehand whether the crystal will be operating at series resonance or not. The conservative approach is to set the voltage amplitude at a safe level for operation at exact series resonance. One unfortunate fallout of the crystal's limit at high frequencies is that an amplifier stage is frequently required at the oscillator's output to boost up the oscillator's low signal level to a usable logic level.

#### 4.5. DC BIASING OF TRANSISTOR AND IC AMPLIFIER STAGES

If a transistor or IC is not biased to an operating point within its linear region when power is applied, oscillation will not start. Proper biasing is the key to solving the no-start problem that plagues some oscillators. Biasing is discussed in detail in Chapter 9.

#### 4.6. TRANSISTOR HIGH-FREQUENCY GAIN LIMIT $f_{T}$

Starting at some frequency in the 1–100 MHz range, the gain of a bipolar transistor falls off with increasing frequency at approximately 6 dB/ octave, due to the RC roll-off of the intrinsic resistance of the transistor's base material and the base-to-emitter's junction capacitance. On the transistor data sheets, this is specified by the frequency  $f_T$ , where the transistor's current gain has dropped down to 1, and no amplification can

Transistor	<b>h</b> <sub>FE</sub> Minimum (@I <sub>c</sub> , mA)	I, Average <b>(max, mA)</b>	f <sub>r</sub> Minimum (MHz)	C <sub>сь</sub> Maximum (рF)	t <sub>on</sub> , t <sub>ott</sub> (max nsec)	R <sub>b</sub> C <sub>c</sub> Maximum (psec)	V <sub>CEO</sub> Maximum (V)
				npn			
2N2369A	40 @ 10       20 @ 100	200	500	4.0 (output to base)	12, 18		15
2N3509	<b>100 @</b> 10 <b>30 @ 100</b>	-	-	4.0	12, 18	-	2 0
2N3694	100 @ 10	200	200	3.5 (output to base)	-		4 5
2N4265	100 @ 10	200	300	4.0	25, 35		12
2N5179	2 5 <b>@</b> 3	50	900	1.0		14	12
MPS6595	$\left[\begin{array}{c} 25 @ 10 \\ 20 @ 50 \end{array}\right]$	_	1200	1.3	3.3,3.6 (typ)	9 (typical	) 12
MRF517	. 40 <b>@</b> 60	150	2200	4.5 (output to base)			25
MRF525 <sup>a</sup>	60 <b>@</b> 80	150	2200	4.0 (output to base)	—		25
MRF904	30 <b>@</b> 5	3 0	4000 typical	1.0	_		15
MRF905	20 @ 100	150	2500 typical	5.0 (output to base)			20
MRF914	30 @ 20	4 0	4500 typical	1.0			12
				pnp			
2N4208	30 <b>@</b> 10	100	700	3.0 (output to base)	15.20		12
2N4258A	<b>30 @</b> 10	100	700	3.0 (output to base)	15, 18		1 2
2N4957	20 @ 2	3 0	1200	0.8		8	3 0
2N5583	20 @ 40	500	1000	5.0	-	11 (typical	) 30
MM4049	20 @ 2 5	3 0	4000	1.3	_	15	10

 TABLE 4.1

 Some Useful High-Frequency Transistors for Oscillator Circuits

"Case tied to emitter.

	JFET	BV <sub>gss</sub> (V)	l <sub>DSS</sub> Minimum (mA)	g <sub>fs</sub> <sup>b</sup> Minimum (μmho)	C <sub>gd</sub> Maximum (pF)	C <sub>gs</sub> Maximum (pF)
23	2N44 16A	3 5	5	4,500	0.8 (rss)	4. (iss)
	J309	2 5	12	10,000	2.5	5.
	U309 <sup>n</sup>	2 5	12	10,000	2.5	5.

TABLE 4.2						
Some	Useful	N-channel	IFETs for	Oscillator	Circuits	

 ${}^{a}$  Case tied to gate terminal; designed for grounded gate operation.  ${}^{b}g_{fs}$ , common source transconductance.  ${}^{c}g_{fg}$ , common gate transconductance.

occur. If a transistor has a DC current gain of 100 and  $f_T$  of 200 MHz, then 2 MHz is the highest frequency at which the full current gain is available. To make an oscillator at 10 MHz, we need a transistor with  $a f_T$  of 1000 MHz to get a current gain of 100 at 10 MHz; however, in manufacturers' catalogs, the selection of transistors with  $f_T$ 's of 1000 MHz or higher is pretty thin. Table 4.1 lists some useful high-frequency transistors for oscillator circuits.

In contrast to the bipolar transistor, the transconductance (or gain) of a FET is constant up to about 1000 MHz. At frequencies of 10-100 MHz, such FET characteristics as high transconductance, minimum input capacitance, and minimum feedback capacitance (Miller effect) are the important ones. Table 4.2 lists some useful high-frequency FETs for oscillator circuits.

### BASIC OSCILLATOR CIRCUITS

This chapter describes the basic design of different oscillator circuits and how they work. To give the reader a better overall view, a short summary describing each circuit is given first. This preliminary overview is followed by a more detailed description of each circuit. The so-called parallel-resonant (high load impedance) circuits are covered first, followed by series-resonant (low load impedance) types, and then the Meacham bridge. VHF harmonic circuits are described last. Three additional circuits of outstanding performance, two of them bridges and the third a harmonic circuit, are described in the Appendix, having been added later. For simplicity and to avoid obscuring the oscillator concepts, the transistor biasing networks are shown in simplified form only. The actual biasing networks can be seen in the actual circuit schematics in Chapters 10 and 11, and in Appendices A, B, & C.

#### 5.1. OVERVIEW AND CIRCUIT SURVEY

This section gives a brief overview of all the oscillator circuits, with three exceptions. The exceptions are the three circuits located in Appendices A, B & C, and which are described there. Brief concept schematics of all the oscillators, however, including the three circuits in the Appendix, are shown here in Figs. 5.1-5.4. Parallel-resonant circuits are shown in Figs. 5. la-d, and series-resonant circuits in Figs. 5.2a-f. Bridge circuits are shown in Figs. 5.3a-c, and harmonic circuits are shown in Figs. 5.4a-e. Figure captions give a brief summary of each circuit's perfor-



Figure 5.1. Parallel-resonant circuits (high load impedance): (a) Miller-poor circuit; poor frequency stability. (b) Colpitts-good circuit; fair frequency stability. Circuit is far more complex **than** it appears to be; widely used. (c) Low capacitance load-works reasonably well; fair frequency stability. (d) High resistance load-works reasonably well; poor frequency stability.

mance. Many of these circuits have a limited frequency range, due to the wide variation in load and source resistances that a crystal needs to see over the wide frequency range of 1 kHz-200 MHz.

Figure 5.5 shows two circuits **not covered in detail because they have** little to offer. The first is the transformer-coupled circuit in **Fig.** 5.5a. **The** transformer provides a  $180^{\circ}$  phase reversal and allows series-resonant **operation with one transistor instead of two. This had some value in the** 







(c)





Figure 5.2. Series-resonant circuits (low load impedance): (a) Common base works very well; good circuit; good frequency stability. (b) Common base, low frequency-works very well; good circuit. Provides high crystal load resistance needed at low frequencies; good frequency stability. (c) **Two-inverters-IC** works fairly well; fair frequency stability. With **TTL**, oscillates spuriously when crystal is removed; widely used. (d) Emitter coupled-works fairly well; good frequency stability. (e) Pierce-very close to series resonance. One of the best circuits; very good frequency stability, best overall design; widely used. (f) Pierce-IC-close to series resonance. Good circuit; good frequency stability; widely used.



(c)

**Figure** 5.3. Bridge circuits: (a) Feedback bridge, (b) RLC half-bridge, and (c) Meacham. All operate at series resonance, with  $L_1C_1$  resonant at oscillation frequency. All are complex circuits and difficult to design. In-circuit Q is higher than crystal's internal Q, have best short term stability of any circuit type.

vacuum tube era, but today it is more practical to use a second transistor to provide the 180" phase reversal.

The second circuit not covered in detail is the capacitance bridge circuit in Fig. 5.5*b*. This circuit cancels out the crystal's terminal shunt capacitance  $C_0$ , but the cancellation can be done in a simpler fashion by shunting the crystal with an inductance and tuning it to parallel resonance



Figure 5.4. Harmonic circuits: (a) Butler common base-operates at or near series resonance. Fair to poor circuit design. Has parasitics, touchy to tune. Fair frequency stability. (b) Butler emitter follower-operates at or near series resonance. Good circuit design. No parasitics, easy to tune. Good frequency stability. (c) Pierce harmonic-operates IO-40 ppm above series resonance. Good circuit design. Good to very good frequency-stability. (d) Emitter coupled harmonic—operates at or near series resonance. Circuit somewhat complex. Very good frequency stability. (e) Colpitts harmonic-operates 30-200 ppm above series resonance. Physically simple, but analytically complex. Low cost. Fair frequency stability.

with  $C_0$ . Two variations of the  $C_0$  capacitance-bridge cancellation idea at 100 MHz are included in the test circuits, however (see Section 10.19 and 10.24).

#### 5.2. MILLER

The Miller is a parallel-resonant circuit, and a basic schematic is shown in Fig. **5.6a**. The crystal is used as a shunt impedance element to ground. The voltage across the crystal is amplified and inverted by the transistor and fed back to the crystal through a small capacitance  $C_2$ . The collector tank circuit  $L_1C_1$  is tuned to a frequency above resonance, so that the net impedance of  $L_1C_1$  is inductive at the frequency of oscillation. The tank circuit  $L_1C_1$  must be inductive at the frequency of oscillation, or the circuit will not oscillate.  $C_1$  is not necessary for the circuit to oscillate, but it cleans up the waveform across  $L_1$  considerably, which is absolutely awful without the capacitor across it.

The circuit operates as follows. The transistor provides a 180" phase reversal. The tank circuit  $L_1C_1$  is inductive at the oscillation frequency, and together with the collector's output resistance provides a nominal 90° phase lead. And  $C_2$ , together with the crystal operating above resonance as an inductance, provides 90° more phase lead, so that the total phase shift around the loop is zero.

This is not a good oscillator circuit because the waveforms across the crystal are very poor and the frequency is unstable. It turns out that the



Figure 5.5. Two oscillator circuits not covered in detail: (a). transformer coupled and (b) capacitance bridge.

n e da land Nicht e





Figure 5.6. Miller circuit: (a) transistor version and (b) FET version.

frequency of oscillation is quite sensitive to the value of the series feedback capacitor  $C_2$ , which is about 5-40 pF. Because of the Miller effect, the effective value of  $C_2$  consists of the actual capacitor  $C_2$  shown in Fig. 5.6*a* plus the transistor's internal base-to-collector capacitance, both multiplied by the transistor's voltage gain. The gain changes with temperature, power supply voltage, and from transistor to transistor. This means that the effective value of  $C_2$  is not stable, and as a result, neither is the frequency of oscillation.

The transistor version of the Miller circuit will operate at high or medium frequencies, but not at low frequencies. At low frequencies, the resistive loading of the transistor's base input resistance across the high-impedance crystal is so great that the crystal will not oscillate.

The FET version of the Miller circuit is shown in Fig. **5.6***b* and can be used at any frequency: low, medium, or high. The crystal voltage waveform is much better with a FET than with a transistor. The frequency is still unstable and for the same reason: variability in the effective feedback capacitance  $C_2$  due to changes in the **FET**'s gain.

#### 5.3. COLPITTS

The Colpitts is a parallel-resonant circuit, and a basic schematic is shown in Fig. 5.7a. Physically, the circuit is very simple, but analytically, it is


Figure 5.7. Colpitts circuit: (a) transistor version, (b) FET version, (c) frequency multiplier, and (d) harmonic  $(L_1C_1$  is not tuned to resonance).

very complex. The oscillator has the following three distinct operating states.

The amplifier is an emitter follower with a gain of 1. The transistor conducts current over only a small portion of each oscillation cycle, usually about 15-20%. The transistor starts conducting a little before (about 10%) its base reaches the most positive peak of the sinusoid and stops conducting immediately after the positive peak. At the positive peak, the transistor saturates and clamps the crystal to the power supply bus through the forward-biased base-collector junction. Positive peak saturation lasts about 5-10% of an oscillation cycle. The transistor shuts off and remains nonconducting over the rest (80-85%) of the cycle. Thus, three circuit conditions exist during each cycle: a short interval (10%),

with the transistor conducting properly and acting as an emitter follower; a second short interval (5–10%), with the transistor saturated and shorting out the crystal; and a third long interval (80–85%), with the transistor shut off and nonconducting.

During the short state when the transistor is on and conducting normally, the circuit operates as follows. Referring to Fig. 5.7*a*, the crystal oscillates in a closed loop in series with  $C_2$ .  $C_2$  is in series with the crystal's internal motional capacitance, which reduces the net capacitance in the crystal loop and raises the oscillation frequency. At this higher oscillation frequency, the crystal is inductive, and together with  $C_2$ , it generates a phase lead from the emitter to the base.  $C_1$ , together with the paralleled sum of  $R_1$  and the emitter's output resistance  $R_{out}$ , generates an equal but opposite RC phase lag, giving zero total phase shift around the amplifier loop from emitter to base. Voltage gain from the emitter to the base is provided by partial series resonance between  $C_2$  and the crystal's inductance.

During the long state when the transistor is shut off, the voltage across  $C_1$  decays at a rate determined by the time constant  $R_1C_1$ . The crystal's in-circuit Q is sensitive to the time constant  $R_1C_1$ .

What values should be used for  $C_1, C_2, R_1$ , and  $R_{\text{bias}}$ ? The answer is that they should be what the crystal wants them to be, which the crystal indicates by maximizing the voltage across itself. The biggest factor is external shunt resistance across the crystal terminals, which is such a strong factor that it determines the lowest frequency the circuit will oscillate at. This shunt resistance is the parallel sum of the biasing resistor  $R_{\text{bias}}$  and the transistor's input resistance. The transistor's input resistance is determined by the transistor's gain and the emitter's load resistance  $R_1$ . Using a high-gain transistor for the emitter follower helps considerably in raising shunt resistance across the crystal.

Not too surprisingly, there is a minimum crystal shunt resistance below which the crystal will not oscillate. This minimum shuntresistance value varies directly with the crystal's internal series resistance  $R_s$ , which varies inversely with frequency. Table 5.1 lists two shunt-resistance values as a function of frequency: One is the shunt resistance at which the crystal's voltage amplitude drops 10%, and the other is the shunt-resistance value below which the circuit will not oscillate. These data were taken from several test circuits, so they are typical rather than exact.

As to the other component values in the **Colpitts** circuit, some change with frequency and some do not. In a transistor circuit,  $C_2$  should be a fixed value of 40-70 pF, independent of oscillation frequency. The oscillation frequency is very sensitive to the value of  $C_2$ , but not to C,. The

Frequency (MHz)	Shunt Resistance to Reduce Crystal Oscillation Amplitude by 10% ( $\Omega$ )	Minimum Shunt Resistance for Oscillation to Occur (Ω)
0.004	220 meg	5 meg
0.05	10 meg	680K
0.1	3 meg	220K
0.2	470K	220K
0.5	330K	100K
1.	1 meg	22K
2.	470K	15K
5.	100K	4.7K
10.	100K	3.3K
20.	22K	2.2K

TABLE 5.1						
Minimum	Crystal	Shunt	Resistance	in	Colpitts	Circuit

time constant  $R_1C_1$  should vary inversely with the oscillation frequency; that is,

$$R_1 C_1 \cong \frac{0.5}{f}$$

where  $R_1$  is in ohms,  $C_1$  is in  $\mu$ F, and f is in MHz. Additionally, there is no requirement for any specific ratio of  $C_1$  to  $C_2$ .

Now, since the crystal's shunt resistance has to increase as the frequency drops, two requirements can be met at the same time in the transistor circuit by holding  $C_1$  fixed and varying  $R_1$  inversely with frequency. Increasing  $R_1$  really helps raise the crystal's shunt resistance, because, in addition to increasing the input resistance of the emitter follower, it also raises the value of the biasing resistor  $R_{\text{bias}}$ . This technique of varying  $R_1$  and holding  $C_1$  fixed works very well in practice. The graph in Fig. 5.8 shows some typical values for  $R_1$  and  $C_1$  in the transistor-Colpitts circuit as a function of frequency.

The Colpitts circuit works better with a FET than a transistor. Figure 5.7b is a schematic of a Colpitts circuit using a FET. The main advantages are: (1) a better crystal waveform; (2) minimum oscillation frequency is lowered from 200 kHz (transistor) to 1 kHz (FET); (3) a higher crystal shunt resistance, which gives a higher in-circuit Q; and (4) no parasitic effects. The drawback to the FET is that above 10 MHz it does not work as well as the transistor circuit. This is because the output resistance of a FET source follower, which is 10 times higher than that of a transistor emitter follower, has a hard time driving the low load im-



Figure 5.8.  $R_1$  and  $C_1$  values for Colpitts-transistor circuit.

pedance that exists in the circuit at 10 MHz and above. With a FET, the waveform across the crystal is less distorted and more of a sine wave, as the waveform in Fig. 10.3a shows.

The minimum Colpitts oscillation frequency is lower with a FET than with a transistor, because the crystal's shunt-load resistance can be made higher with the FET. Table 5.1, for example, shows that at 4 kHz, a crystal shunt resistance of 220 M $\Omega$  will reduce voltage amplitude across the crystal by 10% and a shunt resistance lower than 5 M $\Omega$  will prevent oscillation. These are not practical values with a transistor circuit, but they are with a FET circuit.

In the FET version of the Colpitts oscillator shown in Fig. 5.7*b*, *the* value of the crystal's shunt resistance  $R_{hi}$  is picked from Table 5.1 as the value that will not decrease oscillation amplitude by more than 10%.  $C_2$  should be a fixed value of 22-33 pF, independent of oscillation frequency (in the transistor circuit,  $C_2$  should be a fixed value of 40-70 pF). The oscillation frequency is very sensitive to the value of  $C_2$ , but not to  $C_1$ . And like the transistor circuit, the time constant  $R_1C_1$  varies inversely with frequency:

$$R_1 C_1 \cong \frac{0.3}{f}$$

where  $R_1$  is in ohms,  $C_1$  is in  $\mu$ F, and f is in MHz.

To meet the inverse frequency requirement on the time constant  $R_1C_1$ in the FET-Colpitts circuit, it is convenient to hold  $R_1$  constant at some convenient biasing value and vary  $C_1$  with the frequency of oscillation.

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Figure 5.9. R<sub>1</sub> and C, values for Colpitts-FET circuit.

This is in contrast to the transistor-Colpitts circuit, where it was convenient to hold  $C_1$  fixed and vary  $R_1$ . The graph in Fig. 5.9 shows some typical values of  $R_1$  and  $C_1$  as a function of frequency for the FET-Colpitts circuit. Additionally, there is no requirement for any specific ratio of  $C_1$  to  $C_2$ .

In the transistor-Colpitts circuit, parasitics will occur at some nonoptimum circuit values. In contrast, no parasitics of any kind have been found in the FET-Colpitts circuit. The parasitics turn out to be third harmonic oscillations or a combination of fundamental and third harmonic oscillations. The circuit values are rather critical for obtaining this harmonic oscillation. The effect can be enhanced by decreasing the crystal's shunt resistance down to a point where the fundamental frequency is discouraged from oscillating while still keeping the shunt resistance high enough to permit oscillation at the third harmonic. Setting the time constant  $R_1C_1$  for the third harmonic frequency also helps. Both third and fifth harmonic oscillation have been reported by Bahadur and **Parshad [16]**. The amplitude of oscillation obtained this way is rather low, and there is a better harmonic Colpitts circuit available, which is discussed in the following paragraphs.

The Colpitts can also be used as a harmonic multiplier and a harmonic oscillator, as shown in Figs. 5.7c and 5.7d. In Fig. 5.7c, an LC tank tuned

to the desired harmonic is placed in the collector circuit, where it is isolated and has very little effect on what happens to the crystal at the transistor base. The crystal runs at its fundamental frequency, and the collector's  $L_2C_3$  tank at a harmonic. The transistor conducts during only a short interval in each cycle (about 5–15% of the cycle period) at the crystal's fundamental frequency, which gives a short, sharp pulse of excitation once per fundamental cycle to the harmonically tuned tank in the collector circuit. The harmonic tank rings at its own natural frequency and is essentially resynchronized to the crystal's fundamental frequency is not constant from cycle to cycle, and the amplitude varies over **the** resynchronization interval.

In Fig. 5.7*d*, the crystal itself oscillates at the harmonic frequency. This circuit works much better than the circuit in Fig. 5.7*c*. Figure 5.7*d* shows a FET amplifier, but the circuit works equally well with a transistor. The only difference between this harmonic circuit **and the fun**-damental circuit in Fig. 5.7*b* is that the resistor  $R_1$  is replaced with the inductor  $L_1$ . The key to harmonic operation is to select  $L_1$  so that its impedance at the harmonic oscillation frequency is equal to what *R*, in Fig. 5.7*b* should be to oscillate at that same frequency.

As an example, Fig. 5.10 shows a fundamental Colpitts circuit for 20 MHz. Figure 5.11 shows a third harmonic Colpitts circuit also for 20 MHz. Note that the impedance of the 10  $\mu$ H inductor& is approximately equal to  $R_1$ , 1200  $\Omega$ . The reason the circuit in Fig. 5.11 oscillates at the third harmonic (20 MHz) rather than at the fundamental (6.7 MHz) is that the impedance of  $L_1$  should be 3600  $\Omega$  at 6.7 MHz for fundamental oscillation to occur, whereas the actual impedance of  $L_1$  at 6.7 MHz is only 400  $\Omega$  or <sup>1</sup>/<sub>9</sub> of what it should be for fundamental oscillation.



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Figure 5.11. Third harmonic Colpitts at 20 MHz.

# 5.4. LOW CAPACITANCE LOAD

What happens when a low capacitance load (high impedance) is used on the crystal? The major effects are a higher oscillation frequency and a higher crystal output signal to the amplifier. The external load capacitance is in series with the crystal's internal **motional** capacitance, which reduces net oscillation capacitance and raises the resonant frequency proportionately. The output signal is larger because the impedance of the crystal's current measuring element is larger.

A basic schematic is shown in Fig. 5.12*a*. The crystal is driven by as low a source resistance as possible  $R_{10}$ . The crystal's load consists of two small capacitors in series that act as a 5 to 1 voltage divider to isolate the amplifier's resistive loading and overload peak-clipping effects from the crystal. The amplifier's input stage is a FET in order to make the amplifier's input resistance as high as possible and minimize resistive-loading effects on the crystal.

The 5 to 1 capacitive voltage divider and, to a certain extent, using a FET input stage provide a linear input impedance to the crystal that will not overload and put a short circuit directly across the crystal over a part of the waveform cycle, as the Colpitts circuit does. The FET does overload as a gate-to-drain diode clamp to the power supply bus at the positive peak of the input waveform, but the 5 to 1 voltage divider hides it from the crystal.

Sampling the crystal current by means of the voltage across a capacitor in series with the crystal introduces a 90° phase lag in the amplifier loop. The amplifier itself provides a 180" phase inversion, and the two RC networks ( $R_1C_3$  and  $R_{1o}C_4$ ) in the amplifier introduce two additional 45 phase lags, for a total phase shift of 360° around the amplifier loop.



Figure 5.12. Low capacitance load circuit: (a) using an inverting amplifier, (b) using a noninverting amplifier.

The oscillator works equally well with a noninverting amplifier, as shown in Fig. 5.12b. The noninverting amplifier consists of a cascaded FET source follower and a transistor emitter follower, with a total amplifier gain of 0.7X. Additional gain is obtained by resonance effects between the inductive crystal and the series capacitors  $C_{\rm small}$  and  $4C_{\rm small}$  and between  $L_1$  and  $C_1$ . The 90" phase lag of the crystal's current-sampling capacitor  $4C_{\rm small}$  is compensated by the 90" phase lead of  $L_1$ , which is series resonant with  $C_1$ . The overall loop gain is controlled by two ratios: the ratio of the impedance of  $L_1$  to  $R_1$  and the ratio of the impedance of  $4C_{\rm small}$  to the impedance of  $L_1$ .  $L_1$  is made relatively small and partially reduces the frequency increase caused by the low capacitance load  $C_{\rm small}$  on the crystal.

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## BASIC OSCILLATOR CIRCUITS

## 5.5. HIGH RESISTANCE LOAD

What happens when a high resistance load is used on a crystal? Pretty much the same thing that happens when a low capacitance load is used. The major effects are a much higher oscillation frequency and a larger crystal output voltage to the amplifier. The higher oscillation frequency is due to the crystal's small terminal capacitance  $C_0$  being in series with the crystal's internal motional capacitance, which reduces net oscillation capacitance and raises the resonant frequency.

A basic schematic is shown in Fig. 5.13. The circuit is very similar to the low capacitance load circuit in Fig. 5.12*a* except for the crystal loading. The crystal is driven by as low a resistance as possible,  $R_{1o}$ . The crystal's load consists of its terminal capacitance  $C_0$  and two very large resistors ( $R_{hi}$  and 0.25  $R_{hi}$ ) that act as a 5 to 1 voltage divider to isolate the amplifier's overload peak-clipping effects from the crystal. The amplifier's input stage is a FET in order to make the amplifier's input resistance as high as possible and minimize crystal loading. The 5 to 1 voltage divider provides a linear impedance to the crystal that will not put a short circuit across the crystal over a part of the waveform cycle, as the Colpitts circuit does. The FET overloads as a gate-to-drain diode clamp at the positive peak of the input waveform, but the 5 to 1 voltage divider hides it from the crystal.

The input capacitance of the FET amplifier in Fig. 5.13 is 4 pF, which requires capacitive compensation  $C_3$  of the resistive voltage divider. The reactive impedances of  $C_3$  and the amplifier's 4-pF input capacitance at 1



Figure 5.13. High resistance load circuit.

#### COMMON BASE

MHz are much lower than the resistance of the voltage divider, which means that the divider is really a capacitive divider rather than a resistive one. It also means a 90° phase lag, because the crystal's current is measured by the voltage drop across a capacitor rather than across a resistor.

The amplifier in Fig. 5.13 provides 180" phase inversion. The two RC networks ( $R_1C_1$  and  $R_{1o}C_2$ ) introduce two additional 45" phase lags, for a total phase shift of 360° around the amplifier loop. The oscillator will work equally well with a noninverting amplifier, using a circuit similar to that shown in Fig. 5.12*b* but with a high-resistance voltage divider instead of the capacitive one shown in Fig. 5.12*b*.

## 5.6. COMMON BASE

The common base oscillator circuit is a series-resonant type, and a basic schematic is shown in Fig. 5.14*a*. This circuit has several good design characteristics: It uses a common base amplifier, which is unconditionally stable at all frequencies and has a very wide frequency response. An emitter follower reduces the amplifier's output resistance to a low value for driving the crystal. The crystal is tied between two emitters; one emitter acts as the crystal's load resistance and the other, as the crystal's source resistance. The emitter source and load resistances can be varied over a wide range to provide a suitable crystal load over a wide range of crystal resistances.

The basic circuit works well over a frequency range of 600 kHz-20 MHz. The frequency range can be extended to 4 kHz by moving the crystal to a different part of the circuit, as shown in Fig. 5.14c.

The common base circuit shows very clearly the strong effect that the crystal's internal series resistance  $R_s$  has on circuit design. Referring to Fig. 5.14*a*, we see that the net load resistance on the crystal is the parallel sum of  $R_2$  and  $Q_1$ 's emitter input resistance. The net load resistance and the crystal's internal series resistance  $R_s$  act as a voltage divider, which reduces loop gain. The lower the load resistance on the crystal, the more loop gain is reduced, and the larger the gain that  $Q_1$  has to provide to maintain oscillation.

The gain of  $Q_1$  is proportional to the ratio of its collector and emitter resistors  $R_1/R_2$ . So to keep the gain up, the emitter resistor  $R_2$  should be kept small, and not allowed to get much bigger than  $Q_1$ 's emitter input resistance. The emitter's input resistance is controlled by the **emitter** current, which can be varied over a wide range by varying the base bias voltage.





Figure 5.14. Common base and common gate oscillator circuits. The appropriate circuit is selected on the basis of the crystal's internal series resistance  $R_s$ . (a) At high frequencies:  $5 < R_s < 400 \Omega$ ; (b) At medium frequencies:  $200 < R_s < 1200 \Omega$ ; (c) At low frequencies:  $1K < R_s < 100K \Omega$ .

A transistor emitter's input resistance can be varied from 5 to 100  $\Omega$ , which is suited to the low resistance of crystals at high frequencies. At medium frequencies, replacing the transistor  $Q_1$  with a FET will give the crystal a higher load resistance that is more appropriate to the medium resistance of crystals at these frequencies. Figure 5.14b shows a FET schematic that is appropriate for medium frequency use. The source input resistance for a high transconductance FET such as the

J309 (or U309) is about 200  $\Omega$  and for a medium transconductance FET such as the 2N4416, about 500  $\Omega$ . The crystal's load resistance can thus be varied from 200 to 500  $\Omega$  by selecting the FET used for  $Q_1$ .

It is important to note the diode amplitude clamp in Figs. 5.14~ and 5.14b; the circuits do not work well without it. The purpose of the clamp is to limit oscillation amplitude and thereby keep both  $Q_1$  and  $Q_2$  operating in their linear regions over the complete waveform cycle. If either transistor saturates or ceases conduction at some point over the waveform cycle, the crystal's source and/or load resistances will switch suddenly to either a short circuit or a high value.

At low frequencies (i.e., below 600 kHz), crystals have a relatively high internal series resistance and need a high load resistance to avoid a large gain loss. To obtain this, the crystal is moved to a higher impedance part of the circuit, as shown in Fig. 5.14c. Here, the crystal is tied between collector and base. The two emitters are tied together and use a common emitter resistor.  $Q_2$  should be a high-gain transistor in order to maximize both its base input resistance and the biasing resistor  $R_3$  in parallel with the base of  $Q_2$ .  $Q_2$  acts as an emitter follower driving  $Q_1$  as a common base amplifier. The gain of  $Q_1$  is controlled by the ratio of the collector and emitter resistors  $R_1/R_2$ .  $C_1$  is a small noise-reducing capacitor, which eliminates extra noise switchings that occur at switching crossover points at these low frequencies.

At very low frequencies (below 4 kHz), where the crystal's internal series resistance  $R_s$  goes over 100K  $\Omega$ , the circuit in Fig. 5.14*c* does not have enough gain to oscillate anymore because of the high gain loss through the crystal and its voltage divider. The circuit in Fig. 5.15 can then be used; it is not a common base amplifier circuit, but it is a series-resonant circuit. It uses a straightforward two-stage amplifier, with a FET for the input stage. There is more than enough gain available, so the crystal's source and load resistances  $R_1$  and  $R_{load}$  can both be made considerably smaller than the crystal's internal series resistance  $R_s$ . This will give good in-circuit Q and good short-term frequency stability.

## 5.7. SERIES RESONANCE-IC

There are several ways integrated circuits can be used in a crystal oscillator. The two-inverter circuit shown in Fig. 5.16 is a popular one because of its simplicity and the ease of blending it into digital circuitry. The circuit is series resonant and uses two cascaded digital inverters for an amplifier. It can be built using CMOS-, TTL-, or ECL-type circuitry.



Figure 5.15. Alternative series-resonant circuit at very low frequencies, for  $R_s > 50 \text{ K} \Omega$ .

To solve the start-up problem, each inverter has a DC biasing resistor tied from its output to its input to bias the inverters halfway between the zero and one states, so that they will amplify when power is applied and the crystal will start oscillating. The two inverters are AC coupled to prevent the DC biasing loops on the two inverters from interfering with each other.

The biasing resistor on the first inverter is made up of two resistors in series, with the center point bypassed to ground through  $C_1$ .  $C_1$  reduces the coupling of the switching signal from the output of the first inverter back into the crystal's output and helps clean up the crystal's output waveform. For good in-circuit Q and short-term frequency stability,  $R_{load}$  should be set equal to or somewhat less than the crystal's internal series resistance  $R_{,.}$ 

The two-inverter circuit works well in CMOS and ECL, but in TTL, it has three drawbacks. First, the input resistance of a TTL inverter {or



Figure 5.16. Series-resonant oscillator using ICs.

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gate) goes low just before the instant of switching, creating a flat spot in the amplifier's input waveform at the worst possible time-during the switching interval. The flat spot makes the instant of switching more uncertain in time and worsens the oscillator's short-term stability. Second, the TTL version cannot be used above about 3 MHz because TTL voltage levels exceed the crystal's power dissipation limit. And third, the circuit will not oscillate below about 100 kHz because the parallel resistance of the first TTL inverter's input resistance and the biasing resistor  $R_{\text{bias}}$  act as a voltage divider with the crystal's internal series resistance  $R_s$  and attenuate loop gain too much.

Although Fig. 5.16 shows a crystal load resistor  $R_{load}$ , both  $R_{load}$  and capacitor C<sub>1</sub> are frequently omitted from the circuit, which reduces both the in-circuit Q and short-term frequency stability. Many computer circuits simply need a reliable clock with a 50-50 on/off ratio rather than the accuracy or stability provided by a quartz crystal. Therefore, omitting  $R_{load}$  and  $C_1$  is not a loss under these conditions.

Another IC oscillator circuit is shown in Fig. 5.17. This is a seriesresonant circuit that uses a voltage comparator or a line receiver for the amplifier.

### 5.8. PIERCE

The Pierce is a series-resonant circuit, and its schematic is shown in Fig. 5.18. The Pierce has many desirable characteristics. It will work at any frequency from the lowest to the highest-from 1 kHz-200 MHz. It has





Figure 5.18. Pierce circuit, ideal operation.

very good short-term stability because the crystal's source and load impedances are mostly capacitive rather than resistive, which give it a high in-circuit Q. The circuit provides a large output signal and simultaneously drives the crystal at a low power level. The low power level in the crystal is very helpful at high frequencies, where crystals have low dissipation ratings..

Large phase shifts in RC networks and large shunt capacitances to ground on both sides of the crystal make the oscillation frequency relatively insensitive to small changes in the series resistances or shunt capacitances. In addition, RC roll-off networks and shunt capacitances to ground minimize any transient noise spikes, which give the circuit a high immunity to noise.

In most Pierce circuits, the amplifier consists of just one transistor, and it has no parasitic oscillations of any kind. Being a stable low-impedance circuit, it is not disturbed by connecting a scope probe to any circuit point. This makes it easy to see what is going on in the circuit.

The Pierce circuit does have one disadvantage. It needs a relatively high amplifier gain to compensate for relatively high gain losses in the circuitry surrounding the crystal.

Several writers in the literature, having noted that the Pierce and Colpitts have identical circuit layouts except for the location of the ground point, have used one set of mathematical equations to interpret both cir-

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**cuits.** One set of equations can be applied to both circuits, but since the two circuits operate differently, the equations must be interpreted differently in the two cases. The basic difference between the circuits is that the crystal in the Pierce is designed to look into the lowest possible impedance across its terminals, whereas the crystal in the Colpitts is designed to look into a high impedance across its terminals. This basic difference results in other differences. The operation of the Colpitts, which is described in Section 5.3, is so different from that of the Pierce, described in this section, that there is little significance in using the same set of equations to cover both circuits except that both are three-loop networks containing the same number of RLC components.

To understand how the Pierce oscillator circuit works, the reader should refer to Fig. 5.18. The total phase shift around the loop is 360". Idealistically speaking, the amplifier provides  $180^\circ$ ,  $R_1C_1$  acts as an integration network and provides a 90" phase lag, and the crystal, together with  $C_2$ , acts as a second integration network and provides a second 90" phase lag.

At series resonance, the crystal's impedance is a pure resistance, and together with  $C_2$ , it acts like a RC integrating network, providing a 90" phase lag, as shown in Fig. 5.18. Below series resonance, the crystal's impedance is capacitive, as shown in Fig. 5.18, and together with  $C_2$ , it acts like a capacitive voltage divider with 0° phase shift. Above series resonance, the crystal's impedance is inductive, as shown in Fig. 5.18, and together with  $C_2$ , it provides a 180° phase lag. Thus, the crystal can provide anything from a 0° to 180" phase lag by just a small increase or decrease in frequency from series resonance.

In reality, of course, the amplifier provides slightly more than a 180" phase shift, due to the transistor's internal capacitance and storage time, and the  $R_1C_1$  integrating network provides something less than a 90° phase shift. Figure 5.19 shows more practical phase-shift values to be expected in a Pierce circuit. The crystal typically operates inductively, about 5-40 ppm above series resonance, because the actual phase lag of  $R_1C_1$  is significantly less than 90".

There is a close correlation in the Pierce between the circuit's short-'term frequency stability and the crystal's internal series resistance  $R_s$ . The lower the crystal's resistance at series resonance, the smaller the frequency shift needed to change the crystal's impedance from capacitive to inductive (or vice versa) and correct any phase errors around the loop.

It was mentioned earlier that the oscillator's frequency is relatively insensitive to small changes in resistance and capacitance values. The reason is that the phase lag of each RC integrating network ( $R_1C_1$  and



Figure **5.19**. Pierce circuit, actual operation (slightly above series resonance).

 $R_sC_2$ ) is much greater than 45°, and a small change in either the resistance or capacitance of such a network introduces only a very small change in its phase lag. Changes in either *R* or *C* will introduce significant gain changes, of course, but only small changes in phase.

To design a Pierce oscillator, the frequency of oscillation and the crystal's internal series resistance  $R_s$  must be known. The crystal's internal series resistance need be known only approximately. This can be obtained by referring to Fig. 2.3, which gives the maximum series resistance of crystals at various frequencies. The typical crystal's internal series resistance is about  $\frac{2}{3}$  of the maximum value given in Fig. 2.3. The time constants of the two RC phase-shifting networks should be made as large as possible. This makes their phase shifts as independent as possible of any changes in resistance or capacitance values. Such networks have large gain losses, which mean that the transistor used for the amplifier should be selected on the basis of having the highest possible gain in order to compensate for these losses.

The highest gain RF transistors have a minimum current gain  $h_{FE}$  of 100. This allows a maximum amplifier voltage gain of about 50. To maintain oscillation, we need a net loop gain of 1.5-2, which gives a gain of about 50/1.7 = 30'to cover the losses of the two RC networks. Dividing this gain of 30 equally between them allows each to have a gain loss of about 5.5. This defines the capacitive shunt reactance in each RC network as 1/5.5 or 0.18 its series-resistance value. Thus, the shunt capacitance  $C_2$  on the crystal's output should have a reactance of 0.18 the

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crystal's series resistance. With the known frequency of oscillation, the actual capacitance value can be calculated.

To minimize loading effects of the crystal's internal series resistance  $R_s$  on  $C_1$ , the reactance of  $C_1$  should be much lower than the series resistance of the crystal, say  $\frac{1}{5}$  of it, which means that  $C_1$  should be approximately equal to  $C_2$ . This also means that  $R_1$  should be approximately equal to the crystal's internal series resistance  $R_s$ .  $R_1$  frequently turns out to be a little low for the transistor to drive conveniently, so it is often fudged upward a little to a value that the transistor can drive more easily, and the impedance of  $C_1$  is fudged upward along with it to avoid any additional gain loss.

The preceding describes a typical Pierce circuit at middle frequencies. At low frequencies, the amplifier's input stage must be a FET to avoid resistive loading of the crystal's high internal series resistance  $R_s$  at low frequencies. And at high frequencies, the amplifier's output stage must be an emitter follower in order to be able to drive the low impedance of the crystal at high frequencies.

For harmonic operation, either of two approaches can be used. With the first approach, a resonant LC tank tuned to the desired harmonic is incorporated somewhere within the amplifier. The second approach uses the circuit shown in Fig. 5.20.

The circuit in Fig. 5.20 is the same as the one in Fig. 5.18 except that an inductor  $L_1$  has been added in parallel with  $C_1$ .  $L_1$  is picked to parallel resonate with  $C_1$  at some intermediate frequency (say halfway) between desired harmonic oscillation frequency and the next lower odd harmonic. At the desired harmonic frequency, the impedance of L, will then be high enough with respect to the impedance of  $C_1$  so that it can be neglected, and  $R_1C_1$  will act as an integrating network and provide the desired 90° (idealistically speaking) phase lag. Thus, the circuit will os-



Figure 5.20. Pierce circuit for harmonic operation.  $L_1C_1$  is not tuned to the harmonic oscillation frequency.

cillate normally at the desired harmonic. At all lower harmonics, however, the impedance of  $L_1$  will be lower than the impedance of C<sub>1</sub>. Then,  $C_1$  will be negligible instead of  $L_1$ , and  $R_1L_1$  will act as a differentiating network, providing 90° of phase lead instead of phase lag. The circuit will not oscillate at any of these lower harmonics because the total phase shift around the loop at these lower frequencies is now 180°, which provides negative feedback and stabilizes the circuit instead of making it oscillate.

The shunt inductance scheme in Fig. 5.20 is useful at medium and high frequencies, but it is redundant at VHF. Above 20 MHz, the amplifier has to use a tuned LC tank as a load to get any gain at all, and this same LC tank can be used to select the desired harmonic without adding an extra inductor in front of the crystal.

The Pierce can be made to oscillate exactly at series resonance rather than just slightly above it by using the circuit in Fig. 5.21. The technique is to use three RC lag networks, each providing a 60" phase lag. In each RC lag network, capacitance C is determined by setting its capacitive reactance equal to 0.5R in order to give the 60" phase lag required. Nominally,  $R_1 = R_2 = R_s$ , and  $C_1 = C_2 = C_3$ . Because of loading effects of each RC network on the preceding one, capacitance values of  $C_1$  and  $C_3$ will have to be shifted a little to provide the 60" phase lag needed in each RC network. The quickest way to do this is by experiment, trimming the values of C, and  $C_3$  to get the desired 60" phase lag in each network. A



Figure 5.21. Pierce at exact series resonance.

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scope is used to measure the actual phase shifts obtained. Capacitance values can also be determined by mathematical circuit analysis.

The Pierce circuit in Fig. 5.21 can be made to oscillate below series resonance as well as exactly at resonance. The only change required is increasing the phase lags of  $R_2C_3$  and  $R_1C_1$  to a little more than 60°.

The circuit in Fig. 5.21 requires less amplifier gain than other Pierce circuits, which is helpful if the amplifier to be used is a little short of gain. Each  $60^{\circ}$  RC phase-lag network has a gain loss of 0.5X, and an amplifier gain of 16 will provide a net loop gain of two, which is sufficient for proper oscillation.

## 5.9. PIERCE-K

This section covers implementing the Pierce oscillator with integrated circuits, but does not discuss how the Pierce circuit works, which is treated in Section 5.8.

The Pierce amplifier can be built using digital logic elements in CMOS, TTL, and ECL. The basic frequency range of each technology applies to crystal oscillators; that is, CMOS for low frequencies, TTL for medium frequencies, and ECL for medium and high frequencies. Two primary considerations in each technology are (1) obtaining the high amplifier gain required by the Pierce circuit and (2) the amount of internal phase shift or time delay in the amplifier (or inverter). Each technology will be discussed in turn.

In CMOS, both the gain and frequency bandwidth of a single inverter stage vary widely from manufacturer to manufacturer. The A series are unusable for oscillator purposes because of their low inverter gains of 1.1-2 and their lack of output drive power. **B** series inverters have gains of 10-30. The widest bandwidth (i.e., the least delay) CMOS inverter tested was manufactured by Solid State Scientific, followed by National Semiconductor's 74C series.

A single CMOS inverter is frequently used as the amplifier in the Pierce circuit in Fig. 5.22. The gain of a CMOS inverter is too low to use the normal Pierce circuit in Fig. 5.19, so the resistor  $R_1$  is eliminated and replaced with the internal output resistance  $R_0$  of the CMOS inverter, as shown in Fig. 5.22. This reduces gain loss and allows operation with a single CMOS inverter. The inverter's output voltage swings between zero and one are then highly sloped, and amplitude is sometimes below normal. A second CMOS inverter is added as an external isolation amplifier in order to square up the output signal and ensure getting a full rail-to-rail voltage swing.



**Figure 5.22.** Pierce in CMOS.  $R_1$  is replaced by the inverter's output resistance  $R_0$ .

Using the CMOS inverter's output resistance to replace  $R_1$  in Fig. 519 has the disadvantage that the crystal is driven at a much higher voltage level than it would be in a normal Pierce circuit. At frequencies above 2 MHz, the crystal's power dissipation should be checked to make sure it is within the maximum dissipation limit.

In TTL, only a voltage comparator IC can be used to make a Pierce oscillator. Ordinary TTL inverters have gains of only 3-9X, which is not enough to make a Pierce out of a single inverter. Cascading three inverters in series to increase gain will not work either, because very bad parasitic oscillations occur during the switching interval when a TTL inverter's output voltage moves less than a full voltage swing. TTL line receivers will not work because their gain of about 15X is too low. In order to make a TTL oscillator using something other than a voltage comparator IC, it is necessary to use the series-resonant two-invertertype circuit, which is described in Section 5.7.

In ECL, a single line receiver does not have enough gain to make a Pierce oscillator. But three 10114 line receivers can be cascaded in series to get enough gain. A single 10114 receiver has a gain of 3-6X. The 10116 and 10216 are apparently constructed differently than the 10114, since the units tested showed wider gain variations than the 10114 and exhibited relatively large gain differences between a receiver's two outputs (normal and inverted).

Although a relatively high gain may be desirable in an IC for oscillator circuitry, it should be said that a high gain per stage is undesirable in digital circuitry, which is what many of these ICs are designed for. High gain increases the tendency for spurious oscillations (caused by stray feedback) during the digital switching interval. A low stage gain of 1.5-3X is sufficient in a digital IC, since the primary purpose of gain in a digital IC is to prevent a low amplitude signal from propagating throughout the system.

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Figure 5.23. Emitter coupled oscillator.

## 5.10. EMITTER COUPLED

The emitter coupled oscillator is a series-resonant circuit, and a basic schematic is shown in Fig. 5.23. The oscillator has a positive feedback amplifier with a loop gain of slightly less than one without the crystal, so that the circuit will not oscillate by itself. Loop gain is controlled by the ratio of the collector to emitter resistances in each transistor stage. In the second stage, it is convenient to make emitter and collector resistances ( $R_2$  and  $R_2$ ) equal to each other, giving a stage gain of 1X. The second stage inverts the signal and provides positive feedback.

In the first stage, the collector resistor  $0.8R_1$  is made a little smaller than the emitter resistor  $R_1$  in order to give an overall loop gain of 0.8X. The value of the emitter resistor  $R_1$  is set equal to about twice the crystal's internal series resistance  $R_s$ . When the crystal is tied in parallel with  $R_s$ , the effective resistance of the emitter resistor is reduced at series resonance, since the crystal's internal resistance  $R_s$  is in parallel with  $R_1$ . This raises both stage gain and overall loop gain to about 2X, and the circuit oscillates at the crystal's series-resonant frequency.

An advantage of this circuit is that the crystal sees a very low resistance load. This low resistance load consists mostly of the emitter's input resistance, which is much lower than  $R_1$ . A disadvantage is that circuit waveforms vary with the circuit's stray capacitance, because loop gain is almost high enough to oscillate at any frequency.

## 5.11. MODIFIED MEACHAM

The Meacham [5, 17] is a resistance-bridge circuit, as shown in Fig. 5.24. The crystal is located in one arm of the bridge. A tungsten lamp, located



Figure 5.24. Meacham resistance bridge.

in another arm of the bridge, is used as a variable resistance-amplitude control. There is no voltage out of the bridge at exact bridge balance, so it operates slightly off-balance-just enough to get a loop gain of exactly 1X around the amplifier circuit. The tungsten lamp's resistance increases with the applied voltage, and its variable resistance automatically controls loop gain at exactly 1X. This provides a constant sine wave excitation voltage to the crystal. The amplifier has a large voltage gain  $E_i/E_0$  of 422X.

Clapp's version [18] of the Meacham is shown in Fig. 5.25. The advantage of Clapp's arrangement is the elimination of transformers by using a split-load phase inverter to drive the bridge. Vacuum tube  $V_2$  in Fig. 5.25 has equal cathode and plate voltages of opposite phase for



Figure 5.25. Clapp's version of the Meacham resistance bridge. Note that it has no transformers.



Figure 5.26. Modified Meacham half-bridge.

driving the bridge. Clapp's amplifier also has a large voltage  $gain E_i/E_0$  of about 300X. Both of these circuits use a single stage of amplification, a **pentode** vacuum tube.

If something other than a tungsten filament is used for amplitude control, the Meacham can be simplified further into the half-bridge arrangement shown in Fig. 5.26, which uses a diode clamp for amplitude control. A thermistor (which has a negative temperature coefficient of resistance) can also be used for amplitude control by putting it in the half-bridge in place of  $R_3$ . Oscillation amplitude must be at least four times greater if a thermistor is used rather than a diode clamp, since the thermistor requires a minimum of 4-6 Vp-p to properly activate its negative resistance characteristic. Greater oscillation amplitude increases power dissipation in the crystal, which is undesirable.

The advantage of the Meacham is its extremely good short-term frequency stability. This can be seen by looking at Fig. 5.26 and treating the output of **the** half-bridge at point A as a summing point for two input signals. At series resonance, the amplitude of the positive signal from the emitter of  $Q_3$  is limited at A by the crystal's internal series resistance  $R_s$ . At the same time, the amplitude of the negative signal from the collector of  $Q_3$  is limited at point A by  $R_3$ , which if set equal to  $R_s$ , will cancel out the positive resistive signal from the emitter. What is happening is that the crystal's internal series resistance (but not its internal inductance or capacitance) is being canceled out by the reverse-phase signal through  $R_3$ . The crystal's in-circuit Q increases, and its effective internal resistance decreases. In theory, with exact cancellation of the crystal's internal resistance by  $R_3$ , the crystal's Q would approach infinity. In practice, this cannot happen, since  $R_3$  must be slightly larger than  $R_s$  to get some signal gain (greater than zero) through the bridge. With high amplifier gain, less gain is required through the bridge to maintain oscillation, and  $R_3$  can cancel out a larger percentage of the crystal's internal resistance. Thus, there is a strong advantage in using the highest possible amplifier gain, since that will give the highest possible cancellation of the crystal's resistance and the highest in-circuit Q.

The disadvantage of the Meacham is that it has a strong tendency to oscillate parasitically at high frequencies. It is very difficult to design a stable Meacham circuit. The cause of this can be seen in the bridge's gain versus frequency transfer function, as shown in Fig. 5.27. Figure 5.27 shows that the gain at the crystal's resonant frequency is much less than 1X and 1X at all other frequencies. To oscillate, the circuit has to have enough amplifier gain to bring the low bridge gain at resonance up to a net loop gain of at least 1 or 2X, which means that the gain at all other frequencies is undesirably much higher than this. To prevent parasitic oscillation, this high loop gain at frequencies away from resonance must be reduced to less than 1X while introducing less than 180" additional phase shift. To do this involves consideration of Bode's stability criteria for feedback-type amplifiers, which is too broad a subject to cover here.

Figure 5.24 shows that Meacham used two resonant LC tank circuits to roll off loop gain at frequencies away from resonance. Figure 5.25 shows that Clapp, with a lower loop gain, used only one resonant LC tank circuit to reduce the gain at frequencies away from resonance. The



Figure 5.27. Resistance bridge gain and phase versus frequency for the normal operating condition  $R_3 > R_s$ .

modified Meacham half-bridge circuit in Fig. 5.26 uses one resonant LC tank to roll off loop gain at frequencies away from resonance.

The modified Meacham half-bridge circuit has two additional characteristics of interest. The first is that the sequence of placing the resonant LC tank before the diode amplitude clamp in Fig. 5.26 is significant, since this provides a square wave drive to the crystal. Reversing the sequence will provide a sine wave drive to the crystal. The second characteristic of interest is that the two output signals from the split-load phase inverter  $Q_3$  in Fig. 5.26 do not have to be of equal amplitude. Necessary bridge balance is maintained by adjusting the ratio of  $R_3$  to the crystal's internal series resistance  $R_s$  in proportion to the amplitude ratio of  $Q_3$ 's emitter and collector signals.

It turns out to be very helpful to reduce the collector's output signal from  $Q_3$  in Fig. 5.26 by a factor of two or more with respect to that from  $Q_3$ 's emitter. This is done by reducing the value of  $R_2$  to one-half (or one-fourth or one-eighth) of  $R_1$ . Doing this has three advantages. First,  $R_3$ is reduced proportionately with  $R_2$  to maintain bridge balance. This lowers the crystal's load resistance, which consists mostly of  $R_3$ , and improves short-term frequency stability. Second, all frequencies away from resonance pass through  $R_3$  and the collector of  $Q_3$  rather than through the crystal. Reducing  $R_2$  with respect to  $R_1$  reduces loop gain at all frequencies away from resonance without affecting loop gain at resonance. This helps the high-frequency parasitic oscillation problem considerably. And third,  $R_1$  feeds back to the base of  $Q_3$  a larger percentage of the collector's output voltage, which broadens the bandwidth of the inverter stage  $Q_3$  and reduces the collector's phase-shift error at high frequencies. This helps the high-frequency parasitic oscillation problem.

# 5.12. SPECIAL OSCILLATOR ICs

There is an assortment of special ICs available that are specifically designed to be used as crystal oscillators. Most of them try to cover a wide frequency range of 10 to 1 or so with a fixed circuit, which is very difficult to do. The crystal's load resistance usually matches the crystal at the low end of the IC's frequency range, but it is frequently too large at the high-frequency end. Special ICs use all of the IC technologies: CMOS, TTL, ECL, and LINEAR. Two of them incorporate an AGC (automatic gain control) circuit to keep oscillation amplitude low and minimize frequency drift due to crystal heating. This is a nice touch when implemented properly. Three of the special ICs use the common base cir-



Figure 5.28. Butler common base, capacitive tap.  $L_0$  is not needed below about 70 MHz.

cuit, and one uses the series-resonant circuit; another uses the Pierce and the other, the emitter coupled circuit.

# 5.13. HARMONIC -BUTLER COMMON BASE

The Butler common base circuit is a VHF harmonic oscillator, operating at or near series resonance; a basic schematic is shown in Fig. 5.28. The circuit is used at frequencies between 20-200 MHz. It uses a common base amplifier, which is an inherently stable design at high frequencies. The collector load is an LC tank, detuned a significant amount off resonance at the desired harmonic. Starting at 50-100 MHz, the impedance of the crystal's shunt terminal capacitance  $C_0$  (about 5 pF) starts approaching the size of the crystal's internal series resistance  $R_s$  and provides an alternative path around the crystal, thereby shorting it out. So above about 70 MHz, an inductor  $L_0$  is tied across the crystal to resonate with the crystal's terminal capacitance  $C_0$  and tune it out of the circuit.

The load resistance seen by the crystal in Fig. 5.28 is the parallel sum of the emitter resistor  $R_1$  and the emitter's input resistance. The gain of the transistor is the ratio of the LC tank circuit's impedance divided by the resistance of the emitter resistor  $R_s$ . Practical LC tank circuit impedances are relatively low at VHF, so it is necessary to keep  $R_1$  small to get enough gain for oscillation. The internal series resistance  $R_s$  of crystals at 20-200 MHz is 20-200  $\Omega$ , respectively. A good load resistance for a crystal is about 25-50% of its internal series resistance or 5-50  $\Omega$ . The emitter's input resistance is lower than  $R_1$  and is set to the desired crystal load value by adjusting the emitter current. With a load resistance of

 $0.33R_s$ , this gives (1 + 0.33)/0.33 or a 4 to 1 gain loss by the voltagedivider action of the load resistance with the crystal's internal series resistance R,. The source impedance driving the crystal is mostly capacitive and is one to two times the impedance of  $C_2$ , depending on the value of c,.

The source impedance at the collector is much too high to drive the low impedance of a typical VHF crystal. So, figuratively speaking, the crystal is tapped down on the LC tank circuit to (1) reduce the source impedance seen by the crystal and (2) reduce the crystal drive level and keep the crystal within its power dissipation limit. Experimentally, tapping the crystal across about  $\frac{1}{4}$  of the tank circuit seems to be about optimum from the practical standpoint of maximum energy transfer and minimum gain loss; that is, in Fig. 5.28, let  $C_2 = 3C_1$ . If tapped down much further, total gain loss around the circuit gets too high, and it will no longer oscillate.

Tapping down the crystal on the collector's LC tank drastically changes the operation of the LC tank. The source impedance driving the crystal drops down from 1000  $\Omega$  to 5-15  $\Omega$ , a much lower value than would be expected. Although it gets the point across, the idea of tapping down on the LC tank is too simplistic to describe what really happens when the crystal is tied to an intermediate point part way across the LC tank. What really happens is as follows. Let us rearrange Fig. 5.28 as shown in Fig. 5.29. Referring to Fig. 5.29, the crystal's internal series resistance  $R_s$  is approximately equal to the impedance of  $C_2$ , so that  $C_2$  is partially shorted out from the LC tank. As a result,  $C_2$  has very little effect on the resonant frequency of the LC tank circuit becomes  $L_1C_1$ , which the crystal sees as a (near) series-resonant circuit of low impedance. At



Figure 5.29. Common base circuit in Fig. 5.28 rearranged.  $L_0$  has been left out for clarity.

the same time, the transistor's collector sees the  $L_1C_1$  tank as a (near) parallel-resonant circuit of high impedance. Since the crystal wants to see a low source impedance and the collector wants to see a high load impedance, both like what they see, and the circuit ends up with a good impedance transformation ratio that depends on the Q of the  $L_1C_1$  tank. This explanation of circuit operation has been verified both experimentally and analytically. Tuning the tank circuit depends almost entirely on  $L_1$  and  $C_1$  and is essentially independent of  $C_2$ .

Does it make any difference if the crystal is tapped down on the inductor in the LC tank instead of on the capacitor? Yes, it does. Figure 5.30 shows an inductively tapped circuit. Tapping down on the inductor gives a phase lag to the amplifier circuit, while tapping down on the capacitor gives a phase lead. In both cases, there is a phase lag from the emitter to the collector, caused by operating the LC tank off resonance. The phase lead of a capacitor tap subtracts from the emitter-to-collector phase lag and allows the crystal to oscillate either at or above series resonance. The phase lag of an inductive tap just adds to the emitter-tocollector phase lag and forces the crystal to oscillate below series resonance, where it can provide a phase lead to compensate the two other phase lags in the circuit to zero. The end result is that a capacitive tap allows crystal operation above, at, or slightly below series resonance, while the inductive tap allows crystal operation only below series resonance. These phase-lead and phase-lag effects are analyzed and discussed in detail in Sections 7.6 and 7.7.

Tapping into the capacitive side of the LC tank introduces a lot of parasitic oscillations into the circuit. These parasitic oscillations are **the** biggest drawback to the capacitive tap version of the circuit. Most, but



**Figure 5.30.** Butler common base, inductive tap.  $L_0$  is not needed below about 70 MHz.  $T_2$  is normally  $\frac{1}{5}$  to  $\frac{1}{5}$  of the total coil turns.

not all, of these parasitic oscillations can be suppressed by resistive loading of the LC tank and careful attention to circuit layout. In contrast, the inductive tap gives clean circuit operation without any parasitics and seems to give equal frequency stability, but its oscillation frequency is about 4 ppm lower.

Another difficulty with Butler's common base circuit is that it will only oscillate over a relatively narrow range of collector current. If the current is too small, the circuit will not oscillate because loop gain is too low. And if the current is too large, two undesirable things happen. First, the collector's LC tank gets shunted with a low resistance from the large collector current, which cuts the gain. And secondly, the emitter's input resistance, which makes up most of the crystal's load resistance and is an inverse function of the emitter current, becomes much smaller. This also cuts circuit gain, so much so that the circuit will not oscillate.

A third difficulty is that it is hard to get the crystal drive voltage down low enough to keep it from overdriving the emitter into cutoff and to keep crystal dissipation within its limit. Figure 2.5 shows that the maximum drive voltage for many crystals between 20-100 MHz at series resonance is 0.2 Vrms or 0.6 Vp-p. We can tap down the crystal further on the LC tank in Figs. 5.28 or 5.29, but this reduces loop gain, which is already on the low side, and the circuit may quit oscillating. One solution is to shunt the inductor in the LC tank with two parallel diodes of reversed polarity, as shown in Fig. 10.17. This limits oscillation amplitude without cutting loop gain. Another solution is to reduce the power supply voltage from 5 to 2 or 3 V.

For the Butler common base circuit to oscillate, experimental data indicate that the impedance of the inductor  $L_1$  in the LC tank in Fig. 5.28 should be a certain fixed value (within a factor of 2 or so) regardless of the frequency. This means that the inductive value of  $L_1$  should vary inversely with frequency. Table 5.2 lists some usable inductance values for  $L_1$  at several frequencies from 20 to 100 MHz. The inductance to be used at intermediate frequencies can be interpolated from values given

		IAD	LE 3.2			
Some	Usable	Inductance	Values	for the	$L_1C_1$	Tank
	in t	he Butler C	ircuit ir	n Fig. 5.	28	

TADLE

Oscillation Frequency (MHz)	Usable Range of Inductance for $L_1$
20	0.47-2.4 μH
50	0.22-1.0 μH
100	0.10-0.47 μH



Figure 5.31. Butler emitter follower, capacitive tap.  $L_0$  is not needed at frequencies below about 70 MHz.

in Table 5.2. The circuit seems to work better if the lower inductance value at each frequency is used.

## 5.14. HARMONIC-BUTLER EMITTER FOLLOWER

The Butler emitter follower is a VHF harmonic oscillator, operating at or near series resonance; a basic schematic is shown in Fig. 5.31. The circuit is useful mostly at frequencies between 20 and 200 MHz. The amplifier has a gain of one; the oscillator's loop gain is provided by  $L_1$  and C, operating near series resonance. Tapping the crystal into the capacitive side of the LC tank gives a phase lead, and the crystal then oscillates either at or slightly above series resonance. Starting at 50-100 MHz, the impedance of the crystal's terminal capacitance  $C_0$  (about 5 pF) approaches the crystal's series resistance  $R_s$  and provides an alternative path around the crystal, tending to short it out. So above about 70 MHz, an inductor  $L_0$  is tied across the crystal to parallel resonate with the crystal's terminal capacitance  $C_0$  and tune it out of the circuit.

Although Butler's emitter follower circuit is not so well-known as his common base circuit, his emitter follower circuit offers many practical advantages over the common base arrangement. Tapping down the crystal on the LC tank increases the oscillator's loop gain instead of decreasing it, as in the common base circuit. The amplifier's gain of one gives a stable gain configuration that is independent of bias variations and always works with any transistor. The emitter follower circuit can be operated at frequencies down to 1 kHz, whereas the lowest frequency of the common base circuit is limited to about 8 or 10 MHz by the effect of the emitter's low load resistance on the crystal (high gain loss).

The built-in feedback of an emitter follower circuit gives a very wide

amplifier bandwidth, allowing the circuit to operate at higher frequencies than what the common base circuit will provide. There are no parasitic oscillation effects because of the amplifier's low gain of one and its built-in feedback stabilization. Compared to the common base amplifier, the undesirable oscillation damping provided by DC current flow through the inductor is reduced by the transistor's current gain  $h_{fe}$  of 20-100. And while loop gain drops slightly with a heavy emitter current, the emitter follower is not limited to a narrow operating current range, as is the common base circuit. At any given frequency, a wider range of inductance values can be used with the emitter follower circuit than with the common base arrangement.

A practical Butler emitter follower is shown in Fig. 5.32. It operates as follows:  $L_1C_1$  form a resonant circuit operating near (but not at) series resonance, providing a low input impedance to the crystal and a high output impedance to the transistor base. All of the oscillator's loop gain comes from  $L_i$  and  $C_1$  operating near series resonance. The value of  $C_2$  has almost no effect on the resonant tuning of the LC tank circuit, which seems to be due to the shunting effect of the crystal's low impedance on  $C_2$ .

From the emitter's viewpoint in Fig. 5.32,  $C_2$  is effectively in series with the crystal, which raises the oscillation frequency slightly above series resonance. It is desirable to make  $C_2$  large in order to give it a low impedance, which moves the oscillation frequency down closer to series resonance. There is an optimum value for C,: If  $C_2$  is too large, it short circuits the amplifier gain loop and cuts the gain. If  $C_2$  is too



Figure 5.32. Practical Butler emitter follower circuit.

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small, it starts reacting with the inductive input impedance of  $L_1C_1$ , raising the crystal's load impedance to an undesirably high value. The optimum impedance of  $C_2$  is about 0.5-l times the crystal's series resistance  $R_1$ .

 $R_2$  gives the emitter follower a low output resistance for driving the crystal load. The two Schottky diodes across  $L_1$  limit oscillation amplitude to (1) keep the crystal's power dissipation within its rating and (2) keep the transistor conducting over the complete oscillation waveform and maintain a low emitter drive resistance for the crystal over a complete cycle. The crystal's load capacitor  $C_2$  is tied to the grounded end of the emitter resistor  $R_3$  rather than to the Zener bias supply, as was shown in Fig. 5.31. Tying  $C_2$  to the grounded end of  $R_3$  gives a shorter crystal drive loop from the emitter, and the circuit performs better. The base bias voltage is stabilized with a Zener diode to reduce frequency shift when the power supply voltage changes. This bias stabilization reduces frequency sensitivity to power supply changes by an order of magnitude.

Selection of L and C values is as follows:  $C_2$  is selected so that its reactance is equal to about 0.5 to 1 times the crystal's series resistance.  $C_1$  should be  $\frac{1}{3}$  to  $\frac{1}{4}$  of  $C_2$ . If  $C_1$  is one-half of  $C_2$ , the crystal's load impedance is undesirably high; if  $C_1$  is one-eighth of  $C_2$ , loop gain is too low.  $L_1$  is selected for approximate series resonance with  $C_2$ . There is an experimental cross-check on the correct values of  $C_1$  and  $C_2$ . In Fig. 5.32,  $C_1$  and  $C_2$  are in the right range when voltage at point A is 30–70% of the voltage at point E, indicating that the crystal's load impedance is approximately equal to the crystal's internal impedance.

Figure 5.33 shows an alternative emitter follower circuit with the



Figure 5.33. Butler emitter follower, inductive tap.  $T_2$  is normally  $\frac{1}{5}$  to  $\frac{1}{6}$  of the total coil turns.



Figure 5.34. Alternative compensation scheme for crystal's shunt terminal capacitance  $C_{0}$ .

crystal tapped into the inductive side of the LC tank circuit rather than into the capacitive side.  $T_2$  is set at about  $\frac{1}{5}$  to  $\frac{1}{6}$  of the total turns on the inductor. This provides a phase lag in the amplifier circuit loop, and the crystal then oscillates either at or slightly below series resonance. The *L* and C circuit values are selected on a basis similar to that used for the capacitive tap circuit.

Figure 5.34 shows an alternative scheme proposed by Butler [6] to compensate for the crystal's terminal capacitance  $C_0$ . Above 50-100 MHz, the crystal's shunt terminal capacitance  $C_0$  provides an undesirable shunt path around the crystal's internal frequency-controlling elements. Rather than resonating an inductance  $L_0$  in parallel with  $C_0$ , the idea here is to cancel the effects of  $C_0$  by adding an equal voltage of opposite phase through an equivalent capacitance  $C_2$  to the LC tank. The reversed phase is obtained by extending the inductance winding in the LC tank below AC ground. The emitter signal is then fed to this reversed polarity terminal through a capacitance  $C_2$ . If  $T_2 = T_3$  and  $C_2 = C_0$  (the crystal's shunt capacitance), then the shunt signal through the crystal's capacitance is canceled out. One drawback to this arangement is the increased capacitive loading on the emitter, which is already heavily loaded by the crystal impedance. As will be shown in Section 10.24, this compensation scheme does not work out very well in practice.

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# SHORT-TERM FREQUENCY STABILITY

This chapter shows the relationship between short-term frequency stability and in-circuit Q. Section 6.1 describes the effect of the crystal's external load resistance on in-circuit Q and useful differences between series and parallel equivalents of a combined resistive-capacitive load on a crystal. Section 6.2 presents experimental data showing that the equivalent series resistance of the crystal load is the component to be minimized for maximum short-term frequency stability and shows what values of parallel-load resistance will give good in-circuit Q.

# 6.1. IN-CIRCUIT Q

Crystal Q is important because it controls the short-term frequency stability of the oscillator; the basic mechanism of how it does this is as follows. A small amount of energy is dumped into the crystal on every cycle. This energy in the crystal oscillates back and forth thousands of times before gradually dying out, so that the actual voltage or current out of the crystal at any given instant is the average of energy or frequency dumped into the crystal over thousands of cycles. The more cycles that the readout voltage or current is averaged over, the more constant the readout frequency. Q is a measure of how long energy in the crystal oscillates back and forth before dying out. Thus, the higher the Q, the better the short-term frequency stability of the crystal.

The Q of a crystal in a circuit is usually less than the Q of the crystal alone, since the circuit introduces resistive losses into the crystal's os-

## SHORT-TERM FREQUENCY STABILITY

cillation loop. To minimize Q losses, we can keep the crystal's external load resistance relatively low; that is, equal to or less than the crystal's internal series resistance  $R_s$ , so that the in-circuit Q is not degraded by more than a factor of two from the crystal's internal Q. Another approach is to use a reactive load (which is lossless) rather than a resistive one. An example of this is the Pierce circuit, where the external load on the crystal is primarily capacitive rather than resistive. A third approach, which is not widely known, is to use a load resistance that is very large with respect to the reactance of the crystal's terminal shunt capacitance  $C_{0, so}$  that the external crystal load is effectively capacitive (and low loss) rather than resistive. In general, the technique of using a reactive load on the crystal instead of a resistive one is very effective in obtaining a high in-circuit Q and improves short-term frequency stability.

In describing the load on a crystal, it is important to distinguish between two equivalent representations, that is, as a parallel load with resistance and capacitance in parallel with each other or as an equivalent series load with resistance and capacitance in series with each other. For maximizing in-circuit Q, it turns out that we want to minimize the equivalent series load resistance, as is shown in the next section.

Figure 6.1*a* shows a commonly used crystal circuit, with source and load resistances, load capacitance, and the crystal's shunt terminal capacitance  $C_0$  indicated. From the crystal's point of view, the load impedance across the crystal's terminals is in series with its internal  $L_x$  and  $C_x$  components, as shown in Fig. 6.1*b*. Hence, a reactive load impedance on the crystal will change the resonant frequency by changing the net total series inductance and/or capacitance in the crystal's oscillation loop. It is also apparent from Fig. 6.1*b* that from the viewpoint of the crystal's internal frequency controlling elements  $L_x$  and  $C_x$ , the crystal's shunt terminal capacitance  $C_0$  should be considered as part of the load on the crystal, and not **as** part of its internal frequency-controlling elements.

From the crystal's viewpoint, it is easier to use the equivalent series  $R_sC_s$  load network for determining in-circuit Q, as shown in the right-half of Fig. 6.1*c*. But from a circuit-design viewpoint, it is easier to use the parallel  $R_pC_p$  load network, as shown in the left-half of Fig. 6.1*c*. To tie the two viewpoints together, we need to do some parallel to series (and vice versa) conversions of the crystal's load impedance.

The minimum value of  $C_p$  is the crystal's shunt terminal capacitance  $C_0$ , about 5 pF. Using a fixed value of 5 pF for  $C_p$  and a l-MHz oscillation frequency, Fig. 6.2 shows equivalent series values of  $(R_s)_{load}$  and  $C_s$  for various values of parallel load resistance R. To maximize the crystal's in-circuit Q, we should minimize  $(R_s)_{load}$  in the right-half of Fig. 6.1c. Figure 6.2 shows that either low or high values of  $R_p$  will give acceptably










Figure 6.1. Equivalent crystal RC load circuits in both series  $(R_s)_{\text{load}} C_s$  and parallel  $R_p C_p$  load forms: (a) typical crystal load circuit, (b) intermediate load circuit, and (c) equivalent load circuits.

low values of  $(R_s)_{load}$  but that intermediate values of  $R_p$  near 32K  $\Omega$  will give unacceptably high values of  $(R_s)_{load}$ , with a resulting very low incircuit Q.

By converting equivalent values of  $(R_s)_{load}$  into circuit Q, where

$$Q = \frac{2\pi (\text{frequency}) L_x}{(R_s)_{\text{crystal}} + (R_s)_{\text{load}}},$$



Figure 6.2. Equivalent series  $(R_s)_{\text{load}}$  and  $C_s$  values for a parallel  $R_p C_p$  network at 1 MHz.  $C_p$  is fixed at 5 pF,  $R_p$  is varied from 10  $\Omega$  to 100 M $\Omega$ .

Fig. 6.3 shows the variation of circuit Q with parallel load resistance  $R_{,.}$ Figure 6.3 shows that circuit Q is high for both low and high values of  $R_p$  but very low for  $R_p$  values anywhere near 32K  $\Omega$ . In fact, for circuit Q to be half or more of its maximum value,  $R_p$  has to be more than two orders of magnitude higher or lower than 32K  $\Omega$ . What is happening at 32K  $\Omega$ ? At 32K  $\Omega$ , parallel resistance  $R_p$  is equal to the 32K reactive impedance of parallel capacitance C,. And when that occurs, the transformation of  $R_p$  into its equivalent series value  $(R_s)_{load}$  gives a peak in the series-resistance value  $(R_s)_{load}$ , as shown in Fig. 6.2.

Since all quartz crystals have a shunt terminal capacitance  $C_0$  of about 5 pF, we can generalize this parallel-to-series peaking effect to any frequency by saying that for good in-circuit Q the parallel load resistance  $R_p$  should be greater or less than the reactance of the crystal's terminal capacitance  $C_0$  by two orders of magnitude. Figure 6.4 is a graph of this relationship, showing good and bad values of parallel resistance  $R_p$  for both low and high values of circuit Q. The average value for the crystal's terminal capacitance  $C_0$  was 5 pF, which, with assumed zero load capacitance  $C_L$ , is equal to parallel load capacitance  $R_p$  and in-circuit Q is verified by experimental data in the next section.



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6.2. MEASUREMENT OF IN-CIRCUIT Q

There are many ways to measure in-circuit Q. The method used here is to suddenly disconnect the crystal from the oscillator circuit and measure the decay of the voltage across the crystal (or the current through it) as a function of time. The measurement of Q is taken as the time required for the voltage across the crystal (or the current through it) to decay to 1/eof its initial value. The longer the decay time, the higher the Q.

Figures 6.5 and 6.6 show the envelope of voltage decay across a 1-MHz crystal for various resistive and capacitive loads across the crystal terminals. Loads range from a near open circuit to a short circuit. All waveforms shown are voltage measurements across the crystal except for the short-circuit measurement, which is a current measurement using a Tektronix current probe. The impedance of the current probe is about 0.1  $\Omega$ . A mechanical toggle switch was used for switching the crystal out of the circuit, and the bounce of the switch contacts can be seen at the left edge in some of the photographs. Note, in particular, in Fig. 6.5 the very fast decay with a 10K  $\Omega$  resistive load on the l-MHz crystal.

If we measure the crystal's relative Q, as indicated by decay rates in the photographs in Figs. 6.5 and 6.6 and plot it as a function of load resistance and capacitance, we obtain the curves shown in Figs. 6.7 and



**Figure 6.4.** Calculated in-circuit Q versus crystal parallel load resistance  $R_p$  as a function of frequency.

6.8. Figures 6.7 and 6.8 also show curves of relative crystal Q at four other frequencies: 4, 50, and 100 kHz, and 10 MHz. In order to show all five frequencies, the ordinates in Figs. 6.7 and 6.8 are not plotted in terms of decay time to l/e their initial value but in terms of the total number of oscillation cycles that occur during the l/e decay time. It is probably more relevant to plot the curves this way as well as more convenient.





(b)



(f)

(a)

**Figure** 6.5. Crystal voltage (current) decay as a function of crystal load resistance. All waveforms with same time base of 2 msec/div and crystal disconnected from oscillator circuit. Vertical voltage scales vary. See Fig. 6.11*a* for test circuit used to obtain these waveforms. (a) 10 M $\Omega$ , (b) 1 M $\Omega$ , (c) 100K $\Omega$ , (d) 10K $\Omega$ , (e) 1K $\Omega$ , (f) 100  $\Omega$ , (g) 10  $\Omega$ , and (h) 0  $\Omega$  (short circuit).









Figure 6.6. Crystal voltage decay as a function of crystal load capacitance. All waveforms with same time base of 2 msec/div and crystal disconnected from oscillator circuit. Vertical voltage scales vary. See Fig. 6.11*a* for test circuit used to obtain these waveforms. (a) 40 **pF**, (b) 200 **pF**, (c) 2000 **pF**, and (d) 20,000 **pF**.



**Figure** 6.7. Measured crystal Q versus parallel load resistance  $R_p$  across the crystal terminals.  $C_p = 10-20 \text{ pF}$ .

The Q curve at 10 MHz in Fig. 6.7 contains a measurement error at the high load resistance values, due to the 7 pF of shunt capacitance in the scope probe used. The shunt impedance of the 7 pF of probe capacitance is 3000  $\Omega$  at 10 MHz, which completely swamps out the effect of any high resistance values in parallel with it across the crystal. Without the loading of the probe's shunt capacitance, the Q curve of the 10-MHz crystal would probably look more like the dotted line shown in Fig. 6.7.

These experimental curves of crystal Q versus loading in Figs. 6.7 and 6.8 provide considerable information. First, capacitive loading in general gives a higher Q than resistive loading. Second, the best Q is obtained with the crystal short circuited. Third, each of the resistive loading curves in Fig. 6.7 shows a minimum Q at the middle values of resistive loading, and, in each case, parallel resistive loading  $R_p$  on the crystal must be increased or decreased by about two orders of magnitude away from the resistance value at minimum Q to get good circuit Q. Figure 6.9 shows these minimum Q resistance values plotted as a function of frequency. **Two** additional lines have been drawn in Fig. 6.9, **which are** parallel to the minimum Q line but displaced from it by two orders of magnitude in the parallel load-resistance value. Figure 6.9 shows graphically what resistance-loading values on the crystal will give both good and poor in-circuit Q at any frequency.



Figure 6.8. Measured crystal Q versus parallel load capacitance  $C_p$  across the crystal terminals.  $R_p = 10-1000 \text{ M}\Omega$ .

**Comparing experimental** data in Figs. 6.7 and 6.9 with the calculated data in Figs. 6.3 and 6.4, we see that they are the same except that the experimental values of parallel load resistance are lower than the calculated values by a factor of three at all frequencies. One difference between calculated and measured data is that the calculated value of parallel capacitance  $C_p$  is 5 pF while the experimental value is 15 pF, as defined by the impedance of the line of lowest Q in Fig. 6.9. The 15 pF consists of 5 pF of crystal terminal capacitance  $C_0$  plus 7 pF of scope probe capacitance plus 3 pF of stray capacitance. This 3 to 1 difference between the calculated and experimental values for the parallel load capacitance  $C_p$  would shift the experimental values of parallel load resistance downward by a factor of three, and this is exactly what a comparison of Fig. 6.9 with Fig. 6.4 shows. The experimental data thus confirms that the low Q at medium resistance values is due to converting



the parallel RC load values to their equivalent series values.  $R_p$ ,  $(R_s)_{load}$ ,  $C_p$ , and  $C_s$  are defined in Fig. 6.1c.

Figure

function

The calculation and measurement of the effects of various loads on crystal operation show the following:

1. The load tied across the cry&l's terminals, has a strong effect on the crystal's in-circuit Q.



Figure 6.10. Test circuits for measuring crystal loading effects on in-circuit Q: (a) at 4 kHz and 50 kHz and (b) at 100 kHz.

- 2. The equivalent series load resistance  $(R_s)_{load}$ , and not the parallel load resistance  $R_p$ , is the correct measure of resistive loading effects on the crystal's in-circuit Q.
- 3. Because a crystal always has a fixed shunt capacitance  $C_p$  of 5-15 pF across its terminals, Fig. 6.9 (or Fig. 6.4) is a valid graph of what values of parallel load resistance  $R_p$  across the crystal terminals will give a good or poor in-circuit Q.
- 4. High in-circuit Q can be obtained with either a high or low value of parallel load resistance  $R_p$  across the crystal terminals.
- 5. The worst value of parallel load resistance  $R_p$  for any given value of parallel capacitance  $C_p$ , that is, the resistance value that will give the lowest possible in-circuit Q, is equal to the reactive impedance of  $C_p$ .



Figure 6.11. Test circuits for measuring crystal loading effects on in-circuit Q: (a) at 1 MHz and (b) at 10 MHz.

The test circuits used for measuring the effects of loading on crystal Q are given in Figs. 6.10 and 6.11. In the 10-MHz test circuit, a dry reed relay rather than a mechanical switch was used to switch the crystal, since the contact bounce time of a manually operated switch was excessive at this frequency.

# ANALYSIS OF PHASE VERSUS FREQUENCY

For an oscillator to oscillate, the total phase shift around the oscillator loop has to be  $0^{\circ}$ ,  $360^{\circ}$ , or some multiple of  $360^{\circ}$ . If the total phase shift around the loop changes slightly, the oscillation frequency moves up or down until the total phase shift is again back at  $0^{\circ}$ ,  $360^{\circ}$ , or some multiple of  $360^{\circ}$ . The greater the rate of phase change with frequency, the less the frequency has to shift to drive the phase back to its null point. This correlates directly with circuit Q and the circuit's short-term frequency stability.

LC networks in the loop that are isolated from the crystal do not change phase with frequency fast enough to have any effect on shortterm stability. LC networks directly connected to the crystal do have an effect on the rate of phase change with frequency, primarily because they can be used to short out or hide resistive sources and loads from the crystal.

In the following sections, various crystal circuit configurations and load conditions are analyzed for gain and phase changes with frequency. The intent is to maximize the phase change with frequency, since this is what gives short-term stability to an oscillator.

For brevity, derivations of gain and phase-shift equations for the circuits are not shown, and only analytical results are given. The circuit equations are derived as follows. Each circuit consists of one to three interconnected loops of RLC components. An equation is written for each loop, using standard circuit analysis techniques, and steady state conditions are assumed. These equations are then solved as a simultaneous set of linear equations for the circuits' gain and phase-shift transfer functions of  $|E_0/E_i|$  and  $E_0/E_i \angle \theta$  and plotted as a function of fre-

**quency.** Since everything of interest happens near the crystal's **series**resonant frequency, the plotted data curves are limited to frequencies near series resonance, with the frequency scale marked in **parts-per**million (ppm) deviation from the crystal's series-resonant frequency.

The analysis has been simplified by ignoring the shunt capacitance  $C_0$  across the crystal's case terminals, which limits the validity of the analysis to what happens near series resonance. The analytical curves shown were programmed and calculated on a TI-59 calculator. To help make comparisons between circuits, all phase and amplitude curves are plotted to the same scale, and the same l-MHz crystal values are used in all the fundamental circuits. For the VHF harmonic circuits, the same 20-MHz third harmonic crystal values are used in all of those circuits.

#### 7.1. RESISTIVE LOAD ON CRYSTAL

A circuit with a resistive load on the crystal is shown in Fig. 7.1, with typical circuit values listed. Figure 7.2 shows the circuit's phase shift  $(E_0/E_i) \ \ 2\theta$  as a function of frequency, and Fig. 7.3 shows the circuit's gain  $E_0/E_i$  as a function of frequency. These curves are typical for a reasonably small resistive load on the crystal. Although not shown, if source and load resistances are increased, the rate of phase change with frequency decreases, indicating poorer short-term frequency stability. If source and load resistances are decreased, the rate of phase change with frequency increases, indicating better short-term frequency stability. The maximum phase change with frequency occurs with zero source and load resistances. Assuming no phase shift in the amplifier, this circuit will oscillate exactly at series resonance.

#### 7.2. CAPACITIVE LOAD ON CRYSTAL

A circuit with a capacitive load on the crystal is shown in Fig. 7.4, with typical circuit values listed. Figure 7.2 shows the circuit's phase shift



Figure 7.1. Resistive load on crystal: Frequency = 1 MHz;  $L_x = 4.2$  H;  $C_x = 0.006031228$  pF;  $R_s = 240$ R;  $R_1 = 120$ i-l;  $R_2 = 120$   $\Omega$ .



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Figure 7.4. Capacitive load on crystal: Frequency = 1 MHz;  $L_x = 4.2$  H;  $C_x = 0.0060310228$  pF;  $R_s = 240 \Omega$ ;  $R_1 = 120 \Omega$ ;  $C_2 = 1000$  pF.

 $(E_0/E_i) \angle \theta$  with frequency, and Fig. 7.3 shows the circuit's gain  $|E_0/E_i|$  versus frequency. Note that in Fig. 7.2 the phase slope is greater with a capacitive load than a resistive load on the crystal.

The general idea is to try to use these circuits where the phase slope is the steepest. With the capacitive load this occurs at 3 ppm above the l-MHz series-resonance frequency. The phase shift through the network at this frequency is a 90" lag. Amplifiers usually have a phase shift of  $0^{\circ}$  or 180". So if this capacitive load circuit is to be used in an oscillator, another 90° phase-shift network should be added to the circuit either to increase the phase shift to 180" or decrease it to 0°, depending on whether the amplifier is inverting or noninverting.

### 7.3. PIERCE CIRCUIT

A simplified Pierce circuit (without amplifier) is shown in Fig. 7.5. An explanation of how this circuit works is given in Section 5.8 and will not be repeated here. The phase shift of this circuit from input to output  $(E_0/E_i) \ 2\theta$  is shown in Fig. 7.2; the amplitude transfer function, or gain,  $E_0/E_i$  is shown in Fig. 7.3. Figure 7.2 shows that if this circuit is used with a 180" inverting amplifier, it will oscillate about 6 ppm above series resonance.



Figure 7.5. Simplified Pierce circuit: Frequency = 1 MHz;  $L_x = 4.2$  H;  $C_x = 0.0060310228$  pF;  $R_s = 240 \Omega$ ;  $R_1 = 1000 \Omega$ ;  $R_2 = 1000 \Omega$ ;  $C_1 = 0.001 \mu$ F;  $C_2 = 0.002 \mu$ F.

The phase slope is higher than either the resistive or capacitive load circuits in Fig. 7.2, indicating that it will have better short-term frequency stability than either of those circuits. Note that in Fig. 7.5 capacitors  $C_1$  and  $C_2$  tend to short out source and load resistances, raising the crystal's effective in-circuit Q. It is this shorting-out factor that gives the Pierce circuit its high phase slope with frequency and the very good frequency stability that goes with it.

## 7.4. COLPITTS CIRCUIT

A simplified Colpitts circuit (without amplifier) is shown in Fig. 7.6. As mentioned in Section 5.3, the Colpitts has three different operating states: transistor on, transistor saturated, and transistor shut off. The longest of the three states occurs when the transistor is shut off, so the shut-off stage was picked as the most typical and is the one shown in Fig. 7.6. The phase shift  $(E_0/E_i) \angle \theta$  of this circuit is shown in Fig. 7.2, and the amplitude transfer function, or gain,  $E_0/E_i$  is shown in Fig. 7.3.

The solid curves in Figs. 7.2 and 7.3 represent a transistor-Colpitts, where the crystal's load resistor  $R_2$  is the transistor's base bias resistor of 100K  $\Omega$ . The dotted curves represent a FET-Colpitts circuit, where the crystal's load resistor  $R_2$  is the FET's gate-to-ground resistor of 22 M $\Omega$ . The circuit's actual frequency stability is better than the low slope of the phase shift curve in Fig. 7.2 would indicate, which means that the transistor shut-off state shown in Fig. 7.6 is a poor average of the three states in the actual circuit. Improving the simplified circuit's accuracy requires including the other two states of operation. This requires a large effort. It



Figure 7.6. Simplified Colpitts circuit: Frequency = 1 MHz;  $L_x = 4.2$  H;  $C_x = 0.0060310228$  pF;  $R_s = 240$ R;  $R_1 = 2K\Omega$ ;  $R_2 = 100K\Omega$ ;  $C_1 = 220$  pF;  $C_2 = 47$  pF.

is necessary to match the boundary conditions of the three operating states and the results are not considered worth the effort.

However, the phase shift curve in Fig. 7.2 is correct in showing that the oscillation frequency is a high 79 ppm above series resonance (the actual oscillation frequency measured in the 1 MHz transistor-Colpitts circuit was 94 ppm above series resonance). Note that the phase shift curve in Fig. 7.2 shows 0" phase shift at two frequencies where oscillation could occur, but that the amplitude curve in Fig. 7.3 shows that only the higher frequency of 79 ppm above series resonance has enough gain (i.e., >1) for oscillation to occur.

#### 7.5. MODIFIED MEACHAM CIRCUIT

The modified Meacham half bridge circuit is shown for analysis in Fig. 7.7. The coefficient P allows various bridge excitation ratios between the split-load phase inverter's emitter and collector voltages. When the bridge's excitation ratio P is changed, the bridge resistor  $PR_2$  is changed proportionately with respect to the crystal's internal series resistance  $R_s$  in order to maintain bridge balance.

The emitter and collector source resistances  $R'_1$  and  $R_1$  have different resistance values when measured independently with respect to ground. The two source resistances have the same resistance value, however, if measured with a load tied between them rather than from each point to ground. The source resistances are equal even if the phase inverter's emitter and collector resistors ( $R'_1$  and  $R_2$ ) are not equal.

The capacitances shunting the two bridge arms are nominally bal-



Figure 7.7. Modified Meacham half-bridge circuit: Frequency = 1 MHz;  $L_x = 4.2 \text{ H}$ ;  $C_x = 0.0060310228 \text{ pF}$ ;  $R_s = 240 \Omega$ ;  $R_1 = 8 \Omega$ ;  $R'_1 = 8 \Omega$ ;  $R_L = 2000 \Omega$ ; P = 1, 0.5, 0.25, 0.125;  $R_2 = 240$ , 480, 960, 1920R.

anced to the bridge null. For simplicity, they are left out of the analysis, since they are primarily important for high-frequency stability reasons in this circuit and have little effect on oscillation frequency. The omission limits the accuracy of the analysis, but the intent here is to show only the general amplitude and phase characteristics of the bridge.

Figures 7.8 and 7.9 show the phase shift  $(E_0/E_i) \angle \theta$  and gain  $|E_0/E_i|$  of the modified Meacham half-bridge circuit for various amounts of bridge unbalance. Both bridge arms have equal excitation voltages (P = 1). The



**Figure 7.8.** Bridge phase shift versus frequency for several amounts of imbalance from null. Bridge excitation ratio P = 1 for all curves.



**Figure** 7.9. Bridge gain versus frequency for several amounts of imbalance from null. Bridge excitation ratio P = 1 for all curves.

only changes in the curves occur near the crystal's resonant frequency (1 MHz, in this case), so only the circuit's response at frequencies near resonance is shown. The curves are plotted in terms of the bridge-imbalance ratio  $R_2/R_s$ . When  $R_2/R_s = 1$ , the bridge is balanced with zero output from the bridge at resonance, as shown in Fig. 7.9. At frequencies away from resonance, the output amplitude approaches the input amplitude regardless of the amount of imbalance.

The phase shift through the bridge varies from + 180° at low frequencies to 0" at resonance to – 180" at high frequencies. The one exception to this phase characteristic is when the ratio  $R_2/R_s$  is less than one, and then the phase shift through the bridge stays near +180° at all frequencies. The circuit will not oscillate (except parasitically) when *RJR*, is equal to or less than one, so the useful phase curves are those with a ratio of  $R_2/R_s$  greater than one.

The steeper the slope of the phase shift curve in Fig. 7.8, the better the short-term frequency stability will be, since a smaller frequency change is then needed to provide any given amount of phase-angle correction and maintain the total phase shift around the oscillator loop at 0" (or 360"). To provide a comparison, the Pierce circuit's phase shift (Fig. 7.2) falls about halfway between the two phase-shift curves  $R_2/R_s = 2$  and  $R_2/R_s = 4$  in Fig. 7.8 or at about  $R_2/R_s = 3$ . Thus, by operating the Meacham half-bridge with a  $R_2/R_s$  ratio of less than three, we should get a short-term stability better than that of the Pierce circuit. The Meacham circuit can be operated with a  $R_2/R_s$  ratio of less than three (a ratio of 1.0 is the theoretical limit) by the simple expedient of increasing the oscillator's amplifier gain. In practice, this is not so simple, since the tendency for parasitic oscillation increases when the gain is increased.

There are advantages to operating the Meacham half-bridge with unequal excitation voltages ( $P \neq 1$ ) to the two bridge arms. In particular, it is advantageous for the excitation voltage driving the crystal to be larger than the voltage driving  $R_i$ . These advantages are described in detail in Section 5.11. Figures 7.10 and 7.11 show the bridge's phase shift  $(E_0/E_i \ \ d\theta$  and gain  $|E_0/E_i|$  functions for several values of P, the bridge excitation ratio.

All of the curves in Figs. 7.10 and 7.11 use the same bridge-imbalance ratio  $R_2/R_s = 2$ . This imbalance ratio is typical of the actual Meacham circuits described later in Chapters 10 and 11. The curves show that changing the excitation ratio does not change the phase curve much, but it does change the amplitude curve considerably, particularly at frequencies away from resonance. At frequencies away from resonance, the bridge's gain, or amplitude ratio,  $|E_0/E_i|$  decreases in direct proportion as the excitation ratio P is decreased, which helps considerably in reducing parasitic oscillations.

The exact amount of bridge imbalance is slightly different in each of the four curves in Figs. 7.10 and 7.11, since the source resistances  $R_1$  and  $R'_1$  do not change with *P*. The effect of the difference on the curves is relatively small. The biggest effect is a 16% reduction in the gain curves in Fig. 7.11 at the frequency of resonance (1 MHz).



Figure 7.10. Bridge phase shift versus frequency for several values of bridge excitation ratio P. The bridge has a fixed null imbalance of  $R_2/R_s = 2$  for all curves.

#### 7.6. BUTLER HARMONIC CIRCUITS, C-TAP

The capacitive tap versions of Butler's emitter follower and common base oscillator circuits are shown in Figs. 7.12 and 7.13. These two circuits are analyzed together, since analytically they are the same circuit, one being the reverse of the other. The one difference between them is the gain  $|E_0/E_i|$ , which peaks at about 2.3 maximum for the emitter follower circuit and at about 0.035 maximum for the common base circuit. Phase shifts are the same, gain curve shapes are the same, and the crystal's source impedance  $Z_s$  in one circuit is the crystal's load impedance  $Z_L$  in the other. The notation of the emitter follower circuit will be used here for convenience, since its amplifier has a known gain of one with



Figure 7.11. Bridge gain versus frequency for several values of bridge excitation ratio *P*. The bridge has a fixed null imbalance of RJR, = 2 for all curves.



Figure 7.12. Butler emitter follower, capacitive tap.



Figure 7.13. Butler common base, capacitive tap: Frequency = 20 MHz;  $L_x = 0.053$  H;  $C_x = 0.0011948253$  pF;  $R_s = 30$   $\Omega$ ;  $R_1 = 0.02-0.45$   $\Omega$ ;  $R_2 = 15$   $\Omega$ ;  $R_3 = 1000$   $\Omega$ ;  $C_1 = 12.448$  pF;  $C_2 = 150$ , 330, 680 pF;  $L_1 = 0.25-4.0$   $\mu$ H.

zero phase shift, which makes the gain and phase curves easier to understand and interpret. The oscillation frequency used is 20 MHz, since this is the lowest frequency that this circuit is likely to be used at.

The crystal's load impedance is primarily determined by  $C_2$ .  $C_2$  is normally selected so that its impedance is approximately equal to or a little less than the crystal's internal series resistance  $R_s$ . For analysis purposes, three values of  $C_2$  are selected-one whose impedance is lower than  $R_s$ , one approximately equal to  $R_s$ , and one higher than  $R_s$ . For each value of  $C_2$ , three values of  $L_1$  are selected, with the middle value of  $L_1$  in each case selected to give near maximum circuit gain. This gives nine sets of data, which are sufficient to show the effects of the different circuit components. These nine data sets are plotted in Figs. 7.14, 7.15, and 7.16 and show the following results:

- 1. Circuit loop gain varies with frequency,  $L_1$ , and  $C_1$ . For any given value of  $C_2$ , there is an optimum value of  $C_1$  for maximum circuit gain, Maximum circuit gain occurs when  $L_1$  is selected to give a  $C_2/C_1$  ratio of about 4.
- 2. Oscillation is generally slightly *above* series resonance but can be set exactly at series resonance by tuning  $C_1$  to the right value.
- 3. The impedance of  $C_2$  must be equal to or less than the crystal's internal series resistance  $R_s$  if the crystal's load impedance is to be kept reasonably small.
- 4. The frequency of oscillation is relatively insensitive to the value of  $C_2$ . Making  $C_2$  smaller moves the oscillation band slowly upward and farther away from series resonance.
- 5. Slopes of the better phase shift versus frequency curves are reasonably high, indicating that good short-term frequency stability can be obtained by selecting the right component values.



Figure 7.14. Gain versus frequency for Butler circuits, C-tap.

All five of these analytical results have been observed experimentally in the test circuits. It may be helpful to explain how data in Figs. 7.14, 7.15, and 7.16 were calculated. Oscillation occurs at that frequency where the phase shift through the network is zero. For a given set of circuit values, the frequency of zero phase shift (i.e., the frequency of oscillation) is varied by tuning C<sub>1</sub> over a range of values. The gain through the circuit at each frequency of zero phase shift  $(E_0/E_i) \angle \theta = 0^\circ$  is plotted in Fig. 7.14 as a function of the oscillation frequency. The crystal's load impedance  $|Z_L|$  is plotted in Fig. 7.16 as a function of the oscillation frequency, under the same condition of zero phase shift through the circuit.

For the plots of phase shift  $(E_0/E_i) \angle \theta$  versus frequency in Fig. 7.15, values of all circuit components including C<sub>1</sub> are held fixed, since we are interested here in how large a phase-angle correction is generated if the



Figure 7.15.

oscillation frequency were to deviate slightly from the frequency of zero phase shift. The frequencies at which the phase shifts were calculated were at the peaks of the gain curves shown in Fig. 7.14. Any part of the gain curves in Fig. 7.14 could have been used, however, since phaseshift calculations at other frequencies across the gain curves all showed the same rate of phase change with frequency.

# 7.7. BUTLER HARMONIC CIRCUITS, L-TAP

Inductive tap versions of Butler's emitter follower and common base amplifier circuits are shown in Figs. 7.17 and 7.18. The two circuits are



Figure 7.16. Crystal load impedance versus frequency for Butler circuits, C-tap,



Figure 7.17. Butler emitter follower, inductive tap.



**Figure** 7.18. Butler common base, inductive tap: Frequency = 20 MHz;  $L_x = 0.053$  H;  $C_x = 0.0011948253$  pF;  $R_s = 30 \Omega$ ;  $R_1 = 0.01 - 0.41 \Omega$ ;  $R_2 = 0.004 - 0.036$   $\Omega$ ;  $R_3 = 1000 \Omega$ ;  $R_4 = 15 \Omega$ ;  $C_1 = 7 - 270$  pF;  $K = M/\sqrt{L_1L_2} = 0.12$ ;  $L_1 = 0.14 - 3.45 \mu$  H;  $L_2 = 0.08$ , 0.15, 0.30  $\mu$  H;  $M = .013 - 0.122 \mu$  H;  $L_{total} = L_r + L_2 + 2M = 0.25 - 4.0 \mu$ H.

analyzed together, since analytically they are the same circuit, one being the reverse of the other. The one difference between them is the gain  $|E_0/E_i|$ , which peaks at about 2.3 maximum for the emitter follower circuit and at about 0.035 maximum for the common base circuit. Phase shifts are the same, gain curves are the same, and the crystal's source impedance  $Z_s$  in one circuit is the crystal's load impedance  $Z_L$  in the other. The notation of the emitter follower circuit will be used here, since its amplifier has a known gain of one with zero phase shift, which makes the calculated gain and phase curves easier to understand and interpret. The oscillation frequency used is 20 MHz, since this is the lowest frequency at which this circuit is likely to be used.

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The crystal's load impedance is primarily determined by  $L_2$ , the inductance of the tapped portion of the inductor, as shown in Figs. 7.17 and 7.18. Normally,  $L_2$  is selected so that its impedance is approximately equal to or a little less than the crystal's internal series resistance  $R_s$ . For analysis purposes, three values of  $L_2$  are selected, whose impedances are lower than  $R_s$ , approximately equal to  $R_s$ , and higher than  $R_s$ . And for each value of  $L_2$ , three inductance values for the whole inductor  $L_{total}$  are selected, with the middle value selected in each case to give near maximum circuit gain. This gives nine sets of data, which are sufficient to show the effects of different circuit components. The single-layer aircore Miller coils used in the test circuits had an average coefficient of

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Figure 7.19. Gain versus frequency for Butler circuits, L-tap.

coupling K ( $K = M/\sqrt{L_1L_2}$ ) of 0.12. This coefficient was used to specify mutual inductance **M** between the two parts of the solenoid coil **L**, and  $L_2$ .

Analytical data are plotted in Figs. 7.19, 7.20, and 7.21 and show the following results:

- 1. Circuit gain varies with frequency,  $L_1$ , and  $C_1$ . For any given value of  $L_2$ , there is an optimum value of  $L_1$  for maximum circuit gain. Maximum circuit" gain occurs when the crystal is tapped into the coil at about  $\frac{1}{6}$  of the coil's total number of turns.
- 2. Oscillation is generally **below** series resonance but can be set exactly **at** series resonance by tuning  $C_1$ .



Figure 7.20. Phase shift versus frequency for Butler circuits, L-tap,

- 3. The impedance of  $L_2$  must be equal to or less than the crystal's internal series resistance  $R_s$  if the crystal's load impedance is to be kept reasonably small.
- 4. Frequency of oscillation is relatively insensitive to the value of  $L_2$ . Making  $L_2$  larger moves the oscillation band slowly downward and farther away from series resonance.
- 5. Slopes of the better curves of phase shift versus frequency are reasonably high, indicating that good short-term frequency stability can be had by selecting the right component values.



Figure 7.21. Crystal load impedance versus frequency for Butler circuits, L-tap.



Frequency deviation from 2Q MHz, in ppm

Figure 7.22. Gain versus frequency for Butler circuits, L-tap, as a function of the coil's mutual coupling coefficient K.  $L_1 = 0.7686 \ \mu H, L_2 = 0.15 \ \mu H.$ 

#### BUTLER HARMONIC CIRCUITS, L-TAP



Figure 7.23. Phase shift versus frequency for Butler circuits, L-tap, as a function of the coil's mutual coupling coefficient K.  $L_1 = 0.7686 \ \mu H$ ,  $L_2 = 0.15 \ \mu H$ .

6. Maximum gain is about 2.4 peak for the Butler emitter follower circuit. And although it is not shown in the figures, maximum gain for the Butler common base circuit was calculated as 0.035 peak.

The curves in Figs. 7.19, 7.20, and 7.21 were calculated the same way as curves in Figs. 7.14, 7.15, and 7.16. The reader is referred to Section 7.6 for an explanation of how these curves were calculated.

All six of the analytical results have been observed experimentally in test circuits, with one important difference. The inductive tap circuit would oscillate only below and not at series resonance. In the test circuits, gain curves in Fig. 7.19 appeared to be shifted about 5 ppm farther down in frequency. The Butler emitter follower circuit (but'not the Butler common base circuit) could be made to oscillate at series resonance or slightly above it, just as Fig. 7.19 shows, by removing the diode amplitude clamp across the coil. Why this happens is not understood.



**Figure 7.24.** Crystal load impedance versus frequency for Butler circuits, L-tap, as a function of the coil's mutual coupling coefficient K.  $L_1 = 0.7686 \ \mu H$ ,  $L_2 = 0.15 \ \mu H$ .

The inductive tap circuit differs from the capacitive tap circuit in that it has mutual coupling between the two tapped portions of the coil. Does the mutual coupling have any effect on the circuit? Not much, it turns out. The maximum practical value of the coefficient of coupling K for a single-layer tapped solenoid is about 0.3. Figures 7.22, 7.23, and 7.24 show calculated values of circuit gain, phase shift with frequency, and crystal load impedance for three values of K (0, 0.12, and 0.30), while leaving the values of L, and  $L_2$  constant. As can be seen from the curves, the slope of the circuit's phase shift with frequency, the gain, and frequency of oscillation change very little when K changes. Only the crystal's load impedance changes significantly, increasing about 50% over the full range of K from 0 to 0.3.

The effect of mutual inductance on the circuit was checked in test circuits by breaking the tapped coil into two separate inductors oriented at 90" for minimum coupling (K = 0). The peak of the oscillation band did not shift, staying at about 5 ppm below series resonance, and the oscillation frequency stayed below series resonance.

I

# CHAPTER EIGHT

# TRIMMING THE CRYSTAL FREQUENCY

A certain amount of  $\pm$  frequency tolerance must be allowed in manufacturing crystals to a specific frequency. In addition, either a reactive load on the crystal or a phase shift in the oscillator's amplifier will move the actual oscillation frequency slightly up or down from the crystal's own internal series-resonant value. To tune a crystal oscillator to a specific frequency, it is necessary to adjust the phase shift somewhere in the amplifier loop. This can be done by inserting either a variable inductor or a variable capacitor in the circuit, or by varying the resistance in an already existing RC or RL phase-shifting network. To raise the frequency, a phase lead is added to the amplifier loop, or an existing phase lag is decreased. To lower the frequency, a phase lag is added to the amplifier loop, or an existing phase lag is increased. In a harmonic oscillator, the frequency can be trimmed both up and down by varying the tuning of the circuit's LC tank.

The most common method of frequency trimming is putting a variable capacitor either in series or in parallel with the crystal. Figure 8.1 shows a variety of resistive and capacitive trimmer locations for three popular oscillator circuits. Table 8.1 shows the relative frequency sensitivity of most of these locations. Using an inductor rather than a capacitor will reverse the direction of frequency shift.

Placing a capacitor or an inductor directly in parallel with the crystal for frequency trimming purposes is not recommended, since it tends to short out the crystal and reduce the crystal's control over the circuit. Frequency trimming capacitors or inductors are not used in oscillator circuits in this book for reasons of simplicity and to make the circuits easier to understand.



Figure 8.1. Capacitor locations for frequency trimming in three popular oscillator circuits. \*Indicates locations that are not recommended. (a) Series resonant, (b) Colpitts, and (c) Pierce.

## TABLE 8.1

Relative Frequency Sensitivity of Various Condenser Trimmer Locations at 1 MHz

Circuit	Capacitance or Resistance Added	At Circuit Location <sup>a</sup> in Fig. 8.1 Marked	Frequency Change at 1 MHz ( <b>in ppm</b> )
Series resonant	+33 pF	А	+ 120.
Series resonant	+33 pF	*B	-0.9
Series resonant	+33 pF	С	0.3
Series resonant	$+33  \mathrm{pF}$	D	-0.3
Colpitts	$+33  \mathrm{pF}$	*E	-89.
Colpitts	$+33 \mathbf{pF}$	F	+ 103.
Colpitts	+3 pF (10% of G)	G	-30.
Colpitts	+15  pF (10%  of  H)	H	-3.
Colpitts	$+\Delta R(10\% \text{ of } J)$	I	AF
Pierce	$+\Delta R(10\% \text{ of K})$	K	- A F
Pierce	+100  pF (10%  of  L)	$\boldsymbol{L}$	- 6 .
Pierce	$+100  \mathrm{pF}  (10\%  \mathrm{of}  M)$	М	-0.3
Pierce	$+15  \mathrm{pF}$	*N	+0.1
Pierce	$+15 \overline{\mathrm{pF}}$	P	-0.3

"The \* indicates locations that are not recommended.

# THESTART-UPPROBLEM

Normally, when power is applied to an oscillator, we expect it to start oscillating. Unfortunately, it does not always start unless positive steps are taken to make sure it does. The key is DC biasing, and the solution is a little different for discrete transistors than for integrated circuits. The first section of this chapter covers biasing **ICs**, while the second covers biasing discrete transistors.

### 9.1. BIASING ICs

The amplifiers used in most of the IC oscillator circuits in this book are digital amplifiers: logic inverters, line receivers, voltage comparators, and so forth. They are designed to be used in either a "0" or "1" state. In either state, the amplifier is saturated, and the gain is zero. For oscillation to occur, a circuit's loop gain must be greater than one. Once oscillation starts, energy storage in the crystal will carry the oscillator through the saturated zero-gain intervals. Loop gain exceeds one only during switching intervals between binary states, closing the loop over part of each cycle. When power is first applied to a digital circuit, however, there is no energy storage in the crystal. And if the amplifier is in either binary state, loop gain is zero, and oscillation will not start.

The key to the start-up problem is selecting digital amplifiers to which negative feedback can be applied, in order to bias the amplifier's input and output terminals in the middle of their transition zones between the zero and one states, where the digital amplifier has a finite gain. Since negative feedback is needed only for DC biasing conditions, a shunt capacitance to ground can be added after the feedback resistor to (1) pro-
vide a **6-dB**/octave frequency roll-off that will ensure a stable feedback amplifier condition and (2) limit the gain-reducing effects of the negative feedback network to low frequencies. The negative feedback network ensures that oscillation will always start when power is applied.

For an example, refer to the oscillator circuit in Fig. 9.1. This oscillator uses a voltage comparator as an amplifier. The voltage comparator is assumed to be a TTL unit with an output swing between 0 V and +5 VDC. The midpoint of the two resistors  $R_1$  and  $R_1$  provides a +2.5 VDC reference point halfway between binary zero and one output states. The positive (+) amplifier input terminal is tied to this DC reference point by  $R_{2}$ , and the comparator output will tend to follow this input toward one or the other of its two binary states.  $R_3$  provides negative feedback from the amplifier output to the negative (-) input terminal of the amplifier in order to force the output voltage to follow the input voltage, and it stabilizes at +2.5 VDC. Capacitor  $C_1$  limits negative feedback to low frequencies and together with  $R_3$ , provides a 6-dB/octave roll-off, which gives an inherently stable feedback amplifier condition. Both amplifier input and output are then in an unsaturated state, being biased in the middle of the transition zone, and the gain through the comparator amplifier is then greater than zero. All IC oscillators in this book use the negative feedback concept to ensure oscillation at start-up.



Figure 9.1. Solving the start-up problem with negative feedback.

100 C

#### BIASING DISCRETE TRANSISTORS

# 9.2. BIASING DISCRETE TRANSISTORS

Just as with an IC oscillator, a discrete transistor oscillator must be biased within its linear region if it is to start oscillating when power is applied. It is preferable to bias the transistor stage near the middle of its linear region, which means adjusting the bias so that the collector's DC output voltage is held halfway between ground and the power supply voltage. Figure 9.2 shows an assortment of DC biasing methods for a common emitter pulse-amplifier stage. These biasing circuits illustrate the tradeoff between circuit complexity and bias stability. The first three use a passive biasing arrangement, the second three use an active constant-current arrangement, and the last one uses an active voltagefeedback circuit. A short description of each configuration follows.

The simplest biasing arrangement is shown in Fig. 9.2*a* and is useful only at low and medium frequencies in a benign environment. There is no correction in this circuit for gain changes with temperature, and an adjustable resistor  $R_3$  is required to handle gain differences between individual transistors. The collector's output voltage changes considerably if the power supply voltage changes by even a small amount. The circuit does not work well at high frequencies because it does not have a base-to-emitter discharge resistor  $R_2$ , as shown in Fig. 9.2*b*. This resistor  $R_2$  is required for fast discharge of the transistor's base-to-emitter junction capacitance.

Figure 9.2b shows a biasing method that works a little better. Negative DC feedback from the collector is used to bias the transistor's base. Depending on the value of  $R_2$ , negative feedback will hold the collector's output voltage somewhere between a constant voltage and half the supply voltage, over a reasonably large supply-voltage change. Gain changes with temperature are partially corrected for. An adjustable biasing resistor  $R_3$  is required to handle gain differences between individual transistors. This circuit will work at high frequencies because it has a base-to-emitter resistor  $R_2$  for fast discharging of the transistor's base-to-emitter capacitance.

The biasing arrangement shown in Fig. 9.2*c* is widely used because it does not require an adjustable resistor. The collector's output voltage holds reasonably close to half the power supply voltage, with large changes in the power supply voltage and gain changes with temperature reasonably well-corrected for. The key to biasing this circuit is holding the base at a constant bias voltage (with a fixed power supply voltage) over the three to one differences in emitter current between individual transistors. An emitter resistor  $R_4$  is required and used as an emitter cur-



Figure 9.2(a-g). Some DC biasing schemes for a common emitter pulse amplifier stage.

and the second second

rent feedback resistor.  $R_4$  is selected to be a reasonably large percentage of the collector resistor  $R_1$ . The biasing resistors  $R_2$  and  $R_3$  are given medium resistance values, so that the usual 3 to 1 variation in the base biasing current between individual transistors does not shift the base biasing voltage significantly. Diode  $D_1$  compensates for the transistor's base-to-emitter voltage drop. The diode is sometimes omitted in order to reduce circuit complexity. A fair amount of calculation is required to design this circuit, using maximum and minimum transistor gains and gain changes with temperature.

Figure 9.2*d* uses a FET to provide constant biasing current into the transistor's base. Depending on the value of  $R_2$ , the collector's output voltage is held somewhere between a constant voltage and a fixed voltage increment below the power supply voltage. Gain changes with temperature are not corrected for. An adjustable biasing resistor  $R_3$  is required to compensate for pinch-off voltage differences between individual FETs and gain differences between individual transistors.

Figure 9.2*e* is useful if a negative supply voltage is available. It operates the same as Fig. 9.2*d* except that gain differences between individual transistors and transistor gain changes with temperature are corrected for. FET gain changes with temperature can be compensated for by adjusting current through the FET to its temperature null value. An adjustable biasing resistor  $R_3$  is required to handle pinch-off voltage variations between individual FETs.

Figure 9.2f uses an emitter resistor  $R_2$  to sample the emitter current of Q<sub>1</sub>, Q<sub>2</sub> varies bias voltage on Q<sub>1</sub> to maintain a constant emitter current in Q. Q<sub>1</sub>'s collector output voltage is maintained at a fixed voltage increment below the power supply voltage. Gain changes with temperature are partially compensated for.

The best biasing scheme is also the most complex one, and it is shown in Fig. 9.2g. Figure 9.2g uses two transistors in a voltage-feedback scheme from the collector to the base of  $Q_1$ . It maintains the collector of  $Q_1$  at one-half the supply voltage plus one  $V_{be}$  (base to emitter voltage, about 0.4 V). Transistor  $Q_2$  measures the voltage difference between the collector of  $Q_1$  and the center point of the two resistors  $R_3$  and  $R_3$ , which is amplified and fed back to the base of  $Q_1$ .  $Q_1$ 's collector voltage holds quite accurately at half the supply voltage plus one  $V_{be}$  because of the gain in the feedback way. Gain changes with temperature in all of the transistors are corrected for, and no adjustable resistor is required.

# DISCRETE TRANSISTOR OSCILLATORS

This chapter contains performance test data on the discrete transistor oscillator circuits described in Chapter 5. It is divided into three parts: The first describes the circuit selection and testing philosophy used; the second part describes individual fundamental oscillator circuits one by one; and the third describes individual harmonic oscillator circuits.

# A. CIRCUIT SELECTION AND TESTING

The basic approach in selecting discrete transistor circuits was first to try all basic circuit types, then build a test circuit of each type to determine its strong and weak points. A total of 22 fundamental and 12 harmonic discrete transistor circuits were evaluated in this way. Where practical, the fundamental circuits were all tested at the same frequency of 1 MHz for comparison purposes, and the more important ones were also tested at the frequency extremes of 4 kHz and 20 MHz.

The harmonic circuits were tested at three frequencies: 20, 50, and 100 MHz. Except for special cases, 20 MHz is the lowest frequency at which a harmonic circuit would be used, and 100 MHz is near the upper 200-MHz harmonic frequency limit. 50 MHz was picked as near the middle of the harmonic frequency band.

After selection, each test circuit was individually optimized for best component values, bias, waveforms, and so forth. Because the transistors used have a strong effect on circuit performance, considerable time was spent selecting the right ones for each circuit. Many discrete transistor circuits are not compatible with digital logic, so level shifters or buffers were added to some of them to make them TTL compatible.

Photographs were taken of oscillator waveforms at various points in the circuits. The waveform photos of each circuit have been synchronized to a common point in time and vertically aligned together on the printed page to permit vertical phase comparisons between various parts of each circuit. To facilitate comparing the circuits with one other, the same crystals were used in all circuits, moving them from circuit to circuit as needed. The crystal most used is a l-MHz crystal. It is an AT cut with an internal series resistance of 240  $\Omega$  and is solder sealed in a gas-filled HC-6 metal can.

The circuits were tested for frequency sensitivity to supply voltage and temperature variations. Sensitivity to supply voltage is checked by measuring the frequency shift when the power supply voltage is changed from +4 to +6 VDC. Since the object of the temperature testing was to measure temperature characteristics of the oscillator circuit itself and not the crystal, only the oscillator circuit was subjected to temperature changes, with the crystal left at room temperature. Temperature changes were obtained by the rather crude method of spraying the circuits (but not the crystal) with freon from an aerosol can for 10 seconds to cool the circuits, and blowing hot air on the circuits (but not on the crystal) with a heat gun for 20 seconds to heat the circuits. The temperature sensitivity numbers given in Tables 12.1, 12.2, and 12.3 are the changes in oscillator frequency when the circuit was heated or cooled in this fashion. The intention was to get a rough rather than accurate measure of the circuits' sensitivity to these effects.

The short-term frequency stability of some of the oscillator circuits was checked by measuring the frequency with a frequency counter and looking at the variation in frequency over a short 20-40 second time interval. Measured this way, short-term stability contains errors due to the  $\pm$  1 count accuracy of the counter and inherent short-term frequency variations in the counter's internal oscillator. The intent, again, was to get a rough rather than accurate measure of the short-term stability of the different circuits.

Because temperature and short-term stability measurements were not very accurate, no attention should be paid to small differences in these numbers among circuits. Only a reasonably large difference has any significance.

No long-term frequency stability measurements were made on any oscillator circuits. There are several reasons for this. First, the stability

#### MILLER-TRANSISTOR

needs of most digital circuitry can be satisfied with much less than the maximum stability obtainable from a crystal oscillator. Second, to be meaningful, any long-term stability measurements would have to be made over a protracted period of time. And third, even if such data were obtained, it would be difficult to sort out what was due to the circuit from what was due to the crystal.

# B. FUNDAMENTAL CIRCUITS

## **10.1. MILLER-FET**

The schematic of this oscillator at 1 MHz is shown in Fig. 10.1a. The crystal operates as a shunt element in this circuit and requires a high load resistance to operate properly. A FET has a high input resistance and makes an ideal amplifier here. The parallel  $L_1C_1$  network is not at resonance and must have a net inductive impedance for oscillation to occur. Although  $C_1$  is not necessary for oscillation to occur, the photographs in Figs. 10.1b and c show how much  $C_1$  cleans up the waveform across  $L_{\ell}$ . With  $C_1 = 470$  pF, the waveform across the crystal improves to a very nice sine wave and increases considerably in amplitude. The oscillation frequency is very sensitive to  $C_2$  and the drain-to-gate capacitance in parallel with  $C_2$ . Because the effective value of  $C_2$  is  $C_2$  multiplied by the amplifier gain (the Miller effect), the frequency changes significantly when the FET is changed or when the stage gain changes with power supply or temperature changes. Because of this, the Miller circuit is not a very stable oscillator.

# **10.2. MILLER-TRANSISTOR**

The schematic of this oscillator at 1 MHz is shown in Fig. 10.2*a*. The purpose of this circuit is to show the heavy crystal loading that occurs if a bipolar transistor is used for the amplifier instead of a FET. The parallel  $L_1C_1$  network must have a net inductive impedance for oscillation to occur. Although  $C_1$  is not necessary for oscillation to occur, waveform photographs in Figs. 10.2*b* and c show how much  $C_1$  cleans up waveforms across both  $L_1$  and the crystal. The crystal waveform in Fig. 10.2*c* is still very poor even with  $C_1 = 470$  pF and shows that using a bipolar transistor rather than a FET gives a much poorer oscillator.

The oscillation frequency is very sensitive to  $C_2$  and the transistor's



Figure 10.1. Miller-FET at (a) 1 MHz, (b)  $C_1 = 0$ , and (c)  $C_1 = 470$  pF.

collector-to-base capacitance in parallel with  $C_2$ . Because the effective value of  $C_2$  is  $C_2$  multiplied by the amplifier gain (Miller effect), frequency changes significantly when the transistor is changed or when the amplifier gain changes with power supply or temperature changes. Because of this, the Miller circuit is not a stable oscillator.

# 10.3. COLPITTS-PET

A schematic of this circuit at 1 MHz is shown in Fig. 10.3a. The Colpitts is a parallel resonant circuit and requires a high shunt-load impedance on the crystal. A FET amplifier, with its high input impedance, is a good





Figure 10.2. Miller-transistor at (a) 1 MHz, (b)  $C_1 = 0$ , and (c)  $C_2 = 470$  pF.

selection for the Colpitts oscillator. The voltage swing on the crystal is rather large, from +6 to -6 VDC. The waveform at the **FET's** source shows three operating modes over a cycle: conduction on a rising **wave**-front, saturation limiting at the positive peak, and FET cutoff and RC exponential decay on a falling wavefront. The circuit has a good short-term stability of  $\pm$  0.1 ppm.

When the frequency is changed, the time constant  $R_1C_1$  must be changed. In the FET version, it is convenient to leave  $R_1$  fixed (to hold. the drain current constant) and vary C,.

What happens when the resistor  $R_1$  is replaced with an inductor? Figure 10.3b shows the same circuit with the  $2.4K \Omega$  emitter resistor  $R_1$  re-

a state of the second



Figure 10.3(*a*). Colpitts-FET at 1 MHz.  $R_2$  must be  $\geq 1 \ M\Omega$  for no loading effects and  $\geq 22K \ \Omega$  for oscillation to occur.

placed with a 550- $\mu$ H inductor. The inductor's 3000- $\Omega$  reactance at 1 MHz is a little higher than the 2400  $\Omega$  of resistor  $R_1$ , but it is close enough. Note the much larger waveform amplitudes in Fig. 10.3b when the inductor is used, so much so that the FET's gate goes above +5 VDC and acts as a diode clamp through the FET's drain to the +5 V power supply,

The circuit in Fig. 10.3*b* is more important as a harmonic oscillator than as a fundamental one, but it is included here for waveform comparison with Fig. 10.3*a*. The larger voltage swing across the crystal shows that the in-circuit Q is much higher with the inductor  $L_1$  rather than the resistor  $R_1$  in the circuit.

A schematic for operation at 4 kHz is shown in Fig. 10.3c. Note the

٩

b



Figure 10.3(b). Colpitts-FET at 1 MHz, using an inductor  $L_1$  instead of resistor  $R_1$  in Fig. 10.3*a*.  $L_1C_1$  is not tuned to resonance.

very high shunt resistance required across the crystal to operate at 4 kHz. A FET is the obvious choice for the amplifier in this circuit because of its high input resistance.

A schematic for operation at 10 MHz is shown in Fig. 10.3*d*. At these higher frequencies, the J309 FET works better than the 2N4416, because it has twice the transconductance of the 2N4416 and half the output resistance. The output resistance must be low to drive the low impedance of  $C_1$  at high frequencies. The J309 requires twice the drain current, so  $R_1$  is cut in half to provide this.  $C_1$  is then doubled to keep the  $R_1C_1$  time constant the same.

10 MHz is about the upper limit for a FET-Colpitts circuit. Above 10 MHz, a bipolar transistor makes a better amplifier choice. The output resistance of a transistor emitter follower is 5 to 10 times lower than that of a FET source follower, which makes it much easier for the transistor to drive the lower circuit impedance of a high-frequency oscillator circuit.



Figure 10.3(c). Colpitts-FET at 4 kHz.  $R_2$  must be  $\geq 220 \text{ M}\Omega$  for no loading effects and  $\geq 5 \text{ M}\Omega$  for oscillation to occur.

And the low crystal impedance at these higher frequencies makes the medium input resistance of a transistor amplifier more acceptable as a load for the crystal.

#### 10.4. COLPITTS-TRANSISTOR

A schematic of this circuit at 1 MHz is shown in Fig. 10.4a. The voltage swing across the crystal is rather large, from +5 to -1 VDC. The waveform at the transistor's emitter shows three operating modes over a cycle: normal transistor operation over a short interval near the end of the rising crystal waveform, transistor saturation at the positive signal peak, and transistor shut-off and a long RC exponential decay with a falling crystal waveform. The circuit has a good short-term stability of  $\pm$  0.1 ppm.

To change frequency, the time constant  $R_1C_1$  must be changed. In the transistor version of the Colpitts, it is convenient to change  $R_1$  and leave  $C_1$  fixed. This increases the transistor's input resistance as the frequency goes lower, where the crystal's load resistance must be higher. It also



Figure 10.3(d). Colpitts-FET at 10 MHz..  $R_2$  must be  $\geq 100$ K  $\Omega$  for no loading effects and  $\geq 3.3$ K  $\Omega$  for oscillation to occur.



Figure 10.4(*a*). Colpitts-transistor at 1 MHz. Crystal shunt resistance must be  $\geq$  1 M $\Omega$  for no loading effects and  $\geq$  22K  $\Omega$  for oscillation to occur.

helps to use a high-gain transistor to get the highest possible input resistance at the transistor's base input terminal and minimize crystal loading by the transistor.

What happens when the resistor  $R_1$  is replaced with an inductor? Figure 10.4b shows the same circuit as Fig. 10.4a but with the 2.7K  $\Omega$  emitter resistor  $R_1$  replaced with a 550- $\mu$ H inductance  $L_1$ . Its reactive impedance is 3.1K  $\Omega$  at 1 MHz, roughly near the 2.4K  $\Omega$  of  $R_1$ . The bias resistor  $R_2$  is increased to 470K  $\Omega$  to compensate for removing the emitter resistor  $R_1$ . The waveforms show an increased Q, with signal voltages almost three times larger in amplitude and the peaks showing stronger clipping. This circuit is more important as a harmonic oscillator than as a fundamental one, but it is included here for waveform comparison with Fig. 10.4a.

A schematic for operation at 200 kHz is shown in Fig. 10.4c. 200 kHz



Figure 10.4(b). Colpitts-transistor at 1 MHz, using an inductor  $L_1$  for resistor  $R_1$  in Fig. 10.4*a*.  $L_1C_1$  is not tuned to resonance.



Figure **10.4**(*c*). Colpitts-transistor at 200 kHz. Crystal shunt resistance must be  $\geq$  470K  $\Omega$  for no loading effects and  $\geq$  220K  $\Omega$  for oscillation to occur.







is about the lowest frequency at which a transistor-Colpitts circuit will work because of crystal loading effects. Below 1 MHz, oscillation amplitude is quite low because of crystal loading by the transistor. At frequencies below 1 MHz, a FET is a better choice than a transistor for the Colpitts circuit. A transistor-Colpitts circuit for operation at 20 MHz is shown in Fig. 10.4*d*.

# 10.5. LOW CAPACITANCE LOAD

A schematic of this circuit is shown in Fig. 10.5*a*. The circuit shows good performance; its short-term stability is a good 0.1 ppm. One criticism is that the crystal driving waveform could be more symmetrical than it actually is. As can be seen from the waveforms, the FET input signal is so large that it effectively turns the FET on and off like a half-wave rectifier. Increasing  $C_2$  would help square up the crystal driving waveform. When the FET amplifier input saturates on the positive signal peaks, the only effect on the crystal is that capacitive divider impedance changes from 9.5 to 12 pF. Amplifier gain from point A to point C in Fig. 10.5*a* is only 0.8X, and additional gain is provided by partial resonance of  $C_1$  and  $C_2$  in series with the crystal's internal inductance.

Measuring the crystal current by means of the voltage drop across the series capacitor  $C_2$  introduces a 90" phase lag. The RC networks  $R_3C_3$  and  $R_4C_4$  each introduce an additional 45" phase lag, and the transistor inverts the signal, providing a total phase shift of 360" around the amplifier loop.

Due to the low capacitance load effectively in series with the crystal, the oscillation frequency is about 300 ppm higher than it would be with a low impedance load. This is as expected and what normally occurs in an



Figure **10.5**(*a*). Low-capacitance load circuit at 1 MHz.

oscillator circuit when a small frequency-trimming capacitance is put in series with the crystal.

Are the low capacitance divider and the high resistance of the FET amplifier input effective in reducing resistive load losses? The answer is yes. Figures 10.5b-d show the equivalent crystal load circuit. Converting the parallel RC network of  $C_2$  (47 pF) and  $R_1$  (22 M $\Omega$ ) to its series equivalent gives 47 pF and 0.6  $\Omega$ . The 0.6  $\Omega$  is negligible. The largest resistive loss comes from the driving source resistance  $R_4$ . Since  $R_4C_4$  is shorted to ground by the transistor every half cycle, the effective  $R_4C_4$  impedance values are halved, or 3000 pF and 100  $\Omega$  average over the complete waveform cycle, as shown in Fig. 10.5b. The final equivalent



Figure 10.5. Equivalent crystal load for low-capacitance load circuit: (h) crystal load circuit, (c) intermediate, and (d) equivalent load circuits.

load on the crystal is 9.7  $\Omega$  in series with 14 pF, as shown in Fig. 10.5*d*. The low 9.7- $\Omega$  series resistance is the major reason for the circuit's good short-term frequency stability of 0.1 ppm.

Converting the averaged parallel  $R_4C_4$  network in Fig. 10.5*b* to its series equivalent gives 3840 pF and 22  $\Omega$ , as shown in Fig. 10.5*c*. This series 22- $\Omega$  equivalent resistance is only 9% of the crystal's internal series resistance  $R_s$  of 240  $\Omega$ . Making the source resistance smaller would not improve the circuit Q very much. Note that in addition to providing a needed 45" phase lag,  $C_4$  is also effective in reducing the crystal's driving source resistance  $0.5R_4$  from 100 to 22  $\Omega$ .

## 10.6. HIGH RESISTANCE LOAD

The schematic of this circuit is illustrated in Fig. 10.6a. The circuit shows fair performance and has reasonably good short-term frequency stability of 0.2 ppm. One criticism is that the crystal's driving waveform could be more symmetrical than it actually is. As can be seen from the waveforms in Fig. 10.6a, the FET's input signal is so large that it effectively turns the FET on and off like a half-wave rectifier. Increasing the



Figure 10.6(a). High-resistance load circuit at 1 MHz.

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voltage divider ratio (i.e., reducing  $R_2$ ) at the FET input would help square up the waveform.

When the FET amplifier saturates on the positive signal peaks, the only effect on the crystal is that its capacitive load increases from 5.8 to 6.0 **pF**. Amplifier gain from point A to point C in Fig. 10.6*a* is only 0.8X, and additional gain for circuit oscillation is provided by partial resonance of part of the crystal's inductance with the series combination of  $C_1$  and the **FET's** input capacitance of 4 **pF**.

What sort of load does the crystal see in this circuit? It sees a capacitive load, consisting mostly of the crystal's own terminal capacitance  $C_0$ (about 5 pF). The FET has an input capacitance of 4 pF directly across  $R_2$ . To frequency compensate the voltage divider, about 1 pF is added across R. The impedance of these two capacitors at 1 MHz is much lower than the resistance values of  $R_1$  and  $R_2$ , which means that the voltage divider is effectively capacitive rather than resistive.

Due to the small **5-pF** capacitance of the load effectively in series with the crystal, the oscillation frequency is 670 ppm higher than it would be with a low impedance load; this is as expected. Figures 10.6b-d show



Figure 10.6. Equivalent crystal load for high-resistance load circuit: (b) crystal load circuit, (c) intermediate, and (d) equivalent load circuits.

the equivalent circuit. As can be seen from Fig. 10.6*d*, the equivalent series RC load on the crystal is 122  $\Omega$  and 5.8 pF. The crystal's internal series resistance  $R_s$  is 240  $\Omega$ , so that the external 122  $\Omega$  adds about 50% more, a reasonably small amount in practice. Figure 10.6*c* shows that most of the external 122-R load resistance comes from the high-resistance voltage divider, which means voltage-divider resistances could have been higher. Higher values of 10 and 2.4 M $\Omega$ , respectively, for  $R_1$  and  $R_2$  would have reduced equivalent series load resistance in half, to 61  $\Omega$ , a reasonable improvement in circuit Q.

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This circuit provides a good example of what happens when we put a high resistance load on the crystal. The resonant frequency rises significantly, and a 90" phase lag occurs that must be compensated for in the amplifier. The 90" phase lag is due to measuring the crystal current by means of the voltage across a capacitor (effectively) rather than across a resistor. Two RC networks  $R_3C_3$  and  $R_4C_4$  are added internally in the amplifier, with each providing 45" of phase lag. Transistor  $Q_2$  inverts the signal, giving a total of 360" phase shift around the loop.

## 10.7. COMMON BASE-TRANSISTOR

The schematic of this circuit at 1 MHz is shown in Fig. 10.7*a*. The circuit works very nicely. The crystal's internal series resistance  $R_s$  is 240  $\Omega$ , driving impedance is 10  $\Omega$ , and load impedance is 40  $\Omega$ . The in-circuit Q is degraded from the crystal's internal Q by (240 + 40 + 10)/(240) = 1.2, which is quite reasonable. Waveforms at points A and B in Fig. 10.7*a* show that both transistors stay on over the complete waveform cycle, maintaining their low source and load resistances. The diode amplitude clamp works very well in this circuit. This common base oscillator circuit can be used up to 20 MHz by decreasing the emitter input resistance of Q<sub>1</sub> at point A in order to provide the lower load resistance needed by the crystal at higher frequencies. Increasing the emitter current of Q<sub>1</sub> will decrease its emitter input resistance.

Figure 10.7*b* shows a low frequency variation of the common base amplifier circuit operating at 4 kHz. This circuit also works very well. Here, the crystal is moved to a higher impedance point between collector and base, and the two emitters are tied together. The 4-kHz crystal's internal series resistance is 45K  $\Omega$ , the source resistance is half of  $R_1$  or 5K  $\Omega$ , and the load resistance is 11K  $\Omega$ . This gives an in-circuit reduction of the crystal's internal Q of (45K + 5K + 11K)/ 45K = 1.4, a reasonable value. The capacitor C <sub>1</sub> is added to the circuit to reduce noise at the sine



Figure 10.7(a). Common base circuit at 1 MHz.



**Figure 10.7(b).** Common base circuit at 4 kHz ( $R_s = 45$ KR). For operation at 50 kHz ( $R_s = 20$ K  $\Omega$ ), use  $R_1 = R_3 = R_4 = 4.7$ K  $\Omega$  and  $C_1 = 220$  pF.

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#### PIERCE

wave cross-over switching points in order to avoid multiple on-off switchings of  $Q_2$  due to noise. This circuit also works well at 50 kHz by using circuit values given in the caption to Fig. 10.7b.

The emitter waveform at point *E* in Fig. 10.7*b* is rather interesting; it looks like the output of a half-wave rectifier. The half sine wave occurs when the base of  $Q_2$  goes positive, pulling up the emitter voltage at point *E*. The waveform goes flat when the base of  $Q_2$  goes negative and turns  $Q_2$  off, which pulls  $Q_1$  into a full-on state.

# 10.8. COMMON BASE-F'ET

The schematic of this circuit at 1 MHz is shown in Fig. 10.8; this circuit works very nicely. The l-MHz crystal's internal series resistance is 240  $\Omega$ , source resistance is 10  $\Omega$ , and load resistance is 200  $\Omega$ . This gives an in-circuit Q reduction of (240 + 200 + 10)/240 = 1.9. A high transconductance FET like the J309 or U309 is required to get the FET's source input resistance down to 200  $\Omega$ . At. lower frequencies, where a higher crystal load resistance is desired to avoid excessive gain loss, a FET of normal transconductance like the 2N4416 will provide a source input resistance of about 500  $\Omega$ . Waveform photographs show that both the FET and transistor stay in the linear region and maintain constant source and load resistances for the crystal over the complete waveform cycle. This is due to the use of the diode clamp for voltage limiting.

### 10.9. PIERCE

The schematic of this circuit for l-MHz operation is shown in Fig. 10.9a; the circuit works very well. One criticism is that the crystal's driving waveform could be more symmetrical than it actually is. The short-term stability measures a very good 0.1 ppm.

Figures 10.9b and c show the equivalent series RC load seen by the crystal in Fig. 10.9~. The output resistance of the transistor stage is averaged at 500  $\Omega$ , halfway between the on- and off-state values of 0 and 1000  $\Omega$ , respectively. Figure 10.9c shows that the crystal's equivalent series load resistance is a low 25  $\Omega$ . This is only 10% of the crystal's internal series resistance of 240  $\Omega$ , so that in-circuit Q is only 10% less than the crystal's internal series resistance with respect to the crystal's internal series resistance  $R_s$  is the primary reason for the Pierce circuit's very good short-term frequency stability.



Figure 10.8. Common gate circuit at 1 MHz. To get a higher crystal load resistance  $(R_{in})$  of 500  $\Omega$  at lower frequencies, substitute 2N4416 for U309, and use  $R_1 = 3.3 \text{K} \Omega$ ,  $R_2 = 1.5 \text{K} \Omega$ .



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Figure 10.9(u). Pierce at 1 MHz.

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**Figure 10.9.** Equivalent crystal load for the l-MHz Pierce circuit in Fig. 10.9*a*: (b) crystal load circuit and (c) equivalent circuit.

A schematic for a low frequency Pierce circuit at 4 kHz is shown in Fig. 10.9*d*. The main change here is the use of a FET source follower to avoid loading the crystal, which has a high internal resistance  $R_s$  of 45K  $\Omega$ . This circuit works very well.

Figures 10.9e and f show the equivalent series RC load seen by the crystal in Fig. 10.9d. The output resistance of the transistor stage is averaged at 1000  $\Omega$ , halfway between the on- and off-state values of 0 and 2000  $\Omega$ , respectively. Figure 10.9f shows that the crystal's equivalent series load resistance is only  $1040 \ \Omega$ , about 2% of the crystal's internal series resistance of 45K  $\Omega$ . This means that in-circuit Q is down only 2% from the crystal's inherent internal Q.

A schematic for a high-frequency Pierce circuit at 20 MHz is shown in Fig. 10.9g; this circuit works very well also. In this circuit, two emitter



Figure 10.9(d). Pierce at 4 kHz.

PIERCE



Figure 10.9. Equivalent crystal load for the 4-kHz Pierce circuit in Fig. 10.9*d*: (e) crystal load circuit and (f) equivalent load circuit.

followers have been added at the amplifier output to permit driving the low impedance crystal circuit. The 2N2369 requires a heat sink.  $R_1$  is selected on the basis that 30  $\Omega$  is the smallest resistance that the 2N2369 can drive without distortion. One change that might be made in this circuit would be to replace the 2N2369, which draws a lot of current, with a step-down transformer. This would raise the low impedance of the crystal circuit to something the 2N5179 emitter follower could drive directly.

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Figures 10.9*h* and *i* show the equivalent series RC load seen by the crystal at 20 MHz in Fig. 10.9*g*. The equivalent series load resistance is 1.8  $\Omega$ , which is only 12% of the crystal's internal series resistance of 15  $\Omega$ .



Figure 10.9(g). Pierce at 20 MHz.

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Figure 10.9. Equivalent crystal load for the 20-MHz Pierce circuit in Fig. 10.9g: (h) crystal load circuit and (i) equivalent load circuit.

The in-circuit Q of this 20-MHz Pierce circuit is down only 12% from the crystal's inherent internal Q.

# 10.10. PIERCE AT EXACT SERIES RESONANCE

The schematic of this circuit at 1 MHz is shown in Fig. 10.10*a*. Three 60" RC lag networks are used to generate the 180" phase shift needed to operate the crystal at exact series resonance. It is convenient to increase  $R_1$  to 100  $\Omega$  to give the emitter follower  $Q_2$  an easier load to drive. This raises the  $R_1C_1$  phase shift from 60 to 70". To compensate for this, the  $R_2C_3$  phase shift is decreased from 60 to 50". A heat sink is required for the emitter follower  $Q_2$ .  $C_2$  is selected so that its phase shift with the crystal's internal series resistance  $R_s$  is 60". This circuit works very well and shows a O.1-ppm frequency stability.

Figure 10.10*b* and c show the equivalent series RC load seen by the crystal in Fig. 10.10*a*. The equivalent series load resistance is only 18  $\Omega$  or 8% of the crystal's internal series resistance of 240  $\Omega$ . This means that in-circuit Q is only 8% lower than the crystal's inherent internal Q.

Do we gain anything by operating the crystal at exact series resonance instead of just near it? Yes and no. One advantage of the exact seriesresonant circuit is its lower loop gain losses, which permit using a lower-gain transistor. There may or may not be a difference in the crystal's long-term drift stability by operating it at exact series resonance; short-term stability measures about the same. The exact resonance circuit is more complex, however, since it uses two transistors instead of one and three RC networks instead of two. With a little more design work, it might be possible to eliminate the second transistor.



Fig. 10.10(a). Pierce at exact series resonance, at 1 MHz.

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Figure 10.10. Equivalent crystal load for the l-MHz Pierce circuit in Fig. 10.10*a*: (b) crystal load circuit and (c) equivalent load circuit.

# 10.11. PIERCE WITHOUT SERIES RESISTOR

The standard Pierce circuit in Fig. 10.9*a* is occasionally seen without the series resistor R<sub>i</sub>. This reduces gain losses in the circuit and allows operation with a medium gain transistor instead of the high-gain transistor required by the standard Pierce circuit. The main drawback is that the crystal operates at a higher voltage level. If the circuit is used above 4 MHz, the crystal's power dissipation should be checked in order to be sure it is within the dissipation limit.

Figure 10.11*a* shows a Pierce oscillator circuit without the series resistor  $R_1$ . This circuit is identical to the one in Fig. 10.9*a* except that  $R_1$  is eliminated. Waveform photographs in each figure allow a direct comparison of the difference. When  $R_1$  is eliminated, its function in the  $R_1C_1$  phase-shift network in Fig. 10.11*a* is replaced by the parallel resistance of  $R_2$  and the output resistance of  $Q_1$ 's collector.

Figures 10.11b and c show the equivalent series RC load seen by the crystal. The equivalent series load resistance is 54  $\Omega$  or 23% of the crystal's internal series resistance of 240  $\Omega$ . This gives an in-circuit Q only 23% lower than the crystal's inherent internal Q.

## 10.12. EMITTER COUPLED

The schematic of this circuit at 1 MHz is shown in Fig. 10.12. This circuit works fairly well and has a very good short-term frequency stability of 0.1 ppm. The crystal also has a good waveform across it.

The loop gain with the crystal removed from the circuit is set at slightly less than 1X (about 0.8X). The ratio of collector to emitter resis-



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Figure 10.11. Pierce without a series resistor, at 1 MHz: (a) schematic, (b) crystal load circuit, and (c) equivalent crystal load circuit.

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Figure 10.12. Emitter coupled circuit at 1 MHz.

tances in the first stage is 0.9, and loading effects from the second stage cut the actual first stage gain another 10% to 0.8X. The second stage has a gain of 1X and inverts the signal to provide positive feedback. The I-MHz crystal has an internal series resistance  $R_s$  of 240  $\Omega$ . The emitter resistor shunting the crystal is set at about twice the crystal's internal resistance or 470  $\Omega$ . Because the loop gain is just short of 1X over a wide frequency range, circuit waveforms are sensitive to stray capacitance effects.

To obtain a good waveform across the crystal, a diode amplitude clamp must be used across the collector resistor  $R_2$  in the first stage. The resulting low signal amplitude prevents the emitter current from going to zero and keeps the crystal's load resistance at a desirably low value. The crystal's low load resistance is the transistor emitter's input resistance  $R_{in}$ , which is 18  $\Omega$  in Fig. 10.12. This low load resistance on the crystal is the primary reason for the circuit's very good short-term stability. If the emitter current were to go to zero, the load on the crystal would increase from the 18-R input resistance of the emitter to the 470  $\Omega$  of the emitter resistor R. The diode clamp also keeps the first stage transistor from saturating, which would increase the crystal's load resistance if it occurred.

# 10.13. MODIFIED MEACHAM

A schematic of the modified Meacham half-bridge circuit at 1 MHz is shown in Fig. 10.13 a. It is a complex circuit with good performance and operates at series resonance. Its short-term frequency stability is particularly good, being as good as or better than 0.1 ppm, the limit of available measuring equipment. It was not possible to tell whether the O.I-ppm frequency variation observed was in the circuit or the frequency-measuring equipment. Figure 10.13*b* shows voltage waveforms at various points in the circuit. The somewhat peculiar waveform shown at the bridge output ( $E_A$  in Fig. 10.13*b*) is normal and results from the bridge subtracting a square wave with sloping sides (through bridge arm  $R_2$ ) from a sine wave (through the crystal arm).

The circuit uses a two-stage amplifier, with a gain of 28X from point A to point B in Fig. 10.13a. The split-load phase inverter  $Q_1$  provides a 2 to 1 half-bridge, with the emitter resistor twice as large as the collector resistor.  $C_2$  is twice as large as the crystal's shunt terminal capacitance  $C_0$  of 3.5 pF in order to balance the half-bridge capacitively.  $C_2$  is more important than it looks, since the signal path through  $C_0$  provides positive feedback, which tends to make the amplifier oscillate, while the signal path through  $C_2$  provides negative feedback and stabilizes the amplifier.  $C_3$  improves the high-frequency phase response of  $Q_1$ 's collector, so that its high-frequency response is flat out to 80 MHz. The value of  $C_3$  is determined experimentally, and its use helps considerably in preventing high-frequency parasitic oscillation.

For maximum frequency stability and maximum in-circuit Q, it is desirable to use the smallest possible value of  $R_2$ . With a 2 to 1 half-bridge,





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Figure 10.13(b). Waveforms for modified Meacham circuit in Fig. 10.13a.

the minimum theoretical value of  $R_2$  for the circuit to oscillate is equal to one-half the crystal's internal series resistance  $R_s$ . The l-MHz crystal used has an internal resistance of 240  $\Omega$ , so the minimum value for  $R_2$  is 120  $\Omega$ . The circuit will not oscillate except parasitically when  $R_2$  is less than its theoretical minimum value of 120  $\Omega$ , so this condition makes a good test for parasitics. The circuit in Fig. 10.13*a* does not oscillate when  $R_2$  is less than 120  $\Omega$ , indicating a stable amplifier design. In practice,  $R_2$ has to be slightly larger than 0.5  $R_s$  for the circuit to oscillate, the exact amount depending on amplifier gain. In Fig. 10.13*a*, a practical value for  $R_2$  is 290  $\Omega$ , a small amount more than the bare minimum needed for oscillation, to ensure that the circuit will oscillate under all conditions. This gives a ratio of practical to theoretical minimum values of 290/120 or 2.4. This ratio of 2.4 for  $2R_2/R_s$  provides a measure of the crystal's incircuit Q, with the unattainable ratio of one corresponding to infinite Q.

The amplifier stage  $Q_2$  is designed to present a reasonably high load resistance to the half-bridge and drive the relatively low input resistance of  $Q_3$ 's base-emitter junction. The second amplifier stage drives the diode clamp,  $D_1$ - $D_2$ . Resistor  $R_5$  provides a source resistance for the diode clamp to work against. The feedback resistor  $R_3$  adjusts the on/off ratio of the clamped square wave to 1.0.

The circuit uses one resonant LC circuit, tuned to the frequency of oscillation, to reduce the circuit's frequency response away from resonance. Tuning the LC circuit has a considerable effect on the circuit's oscillation frequency, so both  $L_1$  and  $C_1$  must be stable components.  $L_1$  must be an air core inductor, and  $C_1$  must be adjustable to 1% for close tuning. Note that  $L_1C_1$  is shunted by a resistance  $R_1$ , which corrects the 90" phase shift of  $L_1C_1$  back to 0" at frequencies far away from resonance. This helps stabilize the circuit and prevent parasitic oscillation.

Figure 10.13*c* shows a modified Meacham circuit for 10-MHz operation. This circuit performs well; its short-term stability is 0.1 ppm, at the limit of available measuring equipment. The circuit uses a three-stage amplifier that is different in several respects from the one used at 1 MHz. The differences are primarily due to the crystal's much lower internal series resistance  $R_s$  at 10 MHz. First, the split-load phase inverter  $Q_1$  has much lower emitter and collector resistors, so that  $Q_1$  can drive the low 5-R resistance of the 10-MHz crystal. Second, an emitter follower  $Q_4$  has been added to drive the low input resistance of the phase inverter  $Q_1$ . And third, the  $L_1C_1$  tank circuit for rolling off frequencies away from resonance has been moved to the emitter of  $Q_2$ , where it increases the gain of  $Q_2$  at frequencies near resonance. The base input resistance of  $Q_2$ is low with this arrangement, but it is still relatively high with respect


Figure 10.13(c). Modified Meacham at 10 MHz.

to the very low resistance of  $R_2$  and the crystal's internal resistance  $R_s$ , so it does not load the half-bridge significantly.  $L_1C_1$  is deliberately shunted with  $R_1$  in order to reduce the 90" phase shift of  $L_1C_1$  at frequencies far away from resonance back to 0".

The circuit uses a 2 to 1 half-bridge, so  $C_2$  in Fig. 10.13*b* is set equal to twice the crystal's shunt terminal capacitance  $C_0$  of 8.5 pF. The theoretical minimum value of  $R_2$  in this circuit is 0.5  $R_s$  or 2.5  $\Omega$ . The practical value of  $R_2$ , set at just slightly more than the minimum value for oscillation, is 3.5  $\Omega$ . This gives a practical to theoretical minimum ratio of 3.5/2.5 or 1.4 for  $R_2$ .

The voltage gain of the amplifier from point A to point *B* in Fig. 10.13*c* is 50X. The amplifier is stable and does not oscillate when  $R_2$  is set below its minimum theoretical value for oscillation of 2.5  $\Omega$ . A heat sink is required on transistor  $Q_1$ .

Figure 10.13*d* shows a modified Meacham circuit for 100-kHz operation. This circuit works well and has a short-term frequency stability of 0.1 ppm, at the limit of available measuring equipment. The circuit uses a three-stage amplifier and differs in several respects from the one used at 1 MHz, primarily because of the crystal's higher internal resistance at 100 kHz. An emitter follower  $Q_4$  is used at the bridge output to prevent the amplifier from loading the bridge. The tuned circuit  $L_1C_1$  is moved to the emitter of  $Q_2$  and increases the gain of  $Q_2$  at resonance. The low input resistance of  $Q_2$  at resonance is easily driven by the emitter follower  $Q_4$ .  $L_1C_1$  is shunted with a resistor  $R_1$  to reduce the 90° phase shift of  $L_1C_1$  at frequencies far away from resonance back to 0".

 $Q_3$  is a combination amplifier and diode amplitude clamp and gives a fixed on/off ratio to its square wave output that is very close to 1.0. The on/off ratio is independent of power supply or bias changes.  $R_3$  trims the waveform flatness at the top and bottom of the square wave out of  $Q_3$ .

Because of the 2 to 1 bridge ratio set by  $Q_1$ 's emitter-to-collectorresistance ratio,  $C_2$  is set equal to twice the crystal's terminal shunt capacitance  $C_0$  of 8 pF. The theoretical minimum value of  $R_2$  is one-half of the crystal's internal series resistance  $R_s$  or 200  $\Omega$ , again because of the bridge's 2 to 1 ratio. The practical minimum value of  $R_2$ , set at slightly more than the minimum required for oscillation, is 420  $\Omega$ . This gives a practical-to-theoretical minimum ratio of 420/200 or 2.1 for  $R_2$  in Fig. 10.13*d*. The amplifier is stable and does not oscillate when  $R_2$  is set below the minimum theoretical value for oscillation. The amplifier has a gain of 100X from point A to point B in Fig. 10.13*d*.

Although the modified Meacham circuits described here work well, the amplifiers used in them can probably be simplified and improved.



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Figure 10.13(d). Modified Meacham at 100 kHz.

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One approach would be to combine the best parts of the three amplifiers into one. Such an amplifier would include: (1) a shunt capacitor  $C_3$  across the  $Q_1$  phase splitter's emitter resistor to correct the high-frequency phase response at the phase splitter's collector, as in Fig. 10.13*a*; (2) a series  $L_1C_1$  network across  $Q_2$ 's emitter resistor  $R_1$  in order to amplify only the desired oscillation frequency, as in Figs. 10.13*c* and *d*; and (3) putting the diode amplitude clamp between  $Q_3$ 's base and collector, as in Fig. 10.13*d*. Another approach would be to put the  $L_1C_1$  filter after the diode amplitude clamp in the amplifier, so that the crystal is driven with a sine wave instead of a square wave.

## C. HARMONIC CIRCUITS

#### 10.14. COLPITTS (20 MHz)

The schematic of this harmonic oscillator is shown in Fig. 10.14. This 20-MHz harmonic circuit is the same as the 20-MHz fundamental circuit shown in Fig. 10.4*d* except that the 390-n emitter resistor  $R_1$  is replaced with a 3.2- $\mu$ H inductor whose impedance (410  $\Omega$  at 20 MHz) is approximately equal to the resistance of  $R_1$ . The bias resistor  $R_2$  is also increased to 470K  $\Omega$ , to accommodate the DC voltage shift when  $R_1$  is removed. The voltage swing at both the base and emitter terminals is a large 10 Vp-p (+5 to -5 VDC).

Circuit performance is rated fair. The strong point of this circuit is its low parts count. Its frequency is somewhat sensitive to power supply changes, however. In an effort to reduce this sensitivity, the base biasing



Figure 10.14. Colpitts harmonic circuit at 20 MHz. Crystal shunt resistance must be  $\geq 22K \Omega$  for no loading effects and  $\geq 2.2K \Omega$  for oscillation to occur.

resistor  $R_2$  was replaced with a FET constant current source, but this did not help.

#### 10.15. BUTLER COMMON BASE (20 MHz. C-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.15. The crystal operates at its third harmonic. Bad parasitics seem to be inherent in the Butler common base circuit, and it requires considerable experimental effort to come up with a satisfactory parts layout. Even then, several parasitics usually remain. We end up satisfied if the tank circuit will tune properly without spurious oscillations just at the frequency desired.  $R_2$  and  $R_3$  help damp down parasitic effects considerably and also help isolate external load-capacitance effects from the tuned circuit.

Diode  $D_1$  helps stabilize the collector current against a varying power supply voltage, but it does not help enough. The collector current still varies too much. The circuit works better (less lead inductance?) if  $C_2$  is tied directly to the grounded end of the emitter resistor  $R_1$ , as shown in Fig. 10.15, rather than to +5 VDC, as shown in Fig. 5.28. The emitter waveform shows that the transistor does not cut off and, thus, provides a reasonably constant low resistance load to the crystal over the complete waveform. The diode clamp ensures that the transistor does not saturate and keeps the oscillation amplitude within the transistor's linear region. The crystal's load resistance is about 10  $\Omega$ , and its internal series resistance is about 40  $\Omega$ . This gives a voltage-divider gain loss of  $10/\langle 10 + 40 \rangle$ or 0.20. The crystal's capacitive source impedance is between one and two times the impedance of  $C_2$  (35  $\Omega$ ), depending on the value of C,. The circuit's frequency sensitivity to temperature depends on the collector current and varies two to one over the operating range of collector current.

To oscillate properly, the collector current must be set at a specific value. Below this value, the circuit will not oscillate; above this value, oscillation ceases. If the emitter current is increased even further, the circuit will start oscillating again at some other frequency, either at a harmonic or at some other spurious frequency.

Waveforms in Fig. 10.15 show a 40" phase lag from point E to point C and a 60° phase lead from point C to point A, with the crystal and its resistive load providing a 20° phase lag from point A to point E. Tuning C, will change the crystal's phase shift from lag to zero (series resonance) to lead, with the other two phase angles changing accordingly, so that they always add up to zero.



Figure 10.15. Butler common base at 20 MHz, capacitive tap.

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This circuit works satisfactorily once we get past the parasitics. But its basic design defect of oscillating only over a narrow range of collector current, and its bad parasitics, make it only a poor to fair circuit.

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#### 10.16. BUTLER COMMON BASE (20 MHz. L-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.16. The purpose of this circuit is to find out if an inductive tap offers anything useful over a capacitive tap. The circuit is the same as the one in Fig. 10.15 except that the crystal is tapped down on the inductor in the LC tank instead of on the capacitor. The biggest advantage of the Ltapped circuit is that it has no parasitics (assuming a reasonable parts layout), which makes it much easier to debug and tune. The biggest disadvantage is a lower oscillation frequency. The inductive tap introduces a phase lag in the circuit in comparison with a capacitive tap, which introduces a phase lead. The crystal must provide a large phase lead to compensate for the two phase lags of the LC tank circuit and the inductive tap (see Chapter 7). To provide the phase lead, the crystal must operate below series resonance, which is what gives the circuit its lower oscillation frequency. The phase lag from E to C in Fig. 10.16 is 50" From C to A, the phase lag is 22°, and the crystal and its emitter load provide a 72" phase lead from A to *E*.

The frequency-temperature sensitivity varies 2 to 1 with the emitter current in both the L-tap and C-tap circuits. A minor disadvantage of the L-tap circuit is that it is harder to check. Putting the capacitive load of a scope probe (about 7 pF) at the inductive tap point A in Fig. 10.16 disturbs the circuit and adds unwanted oscillatory ripples to the waveform.

The circuit's overall performance is about the same with an inductive tap as with a capacitive tap. Either way, the circuit is rated only as a poor to fair VHF harmonic oscillator.

## 10.17. BUTLER COMMON BASE (50 MHz)

The schematic of this VHF harmonic oscillator, shown in Fig. 10.17, exhibits parasitic effects typical of this circuit. The 50-MHz third-harmonic crystal used had a relatively low series resistance of 25  $\Omega$ . The crystal's load impedance is 8  $\Omega$ . The crystal's capacitive source impedance is one to two times the impedance of  $C_2$  (70  $\Omega$ ), depending on the setting of C,. The diode amplitude clamp across  $L_1$  is very effective in keeping the

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Figure 10.16. Butler common base at 20 MHz, inductive tap.  $T_1 = 7$  turns,  $T_2 = 19$  turns.



Figure 10.17. Butler common base at 50 MHz.

emitter drive voltage low, so that the transistor will stay in its linear region. The emitter then provides a low and constant load resistance to the crystal over the complete waveform cycle.

Circuit performance is only fair to poor due to its design defect of oscillating over only a narrow range of collector current and its bad parasitic effects.

#### 10.18. BUTLER COMMON BASE (100 MHz. C-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.18. The crystal operates at the fifth harmonic. Diodes  $D_1-D_3$  provide a stabilized bias voltage source for the transistor. Diodes  $D_4$  and  $D_5$  limit oscillation amplitude and keep the transistor from saturating or shutting off at any part of the waveform cycle. The crystal's internal series resistance  $R_s$  is 70  $\Omega$ , and its load impedance is 8  $\Omega$ . The crystal's capacitive source impedance is one to two times the impedance of  $C_2$  (100  $\Omega$ ), depending on the value of  $C_1$ . The circuit can be set to exact series resonance by tuning  $C_1$  so that the voltages at points A and E in Fig. 10.18 are in phase with each other. This assumes that the emitter's input impedance at E is a pure resistance and not reactive.

An adjustable inductor  $L_2$  is placed across the crystal to tune out the crystal's terminal capacitance  $C_0$  of 5.7 pF.  $L_2$  can be an iron-core inductor, but  $L_1$  must be an air-core unit. The circuit will still oscillate if  $L_2$  is

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Figure 10.18. Butler common base at 100 MHz, capacitive tap.

not used, but frequency sensitivity to power supply variations is four times worse, and short-term frequency stability also degrades somewhat.

The performance of this circuit is only fair to poor due to the usual parasitics with this circuit and the circuit's design defect of oscillating over only a narrow range of collector current.

### 10.19. BUTLER COMMON BASE (100 MHz. L-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.19. The purpose of this circuit is to try out Butler's idea [6] of canceling the crystal's terminal capacitance  $C_0$  by adding an equal voltage of opposite phase through an equivalent capacitance  $C_2$  to the crystal's output at the emitter. The opposite phase is obtained by extending  $L_1$  a few turns beyond the normal +5 V power supply end of the coil.

The terminal-capacitance cancellation idea works poorly. The  $L_1$  taps at  $T_1$  and  $T_3$  are low impedance. Circuit operation is quite sensitive to the length of the common lead wire from A and B in Fig. 11.19, which was about a half-inch long in the test circuit. Some sort of common mode effect in the common lead wire from A to B (probably lead inductance) seems to be present and requires an excessively large reverse-phase voltage ( $T_3 > T$ , ) and a compensation capacitance  $C_2$  that is 25% larger than the crystal's terminal capacitance  $C_0$  to cancel out  $C_0$ . In addition, the oscillation frequency is unnecessarily sensitive to small changes in  $C_2$  or C,.

This circuit performs poorly. The idea of canceling out the crystal's

BUTLER EMITTER FOLLOWER (20 MHz, L-TAP)



Figure 10.19. Butler common base at **100** MHz, inductive tap.  $T_1 = 1.2$  turns,  $T_2 = 2.6$  turns,  $T_3 = 2.2$  turns.

terminal capacitance with a capacitance bridge circuit does not work well in practice.

## 10.20. BUTLER EMITTER FOLLOWER (20 MHz, C-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.20. The crystal operates at the third harmonic and is tapped into the capacitive side of the LC tank. The circuit has no parasitic effects of any kind.

There are no 2.6 V Zener diodes available, so four signal diodes are cascaded in series for base biasing. The emitter's output resistance that drives the crystal is 25  $\Omega$ . The crystal's load impedance is mostly capacitive and is one to two times the impedance of  $C_2$  (35  $\Omega$ ), depending on the value of C<sub>1</sub>. The crystal's internal series resistance  $R_s$  is 40  $\Omega$ .

This circuit works very well, and the absence of parasitics is a big help. By tuning  $C_i$ , the oscillation frequency can be set either at or slightly above (2 ppm) series resonance.

## 10.21. BUTLER EMITTER FOLLOWER (20 MHz. L-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.21. The purpose of this circuit is to find out if an inductive tap offers anything more than a capacitive tap does. The crystal operates at the third



Figure 10.20. Butler emitter follower at 20 MHz, capacitive tap.

harmonic. The circuit is essentially the same as the one in Fig. 10.20 except that the crystal is tapped down on the inductor in the LC tank instead of on the capacitor. The inductive tap introduces a phase lag in the circuit, as compared with a capacitive tap, which introduces a phase lead. The crystal must provide a phase lead to compensate for the phase lag of the inductive tap, which means that the crystal must operate below resonance. This gives the circuit a lower oscillation frequency compared with the capacitive tap circuit.





There are no 2.6 V Zener diodes available, so four signal diodes are cascaded in series for base biasing. The emitter's output resistance driving the crystal is 25  $\Omega$ . The crystal's load impedance is mostly inductive and one to two times the 30- $\Omega$  inductive reactance of the tapped portion  $T_1$  of the 1- $\mu$ H inductor. The crystal's internal series resistance  $R_s$  is about 40  $\Omega$ . For good operation, the circuit requires a short coupled

bypass capacitor  $C_2$  from the "grounded" end of the inductor to the grounded end of the emitter resistor  $R_3$ , as shown in Fig. 10.21.

This circuit works very well, but it does not offer any advantages over the C-tap circuit. Neither the L-tap or C-tap circuits show any parasitic oscillation effects. However, the oscillation frequency with the L-tap is always slightly below series resonance (about 2 ppm). Tuning  $C_1$  will vary the oscillation frequency from 3 to 1 ppm below series resonance.

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Why this circuit will not oscillate at series resonance is not known. The analysis in Chapter 7 indicates that it should be possible. Removing the diode amplitude clamp  $D_5$ - $D_6$  will allow the circuit to oscillate at series resonance or even up to 2 ppm above it. But the emitter follower's source resistance that drives the crystal goes too high (the transistor shuts off over part of the oscillation cycle) for this to be a viable alternative.

## 10.22. BUTLER EMITTER FOLLOWER (50 MHz)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.22. The crystal operates at the **third** harmonic and is tapped into the capacitive side of the LC tank. As is typical of this circuit, it has no parasitic oscillation effects. Since there are no 2.6 V Zeners available, four signal diodes in series are used for base biasing. The emitter's output impedance that drives the crystal is 29  $\Omega$ . The crystal's load impedance is



Figure 10.22. Butler emitter follower at 50 MHz.

#### BUTLER EMITTER FOLLOWER (100 MHz, C-TAP)

mostly capacitive and one to two times the 40- $\Omega$  capacitive reactance of  $C_2$ , depending on the value of  $C_1$ . The crystal's internal series resistance  $R_s$  is 30  $\Omega$ . This is a good circuit and works very well without any problems.

## 10.23. BUTLER EMITTER FOLLOWER (100 MHz. C-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.23. The crystal operates at the fifth harmonic and is tapped into the capacitive side of the LC tank. As is typical of this circuit, it has no parasitics. Since 2.6 V Zeners are not available, four signal diodes are cascaded in series for base biasing. The emitter's output impedance driving the crystal is 25  $\Omega$ . The crystal's load impedance is mostly capacitive and, depending on the value of  $C_1$ , is one to two times the 50  $\Omega$  impedance of  $C_2$ .

The crystal has a terminal capacitance  $C_0$  of 4.2 pF and a capacitive reactance of 360  $\Omega$  at 100 MHz. This is tuned out of the circuit by a 0.41  $\mu$ henry inductor  $L_0$  in parallel resonance across the crystal. The circuit will operate without the shunt inductor  $L_0$ , but the inductor provides a 4 to 10 times reduction in frequency sensitivity to power supply changes, which makes its use worthwhile. The oscillation amplitude at 100 MHz is low, so to give a larger oscillation amplitude fast-recovery signal di-



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odes rather than Schottky diodes are used for the amplitude clamp  $D_5$ - $D_6$ . This is a good circuit and works very well.

## 10.24. BUTLER EMITTER FOLLOWER (100 Mhz, L-TAP)

The schematic of this VHF harmonic oscillator is shown in Fig. 10.24. The purpose of this circuit is to find out if Butler's out-of-phase subtraction scheme [6] for eliminating the crystal's terminal capacitance  $C_0$  will work in the emitter follower circuit. The crystal operates at the fifth harmonic and is tapped into the inductive side of the LC tank. The crystal drive signal is fed through a capacitor  $C_2$  to a reversed-phase tap on the inductor. If  $T_1$  equals  $T_3$  and  $C_2$  equals the crystal's terminal capacitance  $C_0$ , then the two capacitances will cancel out one another.

To set up the bridge balance, the crystal and  $C_2$  are disconnected from the emitter and driven in parallel by an external signal generator at a frequency somewhere near (but not at) the oscillation frequency.  $C_2$  is then adjusted for minimum signal at the emitter. The external signal generator is disconnected, and the crystal and  $C_2$  are reconnected to the emitter. The circuit then oscillates at or near the crystal's series-resonant frequency.



Figure 10.24. Butler emitter follower at 100 MHz, showing out-of-phase cancellation of the crystal's terminal capacitance C,.  $L_{AD} = 0.24 \ \mu$  H, 6 turns closewound on 0.28-in. diameter form.  $T_1 = 1.2$  turns,  $T_2 = 2.6$  turns,  $T_3 = 2.2$  turns.



Figure 10.25. Pierce at 100 MHz.

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#### DISCRETE TRANSISTOR OSCILLATORS

This circuit does not work well at all; it performs poorly and tunes poorly. The out-of-phase cancellation idea works, but lopsidedly. At null balance, the capacitance  $C_2$  is twice the crystal's terminal capacitance  $C_0$ , and  $T_3$  has twice the turns of  $T_2$ . The circuit is very sensitive to the length (inductance?) of the ground lead in Fig. 10.24 from point B through the bypass capacitor  $C_3$  to the grounded end of the emitter resistor R, as if there were a common mode effect present. Changing  $C_2$  by 4 pF changes the oscillation frequency by 600 Hz, which is much too sensitive. And finally, the oscillation frequency of 99.996603 MHz is very low for a 100-MHz crystal.

## 10.25. PIERCE (100 MHz)

The schematic of this circuit is shown in Fig. 10.25. The crystal operates on the fifth harmonic. The first stage amplifier uses a tuned  $L_1C_3$  tank as the collector load, with a diode amplitude limiter. The second and third stages are emitter followers to drop the high  $L_1C_3$  tank impedance to about 5  $\Omega$  in order to drive the low impedance crystal circuit.  $L_1$  has to have an air core in order to avoid the detuning effects of core saturation and its associated nonlinearities, but  $L_0$  is less sensitive and can use an iron core. A heat sink is required on the MRF517.

The circuit works well and has relatively low sensitivity to power supply changes. The second emitter follower draws a large power supply current and is an obvious candidate for replacement by a step-down transformer in low power applications. The  $L_1C_3$  tank tunes satisfactorily, but **parasitics** show up quickly when detuned. The circuit has a relatively high parts count.

## CHAPTERELEVEN

# INTEGRATED CIRCUIT OSCILLATORS

This chapter contains performance test data on individual IC oscillator circuits. It is divided into five parts, the first of which describes oscillator characteristics of various IC technologies and gives some general characteristics of various IC oscillator types. The second part covers **series**-resonant circuits, and the third covers Pierce circuits. Special oscillator **ICs** are discussed in the fourth part, and a VHF harmonic oscillator in **the** fifth.

## A. CIRCUIT SELECTION

The basic principle in selecting IC oscillator circuits was to try as many types and kinds of ICs as possible, testing each one to find its strong and weak points. A total of 24 different IC oscillator circuits were built and tested, using ECL, TTL, CMOS, and LINEAR technologies. Eight were series-resonant circuits, six were Pierce circuits, and one was a VHF harmonic circuit. Nine more were special ICs, specifically designed to be used as crystal oscillators.

The search for a good IC that a quartz crystal would like was mainly for a circuit with linear input and binary (square wave) output. A gain of **2–60X** was needed, the exact amount depending on the circuit used. Line receivers and voltage comparators have linear-input resistances and binary outputs, making them potentially good choices.

In general, TTL does not work too well in an oscillator circuit, because its input resistance is highly nonlinear at the switching point, and it exhibits bad parasitic oscillations if it does not switch rapidly between its two binary output states. CMOS has good input characteristics, but it is pretty limited in its output-drive capability. In contrast, ECL is almost ideal for an oscillator circuit, with its high linear input resistance and low output resistance, combined with a good output-drive capability. ١

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Some of the IC oscillator circuits tested were not TTL or CMOS compatible. Level shifters or buffers were added to these circuits to make them **TTL** compatible. After selection, each circuit was individually optimized by test for the best component values, bias, waveforms, and so forth. The **ICs** used have a strong effect on circuit performance, so considerable time was spent selecting the right one for each circuit. Most of the optimizing of the fundamental circuits was done at 1 MHz, and photographs were taken of waveforms at various points in the circuits. Just as with the discrete transistor circuits, waveform photographs were synchronized to a common point in time and vertically aligned together on the printed page. This permits vertical waveform comparisons at the same point in time between various parts of a circuit.

The same test philosophy was used in testing integrated circuits that was used in testing discrete transistor circuits. That test philosophy is described in Section 10A and will not be repeated here.

## **B. SERIES RESONANCE**

#### 11.1. CMOS TWO-INVERTERS-4009

The schematic of this series-resonant oscillator at 200 kHz is shown in Fig. 11.1. This circuit is a variation of the TTL inverter oscillator shown in Fig. 11.3*a*. Because of the longer time delay in a CMOS inverter, this CMOS version is restricted to frequencies below 300 kHz. The CMOS inverter used is the 4009, a high-current driver with a short internal time delay. There is a large variation in this inverter's time delay among different manufacturers. The RCA 4009 had the shortest time delay of any of the brands tested and is recommended.

Each inverter in Fig. 11.1 has negative feedback around it to ensure that it is biased in the middle of its linear region, so that oscillation will always start when power is applied. The feedback resistor around the first inverter is divided into two series resistors, and the center point is bypassed to ground.  $R_L$  is used as the crystal's load resistor and set equal to or somewhat less than the crystal's internal series resistance  $R_s$ .

Figure 11.1 shows good waveforms at the crystal. The small spikes on

CMOS TWO-INVERTERS-4009



Figure 11.1. CMOS Two-Inverters (4009) circuit at 200 kHz.

the crystal's sine wave output appear to be due to the sharp edges of the crystal's square wave drive feeding through on the crystal's shunt terminal capacitance  $C_0$ .

The overall performance of the 4009 inverter circuit is poor, because its frequency is much too sensitive to changes in power supply voltage and ambient temperature.

## INTEGRATED CIRCUIT OSCILLATORS 11.2. CMOS TWO-INVERTERS-74C04

The schematic of this series-resonant circuit at 200 kHz is shown in Fig. 11.2. The purpose of this circuit is to see if the 74C series works any better than the 4000 series, and the answer is yes, it does. The circuit in Fig. 11.2 is the same as the 4009 circuit in Fig. 11.1 except for the substitution of the 74C04 for the 4009. The 74604 will oscillate at a higher frequency (up to 500 kHz, as compared with 300 kHz for the 4009), and it is less sensitive to temperature changes.

As in the 4009 circuit, the crystal's load resistance  $R_L$  is set equal to or somewhat less than the crystal's internal series resistance  $R_s$ . Figure 11.2 shows good waveforms at the crystal. The spikes on the crystal's sine wave output appear to be due to sharp edges of the crystal's square wave drive feeding through on the crystal's shunt terminal capacitance  $C_0$ .

The overall performance of the 74604 inverter circuit is below average, because its frequency sensitivity to power supply voltage changes is higher than it should be. This high sensitivity to power supply voltage changes seems to be characteristic of most CMOS ICs.

## 11.3. TTL TWO-INVERTERS-7404

The schematic of this series-resonant oscillator is shown in Fig. 11.3*a*. Many versions of this circuit are poorly designed; credit for this properly designed version of the TTL inverter circuit goes to S. D. Culp [19]. The circuit gives good performance. Crystal waveforms are fairly good, and the frequency is relatively insensitive to power supply and temperature changes. This circuit, in its many variations, is one of the most widely used TTL oscillator circuits.

The circuit uses two negative feedback schemes to ensure oscillation start-up when power is applied, one on each inverter. The circuit will work with any standard TTL NAND gate, NOR gate, or inverter. The output of each gate (or inverter) must be the negative of its input, so that negative feedback can be used to bias the input and ensure oscillator start-up. This subject is discussed in detail in Chapter 9.

The negative feedback. on the second inverter in Fig. 11.3*a* is the simplest, consisting of the single resistor  $R_2$ . Although it does not hurt the second inverter, the single resistor feedback method has the disadvantage of reflecting back a highly nonlinear load resistance to the input (pin 3) of the inverter. A TTL inverter has a gain of approximately 10X. During transition intervals, the 470- $\Omega$  resistance of the feedback resistor  $R_2$  is reduced to 47  $\Omega$ , as seen at the inverter's input (pin 3). At either of the binary states "0" or "1," amplifier gain is effectively zero, so the

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Figure 11.2. CMOS Two-Inverters (74C04) circuit at 200 kHz. (74C04 Copyright 1981 National Semiconductor Corporation.)

input impedance of the 470-R feedback resistor is then 470  $\Omega$  instead of 47  $\Omega$ . Such a highly nonlinear load on the amplifier input, switching back and forth between 470 and 47  $\Omega$ , is undesirable as a crystal load and it should not be used on the first inverter because of distortion introduced on the voltage output from the crystal.

The negative feedback around the first inverter is arranged differ-





Figure 11.3(a). TTL Two-Inverters (7404) circuit at 1 MHz. Set  $R_L \cong R_s (R_L + R_1) \cong 2$ KR.

## TTL VOLTAGE COMPARATOR-LM319

ently. Here, the feedback resistor is divided into two resistors  $R_L$  and  $R_1$ , and the center point is bypassed to ground with a capacitor. The resistance of the feedback network reflected back to the crystal is then constant over a complete waveform cycle and equal to  $R_L$ . The improvement in the crystal's output waveform by adding the bypass capacitor C<sub>1</sub> in the middle of the two feedback resistors  $R_L$  and  $R_1$  is quite significant.

The input (pin 1) of the first inverter is also tied to ground by a resistor  $R_3$ . This shunt resistor  $R_3$  has two functions. First, it pulls the inverter's input into the transition region, so that both the input and output of the inverter are somewhere near  $\pm 1.6$  VDC. The two feedback resistors ( $R_L$  and R, ) then provide additional negative feedback at low frequencies to stabilize the inverter's output voltage (pin 2) at  $\pm 1.6$  VDC, the binary switching point. The second function of  $R_3$  is to control the on/off ratio of the oscillator's square wave output. Adjusting the value of  $R_3$  ( $\pm 30\%$ ?) will trim the square wave output to a perfect 50/50 on/off ratio. The capacitor  $C_2$  between the two inverters is used for DC isolation and allows them to be independently biased without interaction.

The small spikes on  $E_{-1}$  in Fig. 11.3*a* are high-frequency edges of the crystal's square wave drive, which are feeding through the crystal on its terminal shunt capacitance  $C_0$ . There are flat spots adjacent to the switching spikes on the crystal's output voltage  $E_{-1}$ . These flat spots indicate that the input resistance of the inverter itself becomes very low during these flat-spot intervals. These nonlinear, low-resistance flat spots in  $E_{-1}$  occur at the worst possible place in the cycle, that is, at the switching point. They increase timing uncertainty as to when the inverter will switch from one binary state to the other and degrade the circuit's short-term frequency stability.

Figure 11.3*b* shows the inverter circuit with the 74804 instead of the 7404, and Fig. 11.3*c* shows the inverter circuit with the 74LS04. The 74LS04 is the most useful of the three inverters because it covers a wider frequency range than the other two. The 74LS04's higher input resistance allows the use of larger feedback resistors. This permits a higher crystal load resistance  $R_L$ , which is needed for operation at lower frequencies. The 74LS04 will operate down to 100 kHz, whereas the 7404 will operate down to only 800 kHz, and the 74S04 down to 1 MHz. Dissipation in the crystal limits the highest oscillation frequency to about 3 MHz in all three circuits.

## 11.4. TTL VOLTAGE COMPARATOR-LM319

The schematic of this series-resonant circuit at 1 MHz is shown in Fig. 11.4. This circuit's performance is below average. The LM319 is the



Figure 11.3(b). TTL Two-Inverters (74304) circuit. Set  $R_L \cong R_s$ ,  $(R_L + R_1) \cong 1.2 \text{K} \Omega$ .

fastest of the two voltage comparators (LM319 and LM339) currently available for operation from a single +5 VDC supply. The (+) input terminal is referenced to +2.5 VDC.  $R_1C_1$  provides negative feedback at low frequencies to hold the comparator's DC output in the middle of its transition range in order to ensure oscillation at start-up.

Waveforms at the crystal are reasonable, but the crystal's load resistance  $R_L$  of 510  $\Omega$  is higher than it should be at 1 MHz with respect to the crystal's internal series resistance of 240  $\Omega$ . This is due to the amplifier's high output impedance, which is too high for good operation at 1 MHz. If



Figure 11.3(c). TTL Two-Inverters (74LS04) circuit. Set  $R_L \cong R_s$ ,  $(R_L + R_r) \cong 7K \Omega$ .

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the crystal's load resistance  $R_L$  is made lower than 510  $\Omega$ , the crystaldrive waveform  $E_1$  becomes even more distorted than is shown in Fig. 11.4. At 500 kHz and below, the crystal's internal series resistance  $R_s$  and its load resistance  $R_L$  are both higher, and the crystal loading and drive waveform problems improve considerably.

The comparator's input impedance is highly nonlinear. This would warp the crystal's sine wave output much more than is shown in Fig. 11.4 if it were not for the linearizing effect of the crystal's load resistor  $R_L$ ,

which is effectively in parallel with the comparator's input impedance. This nonlinear loading effect will show up more at lower frequencies, where the desired crystal load resistance  $R_L$  is higher. Waveforms in Fig. 11.4 show about an 80-nsec time delay in the LM319 comparator, which limits it to frequencies below 500 kHz for good oscillator operation. But the nonlinear loading effects that occur at these lower frequencies mean that the LM319 will not work well as an oscillator at any frequency. An additional drawback is that the circuit continues to oscillate at a spurious frequency when the crystal is removed.

#### 11.5. TTL RECEIVER-9615

The circuit of this oscillator at 1 MHz is shown in Fig. 11.5. The circuit gives above-average performance. Both receiver inputs are internally biased at + 1.9 VDC.  $R_1C_1$  provides negative feedback at low frequencies to servo the output at pin 1 to + 1.9 VDC, approximately in the middle of the transition region, in order to ensure oscillation at start-up. Waveforms at the crystal are very good. The frequency is not very sensitive to power supply or temperature changes. The crystal's load resistance  $R_L$  is set equal to or somewhat less than the crystal's internal series resistance  $R_L$ .

The circuit uses very few parts and will operate from 100 kHz to 2 MHz. There are two 9615 receivers in a DIP, and the second one makes a convenient isolating buffer for the oscillator.

## 11.6. TTL RECEIVER-8820

The schematic for this oscillator at 1 MHz is shown in Fig. 11.6.  $R_2$  biases the negative (-) input terminal (pin 1) to approximately the same +2.5 VDC bias point as the positive (+) input terminal.  $R_1C_1$  applies negative feedback at low frequencies to hold DC output at the midpoint of the transition region in order to ensure oscillation at startup.

Waveforms at the crystal are fairly good. The output impedance of the 8820 at pin 6 is too high to properly drive a l-MHz crystal, and so the tops of the  $E_6$  square wave curve downward as the crystal's sine wave of current flows back into its driving source at pin 6. Because of this, the crystal's load resistance, which consists of  $R_L$  and the 8820's input resistance of 2.5K  $\Omega$  in parallel, is not so low as desired. With  $R_L = 1$ K  $\Omega$ , the net crystal load is 715  $\Omega$ , which is about 3 times higher than the crystal's



Figure 11.5. TTL receiver (9615) at 1  $_{m}H_{Z.}$  (9615 Courtesy Fairchild Camera and Instrument Corporation.)

internal series resistance of 240  $\Omega$ . This reduces the circuit's short-term frequency stability.

The waveform of the square wave driving the crystal would look better at frequencies of 500 kHz or lower, where the crystal's internal series resistance  $R_s$  is higher. The waveforms show about a 70-nsec time delay in the 8820 line receiver.



Figure 11.6. TTL receiver (8820) at 1  $\rm mHz.$  (8820 Copyright 1981 National Semiconductor Corporation.)

## 11.7. ECL RECEIVER-10114

The schematic of this series-resonant oscillator at 1 MHz is shown in Fig. 11.7*a* and the circuit waveforms in Fig. 11.7*b*. This circuit has outstanding performance and works very nicely off a +5 VDC supply. Waveforms at the crystal are very good, equal to the best of any circuit tested. The frequency changes very little when power supply voltage or temperature is changed. The low ECL drive voltage keeps crystal dissipation low.

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Figure 11.7(a). Series-resonant circuit in ECL at 1 MHz. Set  $R_L \cong R_s$ . (10114, 10116, 10216 Courtesy Motorola, Inc.)

And the low ECL drive resistance means the crystal can have a low load resistance  $R_L$ , which gives very good short-term frequency stability.

The ECL receiver format is well-adapted to high-frequency oscillator circuits. At high frequencies, crystals are low impedance devices, and ECL circuits can drive low impedance loads down to 50  $\Omega$  easily. Input resistances of ECL circuits are high, and they are also linear over the ECL voltage range. As shown in Fig. 11.7b, the crystal's square wave drive waveform at pin 3 has a definite slope during transitions between binary states, indicating the ECL unit is operating as a linear amplifier during the transition interval.

The 10114, 10116, and 10216 are similar in that they have the same pin connections and are directly interchangeable in the circuit in Fig. 11.7*a*. They differ slightly in speed and internal construction. All three have the required push-pull inputs and outputs needed for an ECL oscillator. The 10216 has the widest bandwidth and should be used at the highest frequencies (4-20 MHz). The 10116 has medium bandwidth and should be used at medium frequencies (l-6 MHz). The 10114 has the least bandwidth and should be used at lower frequencies (500 kHz-4 MHz).

Figure 11.7*c* shows the circuit at 20 MHz. The crystal's internal series



Figure 11.7(b). Waveforms for series-resonant-ECL circuit in Fig. 11.7a.

resistance  $R_s$  is 7  $\Omega$ ; the crystal's load resistance  $R_L$  is 10  $\Omega$ . At 20 MHz, the ECL receiver has to be able to drive a 17-R load ( $R_s + R_L = 17 \Omega$ ), a very low value. The receiver's output resistance is controlled by the ECL emitter's output current, which is, in turn, controlled by the emitter's pulldown resistor  $R_3$ ,  $R_3 = 510 \Omega$  works well at 1 MHz, but it has to decrease to 100  $\Omega$  at 20 MHz to get the ECL output resistance down low enough to provide a reasonable drive waveform to the crystal.

There are three ECL receivers in one DIP. One of the two unused ones could be used as a no-cost buffer between the oscillator and the two-transistor buffer, but the circuit will oscillate spuriously when the crystal is removed. Because of this, the ECL receivers are not used as buffers.

The buffer circuit is specifically designed to minimize capacitive loading (the Miller effect) from the buffer onto the oscillator, which can



Figure 11.7(c). Series-resonant circuit in ECL at 20 MHz. Set  $R_L \cong R_s$ . (10116, 10216 Courtesy Motorola, Inc.)

change the oscillation frequency. Part of the buffer design shown in Fig. 11.7*a* is taken from Blood [20]. To minimize the Miller capacitance effect,  $Q_1$  is operated without a collector load resistor, and the voltage swing at the collector of  $Q_2$  is limited to 0.7 V peak by the base-emitter junction of  $Q_3$ . The square wave on/off ratio at the output of  $Q_3$  depends on the gain of  $Q_3$ , which varies from one transistor to the next. The on/off ratio at the output also depends on  $R_4$ . Making  $R_4$  adjustable provides an adjustment of the on/off ratio at the output if it is needed.

## C. PIERCE

## 11.8. CMOS INVERTER-74C04

The circuit of this Pierce-IC oscillator at 1 MHz is shown in Fig. 11.8. The output resistance  $R_0$  of the first inverter is used as the integrating resistor for the  $R_0C_2$  phase-lag network. Small values of  $C_1$  and  $C_2$  are used in order to minimize the gain reduction they introduce. One result of this is that the crystal oscillates a little higher above its series-resonant frequency.  $R_1$  provides negative DC feedback around the inverter in order to put it in the linear region so that oscillation will start when





power is applied. The second inverter squares up the output waveform and also acts as an isolation buffer.

This CMOS circuit works reasonably well at frequencies up to 1 MHz. Above 1 MHz, variations among manufacturers show up, and only certain brands will work satisfactorily. National Semiconductor's 74C series will work up to 2 MHz, and Solid State Scientific's 4000A/B series will work up to 5 MHz. Capacitance values of  $C_1$  and  $C_2$  at 1, 2, and 5 MHz are listed in Fig. 11.8. Above 2 MHz, the crystal's dissipation should be checked, so that its dissipation limit is not exceeded.

#### ECL RECEIVER-10114

## 11.9. TTL VOLTAGE COMPARATOR-LM319

The schematic of this Pierce-IC at 1 MHz is shown in Fig. 11.9. The LM319 is a voltage comparator with a relatively large 60-nsec internal time delay, which limits its upper oscillation frequency to about 2 MHz. There are faster comparators available, but they require  $\pm 15$  V power rather than only  $\pm 5$  V. The LM319's high input impedance allows it to operate at frequencies down to 10 kHz. Its input impedance is quite nonlinear, however, which will distort the crystal's output waveform at lower frequencies.  $R_2$  and  $R_3$  provide a DC feedback to ensure that the comparator is in its linear conducting region and will start oscillating when power is applied.

The LM319 performs well as a Pierce oscillator. The  $50-\Omega$  reactive impedance of the 3300-pF capacitor  $C_2$  (at 1 MHz) swamps out the LM319's nonlinear input impedance, and the voltage waveforms at the crystal are reasonably good. The on/off ratio at the output can be adjusted closer to 50/50 than is shown in the waveform photograph by adjusting the ratio of the biasing resistors  $R_4$  and  $R_5$ . The circuit does have the disadvantage that it oscillates spuriously with the crystal out of the circuit. There are two LM319 comparators in a DIP, and for convenience, the second one is used as an isolation amplifier.

## 11.10. ECL RECEIVER-10114

A schematic of this Pierce-IC at 1 MHz is shown in Fig. 11.10a and its waveforms in Fig. 11.10b. Three ECL receiver stages are cascaded to provide the high gain required by the Pierce circuit. The circuit works well at 1 MHz with the 10114, but not with the 10116.  $R_2$  and  $R_3$  provide DC feedback around the receivers to bias them into the linear operating region, so that the circuit will start oscillating when power is applied.

Frequency stability with both power supply and temperature changes is very good; crystal waveforms are also reasonably good. One drawback to the circuit is the fairly large number of discrete parts required. The buffer circuit converts the oscillator's ECL output to a TTL format. The buffer is designed to minimize capacitive loading effects on the oscillato . circuit. The design of the buffer is discussed in more detail in Section 11.7.

Figure 11.10*c* shows the same circuit at 20 MHz. Either the IO116 or the 10216 can be used at this frequency, but not the 10114, which does not have enough gain at 20 MHz for the circuit to oscillate. This circuit



Figure 11.9. Pierce in TTL (LM319) at 1 MHz. (LM319 Copyright 1981 National Semiconductor Corporation.)

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Figure 11.10(a). Pierce in ECL (10114) at 1 MHz. (10114 Courtesy Motorola, Inc.)

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Figure 11.10(b). Waveforms for Pierce-ECL circuit in Fig. 11.10a.

gives good performance and has good waveforms at the crystal. Note that the output resistance of the ECL stage that drives the crystal has been lowered by decreasing emitter-pulldown resistors  $R_4$  to 200  $\Omega$ , so it can drive the low resistance crystal load at 20 MHz. The frequency sensitivity of the 10116 to power supply changes is only half that of the 10216. The 10116 oscillates spuriously when the crystal is removed from the circuit, but the 10216 does not. For best short-term frequency stability,  $C_2$  should be four times larger than the 470 pF shown in Fig. 11.10c, but the circuit does not have enough gain to permit the additional gain loss involved in doing this. Circuit layout is important in this circuit to prevent spurious oscillation.



Figure 11.10(c). Pierce in ECL (10216) at 20 MHz. (10116, 10216 Courtesy Motorola, Inc.)

## D. MEACHAM

### 11.11. MEACHAM-10114

As an IC oscillator, the Meacham circuit's needs for both positive (+) and negative (-) bridge drive signals effectively limits it to ECL. An ECL receiver has both (+) and (-) inputs and outputs and provides an opportunity to try Meacham's full-bridge rather than only the half-bridge circuit. A schematic of Meacham's full-bridge circuit at 10 MHz is shown in Fig. 11.11*a*; it is a complex circuit with good performance. Figure 11.11*b* shows voltage waveforms at several points in the circuit in Fig. 11.11*a*.

The 10114 works well in this circuit, but not the 10116 or the 10216. The amplifier uses two ECL stages, giving a gain of 18X from point *A* to pin 14. If three ECL stages are used, the amplifier becomes unstable and oscillates parasitically at 60 MHz. Emitter-pulldown resistors at the ECL amplifier's output are set to give maximum emitter current, which gives the lowest possible output resistance. This is needed to drive the crystal's low internal series resistance  $R_s$  of 5  $\Omega$ .

 $C_3$  and  $C_4$  permit negative feedback at DC, stabilizing the bias point and ensuring that oscillation will start when power is applied.  $C_2$  balances out the crystal's shunt terminal capacitance  $C_0$ , which helps minimize parasitic oscillation.

The bridge excitation is a square wave. The resonant  $L_1C_1$  tank selects the fundamental sine wave from the bridge output, ignores the harmonics, and reduces the response at frequencies away from resonance.  $R_1$  reduces the  $L_1C_1$  phase shift from 90" down to 0° at frequencies far away from resonance.  $R_3$  isolates  $L_1C_1$  from the crystal. The waveform clean-up by the  $L_1C_1$  tank can be seen in  $E_2$  (waveform at pin 2), which is proportional to the differential input signal between pins 4 and 5 in Fig. 11.11*a*. The peculiar looking waveform  $E_A$  out of the bridge at point *A* is normal and occurs when a square wave with sloping sides (through bridge arm  $R_2$ ) is subtracted from a sine wave (through the crystal arm).

The minimum theoretical value for  $R_2$  is equal to the crystal's internal series resistance  $R_s$  of 5  $\Omega$ . The minimum practical value for  $R_2$  measures 8.2  $\Omega$ , which gives a practical to theoretical minimum ratio of 8.2/5 or 1.6 for  $R_2$ .

Meacham's full-bridge circuit can be changed into the modified Meacham half-bridge circuit shown in Fig. 11.1 1*c*. The isolation resistor  $R_3$  is increased to 240  $\Omega$  to compensate for the drop in bridge source resistance when the two 240- $\Omega$  bridge arms are removed. The performance of the half-bridge circuit is just as good as that of the full-bridge



Figure 11.11(a). Meacham at 10 MHz. (10114 Courtesy Motorola, Inc.)

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Figure 11.11(b), Waveforms for Meacham circuit in Fig. 11.11a.

**CMOS 7209** 



**Figure 11.11**(*c*). Modified Meacham at **10** MHz. (10114 Courtesy Motorola, Inc.)

circuit, as far as could be measured. The minimum practical value for  $R_2$  in the half-bridge circuit is also 8.2  $\Omega$ , which gives the same ratio of 8.2/5 or 1.6 for  $R_2$ . The full-bridge circuit does cancel out source resistance variations in the bridge drive, so its frequency stability is potentially better than that of the half-bridge circuit. The short-term stability of both circuits measured 0.1 ppm, at the limit of available measuring equipment. The full-bridge circuit is preferred to the half-bridge; the only advantage of the half-bridge circuit is that it uses one less resistor than the full-bridge circuit.

## E. SPECIAL OSCILLATOR ICs

## 11.12. CMOS 7209

The schematic of this Pierce-IC oscillator at 10 MHz is shown in Fig. 11.12. The 7209 uses a single CMOS inverter in the oscillator circuit and has an internal feedback resistor around the inverter to bias the input into its linear conducting region and ensure oscillator start-up when power is applied. The advantage of the 7209 is that it will oscillate at frequencies up to **10** MHz, while an ordinary CMOS inverter quits at 2-5 MHz in the Pierce circuit (see Section 11.8). The oscillator and its fundamental frequency output will operate at frequencies down to at least 4 **kHz**.



Figure 11.12. 7209 at 10 MHz. (7209 Reproduced by permission of Intersil, Inc. from Data Sheet ICM 7209 CMOS Clock Generator. Copyright 1979 Intersil, Inc. All rights reserved.)

The 7209 provides a second output frequency at <sup>1</sup>/<sub>8</sub> the **crystal** frequency. This divide-by-eight output uses dynamic divider circuitry, which will operate at 2 MHz (crystal frequency) with a 5 V supply voltage. The divide-by-eight circuit will work at crystal frequencies lower than 2 MHz by reducing the supply voltage below 5 V. When the crystal is removed from the circuit, the fundamental frequency output stops (as it should), but the dynamic divide-by-eight frequency output at pin 6 continues to free run at a spurious frequency.

The 7209 gives reasonably good performance at both 1 and 10 MHz. At 1 MHz, it operates over a wide range of supply voltage and temperature. At 10 MHz, the supply voltage must be greater than +4 V, and the

temperature rise above ambient must be somewhat less than what is permissible at 1 MHz, or the output voltage swing at pin 5 will drop to zero.

In a Pierce circuit, the values of the two capacitors  $C_1$  and  $C_2$  should be changed when the frequency is changed. At 1 MHz, both  $C_1$  and  $C_2$  in Fig. II.12 should be 100 pF. And at 100 kHz, both  $C_1$  and  $C_2$  should be **470** pF.

The 10-MHz waveform photographs in Fig. 11.12 show that voltage across the crystal is 2.4 Vrms, while Fig. 2.5 shows that maximum crystal voltage at series resonance is 0.3 Vrms at 10 MHz. Is the crystal's 2-mW dissipation limit being exceeded? The answer is no, because the crystal is operating inductively, way above series resonance. The current through the crystal can be determined from the voltage drop across the crystal load. Figure 11.12 shows 1.4 Vrms across a total capacitive load of about 32 pF (22 pF plus 5 pF stray plus 5-pF amplifier input capacitance). At 10 MHz, 32 pF has an impedance of 520  $\Omega$ , which gives a crystal current of 1.4/520 = 2.7 mA rms. Figure 2.3 shows a maximum crystal series resistance  $R_s$  of 25  $\Omega$  at 10 MHz. Calculating the crystal's power dissipation from  $I^2R_s$  gives 0.18 mW, which is less than the crystal's 2-mW dissipation limit.

## 11.13. TTL 74LS321

The 74LS321 uses a variation of the common base amplifier circuit, and a brief schematic at 1 MHz is shown in Fig. 11.13. The 74LS321 operates over a frequency range of 1-20 MHz and is the oscillator section of the 74LS362. The 74LS320 is identical to the 74LS321 except that the divide-by-two and the divide-by-four frequency outputs have been deleted in the 74LS320.

The source and load resistances seen by the crystal looking back into the circuit at pins 14 and 15 both measure 40  $\Omega$ , giving the crystal an external load resistance of 80  $\Omega$ . The inductor  $L_1$ , together with the collector resistor  $R_1$ , provides a phase-lead network in the oscillator loop. The inductance value to be used for  $L_1$  varies with frequency, and the circuit will not oscillate unless the proper inductance value is used. Table 11.1 lists inductance values recommended by the manufacturer at various frequencies. From a design point of view, it is not necessary to use an inductor to make a common base amplifier circuit operate as a fundamental oscillator over the 1–20-MHz frequency range. The inductor is apparently carried over from the 74LS362 design, where it was needed to provide an LC tank for harmonic operation at 48 MHz.



Figure 11.13. 74LS321 at 1 MHz. (74LS321 Courtesy Texas Instruments Incorporated.)

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## TTL SP705B

Frequency (MHz)	Inductance $L_1$ ( $\mu$ H)		
1	160.		
2	100.		
3	59.		
4	37.		
5	24.		
6	16.5		
7	11.		
8	8.5		
9	7.		
10	6.		
15	5.5		
20	5.		

			TAP	1 1	1.1		
Inductance	to	Be	Used	in	the	74LS321	Circuit
	at	Va	rious	Fre	eque	ncies	

This circuit does not perform very well; the voltage waveform driving the crystal is poor. At 1 MHz, the frequency is reasonably stable and changes only 4 ppm when the power supply voltage is changed from 4 to 6 V. But at 20 MHz, the frequency drifts 1 ppm short termwise and changes 102 ppm when the power supply voltage is changed from 4 to 6 V.

## 11.14. TTL **SP705B**

A schematic of this circuit at 1 MHz is shown in Fig. 11.14. The **SP705B** uses the common base amplifier circuit and is designed for frequencies up to 10 MHz. No minimum frequency is specified by the manufacturer, but the crystal's internal series resistance  $R_s$  is specified at 300  $\Omega$  maximum, which corresponds to a minimum frequency of about 1 MHz.

Looking back into the circuit at pin 6, the source resistance  $R_0$  driving the crystal is 110  $\Omega$ , and looking back into the circuit at pin 5, the crystal's load resistance  $R_L$  is 32  $\Omega$ . This gives a total resistive load on the crystal of 142  $\Omega$ . This is a reasonable load value at 1 MHz, where the crystal's internal series resistance  $R_s$  is 240  $\Omega$ , and gives fairly good incircuit  $\Omega$  and short-term frequency stability at 1 MHz. But 142  $\Omega$  is too high a load resistance at 10 MHz, where the crystal's internal series resistance is about 15  $\Omega$ . This high load resistance reduces both the crystal's in-circuit  $\Omega$  and the short-term frequency stability at higher frequencies.





Figure 11.14. SP705B at 1 MHz. (SP705B Courtesy Plessey Semiconductors.)

ECL 12061

At 1 MHz, it takes the circuit about 1 second to start oscillating, but at 10 MHz, it starts immediately. Only the half-frequency and quarterfrequency outputs have a **TTL** format. The crystal's fundamental frequency is available at pin 6, but it is a low voltage signal (0.6 Vp-p) and will not drive TTL circuitry directly.

The circuit's performance is fair at 1 MHz but poor at 10 MHz. Waveforms at the crystal are poor; the driving waveform is distorted, and the output waveform shows a pair of switching spikes riding on top of the waveform. At 1 MHz, the oscillation frequency is relatively insensitive to temperature and power supply voltage changes, But at 10 MHz, the frequency shifts 47 ppm when the power supply voltage changes from 4 to 6 V.

## 11.15. ECL 12061

A schematic of this IC oscillator is shown in Fig. 11.15. This oscillator uses a variation of the common base amplifier circuit and incorporates an AGC (automatic gain control) loop to keep oscillation amplitude at a low level and minimize power dissipation in the crystal. The oscillator has three outputs: sine wave, ECL, and TTL and comes in two frequency ranges: the 12060 for a 100 kHz-2 MHz operation and the 12061 for a 2-20 MHz operation. In the 12060, the source and load resistances seen by the crystal looking back into pins 5 and 6 are both 2.7K  $\Omega$ , giving a total crystal load resistance of  $5.4 \text{K} \Omega$ . In the 12061, the source and load resistances looking back into pins 5 and 6 are both 130  $\Omega$ , giving a total crystal load resistance of 260  $\Omega$ . A 0.1- $\mu$ F bypass capacitor is required directly across the oscillator section's power pins from pin 1 to pin 8 to minimize noise coupling into the oscillator. If the TTL output section is used, a second 0.1- $\mu$ F capacitor is required directly across its power pins from pin 9 to pin 11 to minimize noise coupling of the TTL switching transients into the oscillator section.

Unfortunately, neither the 12060 nor the 12061 work very well, particularly at the high-frequency ends of their range. Crystal waveforms are poor; the **2-MHz** waveforms shown in Fig. 11.15 for the 12061 are typical of either IC at any frequency. The 12060 is reasonably insensitive to power supply and temperature changes at 100 kHz. But at its upper frequency limit of 2 MHz, the frequency is unstable with temperature and shifts 150-180 ppm when heated or cooled above or below ambient. The 12061 works reasonably well at its low frequency limit of 2 MHz, but at its upper frequency limit of 20 MHz, there is a relatively large



Figure 11.15. 12060, 12061 circuit. Waveforms are for the 12061 at 2 MHz. (12060, 12061 Courtesy Motorola, Inc.)

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#### LINEAR LM375

14-ppm frequency shift when the power supply voltage is changed from 4 to 6 V and a large 28-ppm frequency shift when heated above ambient. The basic difficulty seems to be that IC source and load resistances seen by the crystal are scaled for operation at the low end of each frequency range and are too large to operate well at the high end.

#### 11.16. LINEAR LM375

A schematic of this series-resonant circuit at 500 kHz is shown in Fig. 11.16*a*. The LM375 contains two buffer amplifiers and provides both sine wave and TTL outputs. A sine wave rather than a square wave can be obtained from the first buffer by interchanging its input leads and disconnecting the TTL driver. The LM375 oscillator section contains a very wideband amplifier, with a relatively high output resistance at pin 5. Because of the amplifier's wide bandwidth, it is necessary to add capacitor  $C_1$  across the oscillator's input at the lower frequencies (500 kHz), as shown in Fig. 11.16*a*, in order to avoid extra noise switchings when the oscillator's waveform switches polarity.

With a resistive load  $R_2$  on the oscillator, the highest oscillation frequency is limited to about 500 kHz because of loading effects on the oscillator's high output resistance. Above 500 kHz, the amplifier's square wave output gets too distorted to drive a low resistance crystal.

The LM375 can be used at frequencies up to 10 MHz if a tuned LC tank instead of the resistor  $R_2$  is used for the oscillator load. Figure 11.16b shows a circuit for 10 MHz operation. The crystal is tapped down on the LC tank in order to raise the crystal's low internal resistance  $R_s$  to a much higher value, as seen by the amplifier's output at pin 5. Tapping down the crystal on the LC tank has a considerable effect on the circuit, and this is discussed in detail in Sections 5.13 and 7.6.

The oscillator section of the LM375 will work at up to 60 MHz, but the buffer and TTL driver circuits will not operate properly above 10 MHz. From a general design viewpoint, it is not necessary to use an LC tank for fundamental operation at 10 MHz, but it is needed here because the oscillator's high output resistance needs a high load impedance to work into.

The oscillator performs well with a resistive oscillator load at and below 500 kHz. Crystal waveforms are good, and the oscillation frequency is relatively independent of power supply and temperature changes.

The oscillator gives only a fair performance with a resonant LC tank

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**Figure 11.16**(*a*). **LM375 at 500** kHz. **(LM375 Copyright 1981 National** Semiconductor Corporation.)



**Figure 11.16(b).** LM375 at 10 MHz. (LM375 Copyright 1981 National Semiconductor Corporation.)

for the oscillator load. The crystal's load resistance  $R_L$  at 10 MHz should be about 10  $\Omega$  or less but could not be reduced below 33  $\Omega$  without starting parasitic oscillations. In addition, the circuit oscillates spuriously when the crystal is removed from the circuit. The LM375 has been discontinued by the manufacturer.

## 11.17. LINEAR SL680C

A schematic of this emitter coupled circuit at 2 MHz is shown in Fig. 11.17*a*, and its waveforms are shown in Fig. 11.17*b*. The SL680C has an AGC loop to keep the crystal's power dissipation low; it has only a sine wave output, at pin 6. The emitter follower output at pin 7 should not be used, since any external noise picked up here couples directly onto the crystal, and any loading effects will reduce loop gain and may prevent the circuit from oscillating.

The power supply voltage of the SL680C is rated at +6 to +10 VDC, but it will operate at +5 V if a sine wave output with its negative peak flattened off is acceptable. Waveforms in Fig. 11.17*b* are for a +6 V rather than +5 V supply, in order to show the sine wave output at pin 6 when the IC is operated within its rated power supply range.

The load resistance seen by the crystal looking into pin 1 is 45  $\Omega$ . The loop gain of the emitter coupled circuit varies inversely with the crystal's internal series resistance  $R_s$ , which means that loop gain decreases as



Figure 11.17(*a*). SL680C at 2 MHz. (SL680C Courtesy Plessey Semiconductors.)

frequency decreases. The **SL680C** oscillated properly at frequencies of 2-20 MHz but would not oscillate at 1 MHz or lower. It would not operate harmonically much above 20 MHz even when a parallel tuned LC circuit (AC coupled) was added from pin 4 to ground in Fig. 11.17*a*.

The circuit gives good performance at 2 MHz and fair performance at 20 MHz. Operating the circuit at +5 VDC rather than at +6 V makes little difference at 2 MHz other than the flattened negative peak on the sine wave output. At 20 MHz and +5 V, frequency is fairly sensitive to the power supply voltage, changing 35 ppm when the power supply voltage is dropped from +6 V to +5 VDC. The frequency shift is much less within the **SL680C's** rated supply range, changing only 3 ppm when the power supply voltage is changed from +6 to +8 V. Also, at 20 MHz, the frequency changes quite a bit (12 ppm) when heated above ambient regardless of whether the power supply voltage is +5 V or +8 V.





## F. VHF HARMONIC

## 11.18. ECL RECEIVER-10216 (100 MHz)

This is a VHF harmonic oscillator that uses an ECL IC for its amplifier. It is a series-resonant circuit oscillating at 100 MHz, with a capacitive tap on the LC tank; the schematic is shown in Fig. 11.18. The circuit is a variation of Butler's emitter follower circuit in Fig. 5.31, with the emitter follower having a gain of 1.5-6X instead of just 1X. For frequency stability,  $L_1$  must have an air core, while  $L_0$  is not very critical and can have an iron core.  $R_1$  has a big effect on circuit operation; if  $R_1$  is too high,  $L_1C_1$ tunes so strongly that it takes control over the oscillation frequency away from the crystal. If  $R_1$  is too low, it broadens the bandwidth of the  $L_1C_1$ tank so much that the tank loses its primary function of selecting which harmonic the crystal is to oscillate at. If  $R_1$  is made even smaller, loop gain becomes less than IX, and the circuit will not oscillate at all.



Figure 11.18. VHF harmonic oscillator in ECL (10216) at 100 MHz. (10216 Courtesy Motorola, Inc.)

This circuit works very well. Its short-term frequency stability is very good, and its sensitivity to power supply changes is low and reasonably low to temperature changes. The circuit shows no parasitic oscillation effects. The buffer is designed to minimize capacitive loading effects on the oscillator circuit. The design of the buffer is discussed in more detail in Section 11.7.

STATISTICS OF

## CHAPTER TWELVE

# COMPARING THE CIRCUITS

This chapter describes the relative performance of all the oscillator circuits and lists their strong and weak points. To obtain the performance data, a test circuit of each type was built and its performance measured. The circuits are discussed individually, and their performance is summarized in four tables: discrete transistor circuits, ICs, bridge circuits, and harmonic circuits. At the end of this chapter, the circuits are rated on a relative scale of outstanding to poor.

## 12.1. PERFORMANCE CRITERIA

There are several criteria for rating the performance of oscillator circuits. One important factor is whether the crystal likes the circuit, as indicated by voltage waveforms in and out of the crystal. Another important factor is the in-circuit Q, which depends on the ratio of the circuit's external resistance as seen by the crystal across its terminals to the crystal's internal series resistance  $R_s$ . The frequency should be reasonably independent of power supply and temperature changes, and power dissipation in the crystal should be low. Circuit complexity and parts count are factors to be considered. Spurious oscillations when the crystal is removed from the circuit are undesirable, as are parasitics.

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#### 12.2. OSCILLATORS USING DISCRETE TRANSISTORS

Performance of the different discrete transistor circuits varies from outstanding to poor, and is listed in Table **12.1**. The data were obtained from the

			Measured	Performance
Circuit	Schematic in Figure	Useful Frequency Range	Does Circuit Oscillate Without Crystal?	Frequency of Oscillation ( <b>MHz</b> )
Miller-FET	10.1 <i>a</i>	1 <b>kHz-</b> 20 MHz	No	1.000 139
Miller-transistor	10.2a	500 <b>kHz-</b> 20 MHz	No	1.000 030
Colpitts-FET, RC	10.3 <i>a</i>	1 <b>kHz–</b> 10 MHz	No	1.000 150
Colpitts-FET, LC	10.3b	1 <b>kHz-</b> 10 MHz	No	1.000 136
Colpitts-transistor, RC	10.4 <i>a</i>	200 <b>kHz-</b> 20 MHz	N o	1.000 094
Colpitts-transistor, LC	10.4b	200 <b>kHz-</b> 20 MHz	No	1.000 257
Low capacitance load High resistance load Common <b>base</b> - transistor	10.5 <i>a</i> 10.6 <i>a</i> 10.7 <i>b</i>	100 kHz- 10 MHz 100 kHz- 10 MHz 1- 600 kHz	No No No	1.000 301 1.000 671 0.004 000
Common base-	10.7a	<b>1–</b> 20 MHz	No	0.999 997
Common gate-FET	10.8	100 <b>kHz-</b> 1 MHz	No	0.999 997
Pierce	10.9a	1 <b>kHz-</b> 20 MHz	No	1.000 009
Pierce-exact series	10.10 <i>a</i>	1 <b>kHz-</b> 20 MHz	No	1.000 000
Pierce without	10.11 <i>a</i>	1 <b>kHz-</b> 20 MHz	N o	1.000 009
Pierce low	10.9d	<b>l</b> - 500 <b>kHz</b>	No	0.004 000
Pierce high frequency	10.9g	<b>5-</b> 20 MHz	No	20.000 432
Emitter coupled	10.12	100 <b>kHz-</b> 20 MHz	No	0.999 998

## TABLE 12.1 Performance of Discrete Transistor Oscillator Circuits

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	Mea	sured Perfor	mance		
Wayoforms	DS Sonsitivity	Circuit Te Sensi	emperature tivity		
at Crystal	$(\Delta V_{cc} = 2 V)$ $\Delta f (ppm)$	Freeze $\Delta f$ (ppm)	Heat $\Delta f$ (ppm)	Overall Performance	Remarks
Good	3.	- 6 .	+4.	Poor	Not recom- mended
Poor	9.	i-3.	- 4 .	Poor	Not recom- mended
Good	0.7	+2.	-1.	Good	Low parts count
Fair	2.	+2.	- 5 .	Good	Useful as harmonic oscillator
Fair	3.	-1.	-0.6	Fair	Low parts count
Fair	4.	+2.	- 3 .	Fair	Useful as harmonic oscillator
Fair	1.	+0.6	-1.	Good	obolinator
Fair	3.	+2.	- 3.	Fair	
Very good	2.	+3.	- 4 .	Very good	
Good	0.3	0.0	- 2 .	Very good	
Very good	0.1	+0.4	- 5 .	Very good	
Good	1.	+0.5	- 2 .	Best	Recom- mended
Very good	0.8	+2.	- 2 .	Best	Recom- mended
Fair	0.7	+0.5	- 0 . 7	Good	
Very good	0.0	+0.1	- 3 .	Very good	Recom- mended
Very good	2.	- 3 .	+0.1	Good	High parts count
Good	0.5	-0.3	-0.8	Good	High parts count

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circuits in Figs. 10.1-10.13, and their performance is summarized in the following paragraphs.

Miller circuits (Figs. 10. la and 10.2a) give poor performance. The crystal waveform is awful in the transistor circuit, and only fair in the FET circuit. The frequency is 30-139 ppm above series resonance. The frequency shifts considerably with power supply and temperature changes, and with the gain of the transistor used. In addition, the frequency is very sensitive to the feedback capacitance used.

Colpitts circuits (Figs. 10.3a–d and 10.4a–d) give average performance. The crystal waveform varies from poor to very good. The frequency is 94–257ppm above series resonance, and is very sensitive to the value of capacitor  $C_2$ . A FET works much better in this circuit than a transistor. Colpitts circuits have very few parts, a practical advantage.

The low capacitance load circuit (Fig. 10.5a) gives average performance. The crystal waveforms are only fair, but the circuit is very stable in the face of power supply and temperature changes. It has a good short-term frequency stability of 0.1 ppm. Its oscillation frequency is very high, however, at 301 ppm above series resonance. This is due to the low capacitance load on the crystal acting in series with the crystal's internal motional capacitance, reducing the total net series capacitance and raising the oscillation frequency.

The high resistance load circuit (Fig. 10.6a) turns out to be essentially the same as the low capacitance load circuit, but with poorer performance. The former oscillates at an even higher frequency than the low capacitance load circuit, at 671 ppm above series resonance. This is due to the very small capacitance load on the crystal.

Common base amplifier circuits (Figs. 10.7a and b and 10.8) give above average performance. Crystal waveforms and the short-term frequency stability are both very good. The crystal has very low source and load resistances, which give it its very good short-term frequency stability. The frequency is somewhat sensitive to temperature changes. The circuit oscillates exactly at series resonance.

Pierce circuits (Figs. 10.9a, d, and g and 10.10a) give outstanding performance. Crystal waveforms are good to very good. The short-term stability is 0.1 ppm, as good as any circuit tested with the exception of the bridge circuits. The oscillation frequency is normally a little above (5-40 ppm) series resonance but can be set exactly at series resonance or even below it. The frequency sensitivity to power supply and temperature changes is very low, as good as any circuit tested. The circuits dissipate very little power in the crystal and provide a high output voltage at the same time. The increased gain advantage of operating the Pierce without a series resistor (Fig. 10. lla) does not offer much in the discrete transistor circuit, but it does permit making a Pierce oscillator out of a CMOS inverter, which does not have enough gain for the standard Pierce circuit. Operating the Pierce at exact series resonance requires more parts in the circuit and does not seem to offer much advantage in exchange for the higher parts count.

The Emitter coupled circuit (Fig. 10.12) gives average performance. Its measured performance is above average, but the sensitivity of its waveforms to stray capacitance effects brings its overall performance down to average. Its sensitivity to power supply and temperature changes is very low, and its short-term frequency stability is very good. One disadvantage of the circuit is its relatively high parts count.

## 12.3. SERIES-RESONANT OSCILLATORS USING ICs

The performance of series-resonant IC oscillators varies from above average to poor. The measured performance of a test circuit of each type is listed in Table 12.2; the data were obtained from the circuits shown in Figs. 11.1–11.7. The performance of these series-resonant IC oscillators is summarized in the following paragraphs.

The CMOS two-inverters circuit (4009 in Fig. 11.1) gives poor performance. It has good waveforms at the crystal, but its frequency is very sensitive to power supply and temperature changes. Its upper frequency limit is 300 kHz. The 74C04 (Fig. 11.2) also gives poor performance. It has good waveforms at the crystal, but its frequency is very sensitive to power supply changes. The 74C04's performance is slightly better than that of the 4009, and it has a higher upper frequency limit of 500 kHz.

The TTL two-inverters circuit (7404 in Fig. 11.3a) gives average performance. Waveforms at the crystal are good, and the frequency is reasonably independent of power supply and temperature changes. The 74804 offers no advantages over the 7404, but the 74LS04 does. The 74LS04 can be used at lower frequencies (down to 100 kHz), but its frequency is a little more sensitive to power supply changes. All three TTL inverters oscillate at a spurious frequency when the crystal is removed from the circuit, a practical disadvantage. The upper frequency limit for all three TTL inverters is about 3 MHz. This is controlled by the crystal's power dissipation limit rather than by the inverters themselves.

The TTL voltage comparator circuit (LM319 in Fig. 11.4) gives below average performance. Waveforms at the crystal are only fair, and the frequency is rather sensitive to power supply voltage changes. The crystal's source and load resistances are a little high, reducing the short-term frequency stability. The circuit's upper frequency limit is 1 MHz.

As to the two TTL receiver circuits (9615 and 8820 in Figs. 11.5 and 11.6), the performance of the 9615 is above average. Waveforms at the crystal are

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Does Circuit Frequency Schematic Useful Oscillate of Oscillation IC in Frequency Without Number Circuit Type Figure Range Crystal? (MHz) 11.1 Below 300 No 0.199 993 4009 Series CMOS-2 kHz resinverters onance CMOS-2 11.2 Below 500 74604 No 0.199 995 Series resinverters kHz onance 11.3a800 kHz-3 TTL-2 7404 Series Yes 0.999 999 MHz inverters resonance l-3 MHz 74S04 TTL-2 11.3bYes 0.999 998 Series resinverters onance 11.3c74LS04 TTL-2 100 kHz-3 Yes 0.999 996 Series MHz resinverters onance Below 1 0.999 981 Yes 319 Series TTL-V. 11.4 rescompar. MHz onance 9615 Series TTL-Line 11.5 100 kHz-2 No 0.999 996 MHz receiver resonance 8820 TTL-Line 11.6 100 kHz-1 No 0.999 984 Series MHz receiver resonance 10114 ECL-Line 11.7a500 kHz-1.000 001 Series No 10 MHz resreceiver onance 10116 ECL-Line 11.7al-20 MHz 1.000 001 Series . No receiver resonance 11.7a10216 Series ECL-Line 1-20 MHz No 1.000 001 receiver resonance 10216 ECL-Line 11.7cl-20 MHz NO 19.999 773 Series receiver resonance 74C04 CMOS-1 kHz-2 Pierce 11.8 No 1.000 040 inverter MHz 319 Pierce TTL-V. 11.9 10 kHz-2 Yes 1.000 001 compar. MHz 10114 ECL-Line 11.10a100 kHz-1.000 006 Pierce No receiver 20 MHz

Measured Performance

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	Measured Performance					
Waveforms	Square Wave on/off Times (usec:	P.S. Sensitivity $(\Delta V_{cc} =$	Circuit 7 Sen:	<b>Femperature</b> sitivity	<b>Overall</b> Perfor- mance	
at Crystal	should be equal)	$\frac{2}{\Delta f} \stackrel{(\text{ppm})}{(\text{ppm})}$	<b>Freeze</b> $\Delta f$ (ppm)	Heat $\Delta f$ (ppm)		Remarks
Good	2.4/2.6	13.	+3.	+12.	Poor	
Good	2.45/2.55	14.	+2.	- 4 .	Poor	
Good	0.49/0.51	2.	+0.5	0.0	Good	
Good		1.	-	-	Good	
Good	-	2.		-	Good	
Fair	0.60/0.40	5.	-0.7	-1.	Fair	
Very good	0.50/0.50	0.2	+0.3	-1.	Good	Low parts count
Fair	0.40/0.60	2.	+3.	- 6 .	Fair	
Very good	0.50/0.50	0.1	-	<u> </u>	Very good	Recom- mended
Very good	0.50/0.50	0.4	-	-	Very good	Recom- mended
Very good	0.50/0.50	0.1	-0.1	- 0 . 4	Very good	Recom- <b>mended</b>
Very good	0.025/0.025	0.7	-	-	Very good	Recom- mended
Good	0.50/0.50	3.	+2.	- 2 .	Good	Low parts count
Good	0.6010.40	1.	- 0 . 3	- 2 .	Good	
Good	0.4910.51	0.2	+0.8	- 0 . 5	Very good	High parts count

(continued)

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Measured Performance

<b>IC</b> Number	Circuit	Type	Schematic in Figure	Useful Frequency Range	Does Circuit Oscillate Without Crystal?	Frequency of Oscillation (MHz)
10216	Pierce	ECL-Line receiver	11.10c	100 <b>kHz-</b> 20 MHz	No	20.000 525
7209	Pierce	CMOS- Special	11.12	4 <b>kHz-10</b> MHz	No	1.000 077
7209	Pierce	CMOS- Special	11.12	4 kHz-10 MHz	No	10.006 329
74LS321	Common base	TTL- Special IC	11.13	l-20 MHz	No	1.000 006
74LS321	Common base	TTL- Special IC	11.13	l-20 MHz	No	19.999 080
SP705B	Common base	TTL- Special IC	11.14	l-10 MHz	No	1.000 000
SP705B	Common base	TTL- Special IC	11.14	l-10 MHz	No	9.998 560
12060	Common base	ECL- Special IC	11.15	100 <b>kHz-2</b> MHz	No	0.100 003
12060	Common base	ECL- Special IC	11.15	100 <b>kHz-2</b> MHz	No	1.999 428
12061	Common base	ECL- Special IC	11.15	2-20 MHz	No	2.000 000
12061	Common base	ECL- Special IC	11.15	2-20 MHz	No	19.992 953
LM375	Series res- onance	Linear- special IC	11.16a	100 <b>kHz–</b> 10 MHz	No	0.500 073
LM375	Series res-	Linear- special	11.16b	100 <b>kHz-</b> 10 MHz	Yes	10.000 338
SL680C	Emitter coupled	Linear- special IC	11.17a	2-20 MHz	No	1.999 986
SL680C	Emitter coupled	Linear- special IC	11.17a	2-20 MHz	No	19.999 001

TABLE 12.2 (continued)

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		Measured	Performance			
Waveforms at Crystal	Square Wave on/off Times (µsec; should he equal)	P.S. Sensitivity $(\Delta V_{cc} = 2 \text{ V})$ $\Delta f \text{ (ppm)}$	Circuit Sen Freeze $\Delta f$ (ppm)	Temperature sitivity Heat $\Delta f$ (ppm)	Overall Perfor- mance	Remarks
Good	0.026/0.024	2.			Good	High parts count
Very good	0.48/0.52	1.	+0.7	- 2 .	Good	Low parts count
Very good	0.052/0.048	1.	- 3 .	- 4 .	Good	Low parts count
Poor	0.46/0.54	4.	+1.	- 2 .	Poor	
Poor	—	102.	_		Poor	
Poor	1.0/1.0	0.2	-0.2	-1.	Fair	
Poor	_	47.	_	_	Poor	
Poor	4.4/5.6	0.	0.	-1.	Poor	
Poor	0.22/0.28	10.	t 180.	-150.	Poor	
Poor	0.23/0.27	0.2	+0.1	-0.2	Poor	
Poor	0.018/0.032	14.	+ 11.	-28.	Poor	
Good	0.95/1.05	0.2	-0.4	+2.	Good	
Very good	0.056/0.044	2.	_		Fair	
Very good		0.0	- 2 .	- 2 .	Good"	Sine wave output
Very good	—	3.	-1.	-12.	Fair <sup>a</sup>	Sine wave output

<sup>a</sup> Data at +6 VDC

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very good, and its frequency is relatively insensitive to power supply and temperature changes. The 9615 has a low parts count and an upper frequency limit of 2 MHz. The performance of the 8820 is below average. Crystal waveforms are only fair, its frequency is sensitive to temperature changes, and the crystal's load resistance has to be relatively high, reducing its short-term frequency stability. Its upper frequency limit is 1 MHz.

All three of the ECL receivers (10114, 10116, and 10216 in Figs. 11.7*a* and c) give above average performance as series-resonant circuits. Crystal waveforms are very good, and the frequency is relatively independent of power supply and temperature changes. The crystal's source and load resistances are low, giving good short-term frequency stability. The upper frequency limit is at least 20 MHz. One drawback for TTL use is that they need a buffer to convert the oscillators' ECL output to the TTL format.

## 12.4. PIERCE OSCILLATORS USING ICs

Pierce-IC oscillators give above average to average performance. The measured performance of a test circuit of each type is listed in Table 12.2. The data were obtained from the circuits in Figs. 11.8-11.10. The performance of Pierce-IC oscillators is summarized in the following paragraphs.

The Pierce-CMOS inverter circuit (74C04 in Fig. 11.8) gives average performance. Crystal waveforms are good, and the oscillation frequency is reasonably independent of power supply and temperature changes. Maximum frequency for the Pierce-CMOS circuit is about 1 MHz for most manufacturers' CMOS (B series), 2 MHz for National Semiconductor's 74C series, and 5 MHz for Solid State Scientific's 4000A/B series CMOS.

The Pierce-TTL circuit (Fig. 11.9) uses an LM319 voltage comparator and gives above average performance. Crystal waveforms are good, and the oscillation frequency is reasonably independent of power supply and temperature changes. A voltage comparator is the only TTL circuit that has enough gain to make a Pierce oscillator. Maximum frequency for the voltage comparator circuit is about 2 MHz. Although Pierce circuits normally operate at 5-40 ppm above series resonance, the oscillation frequency in the test circuit was only 1 ppm above series resonance, due to the large 60-nsec time delay in the voltage comparator.

Pierce-ECL circuits (10114, 10116, and 10216 in Figs. 11. 10a and c) give above average performance at 1 MHz and average performance at 20 MHz. Crystal waveforms are good at both frequencies, and at 1 MHz, the frequency is almost completely independent of power supply and temperature changes. The three receivers in a DIP are connected in series to get enough gain for the Pierce circuit. The 10114 is used at 1 MHz and the 10116 or 10216 at

#### SPECIAL OSCILLATOR ICs

20 MHz. When used to drive TTL circuitry, the parts count is relatively high. This is due to the large number of emitter pull-down resistors used in the circuit and the ECL-to-TTL interface circuit that is needed at the output.

## 12.5. SPECIAL OSCILLATOR ICs

As a group, ICs that are specifically designed for use as crystal oscillator circuits do not perform very well when compared with discrete transistor circuits. The special oscillator ICs generally try to cover a wide range of frequencies with a fixed circuit, and this is very difficult to do. As a rule, 'the ICs work best at the low end of their frequency range and poorest at the high end. Many of them drive the crystal with a badly distorted waveform. Their general performance ranges from average to poor. Special oscillator ICs can usually provide reasonable source and load resistances for the crystal at the low-frequency end of their range, but source and load resistances are invariably too high for high-frequency operation, and, hence, their short-term stability is not too good at the higher frequencies. To maintain a perspective, poor does not mean unacceptable. The label poor performance here is with respect to what can be done with discrete transistor circuits. Even the poorest crystal oscillator circuit will provide a more stable frequency source than an LC-type oscillator circuit.

The measured performance of a test circuit of each type is listed in Table 12.2. The data were taken from the circuits shown in Figs. 11.12-11.17. The performance of the special oscillator **ICs** is summarized in the following paragraphs.

The 7209 (CMOS) uses the Pierce circuit and operates from at least 4 kHz up to 10 MHz. It gives good performance at 1 MHz and 10 MHz. Crystal waveforms are very good, and the frequency is reasonably independent of power supply and temperature changes. And as with any Pierce circuit, capacitors  $C_1$  and  $C_2$  in the circuit should be changed when the frequency is changed.

The 74LS321 (TTL) uses a variation of the common base amplifier circuit and operates from l-20 MHz. Performance is poor at 1 MHz and 20 MHz. The circuit has two main drawbacks. The waveform driving the crystal is poor, and an inductor is used in the circuit when it is not necessary (from a design viewpoint). The frequency is reasonably independent of power supply and temperature changes at 1 MHz. At 20 MHz, the frequency drifts 1 ppm short term and changes a large 102 ppm when the power-supply voltage changes from 4 to 6 V.

The SP705B (TTL) uses the common base amplifier circuit and operates from l-10 MHz. It gives fair performance at 1 MHz but is poor at 10 MHz.

Crystal waveforms are distorted. At 1 MHz, the frequency is relatively independent of power supply and temperature changes, but at 10 MHz, the frequency changes a large 47 ppm when the power supply voltage is changed from 4 to 6 V.

Both the 12060 and the 12061 (ECL) use a variation of the common base amplifier circuit, and cover frequency ranges of 100 kHz-2 MHz and 2-20 MHz, respectively. Sine wave, ECL, and TTL outputs are provided. The performance of the 12060 is poor at both 100 kHz and 2 MHz. Crystal waveforms are distorted. The frequency is relatively independent of power supply and temperature changes at 100 kHz, but changes a large 150-180 ppm with temperature at 2 MHz. The performance of the 12061 is poor at both 2 and 20 MHz. Crystal waveforms are distorted. At 2 MHz, its frequency is relatively independent of power supply and temperature changes. But at 20 MHz, it is sensitive to power supply and temperature changes, changing 14 ppm when the power supply is changed from 4 to 6 V and changing 28 ppm when heated above ambient.

The LM375 (LINEAR) uses the series-resonant circuit and can be used over a frequency range of 100 kHz–10 MHz. Above 500 kHz, a tuned LC tank is required for the oscillator load. The LM375 has both sine wave and TTL outputs, and gives good performance at and below 500 kHz with a resistive oscillator load. Crystal waveforms are good, and the frequency is relatively independent of power supply and temperature changes. Above 500 kHz, the LM375's performance is only fair, because of the unnecessary use (from a design viewpoint) of an LC tank and because it oscillates spuriously with the crystal removed from the circuit.

The **SL680C** (LINEAR) uses the emitter coupled circuit and operates at frequencies from 2-20 MHz. The **SL680C** has a sine wave output only. It is designed for a power supply voltage of + 6 to + 10 VDC but will operate at +5 V if a clipped sine wave output is acceptable. The **SL680C's** performance is good at 2 MHz and fair at 20 MHz. The crystal's waveform is a nice sine wave. At 2 MHz, its frequency is relatively independent of power supply and temperature changes. But at 20 MHz, the frequency is sensitive to temperature, changing 12 ppm when the IC is heated above ambient.

## **12.6. BRIDGE OSCILLATORS**

All of the discrete transistor bridge circuits give outstanding performance, as shown in Table 12.3. They all operate at or near series resonance, depending on the tuning of their LC tanks. The oscillation frequencies are all relatively insensitive to power supply changes.

The short term stability of all the bridges is equal to or better than the 0.1 ppm limit of measurement. The electronic improvement in in-circuit Q is experimentally shown by temporarily decreasing the in-circuit Q of a Feedback bridge oscillator (Appendix C) by 10X, so that its electronic improvement (3X) in in-circuit Q could be seen with the measurement equipment available. The temporary 10X reduction in in-circuit Q was obtained by adding nine times more resistance in series with the crystal.

In the Modified Meacham circuit (Figs. 10.13a, c, & d), the crystal waveforms are fair to good. The maximum gain obtained in a stable two- or threestage transistor amplifier varied from 28-100X, considerably less than the 300-422X obtained by Clapp and Meacham in their original circuits using a pentode vacuum tube amplifier.

The Modified Meacham circuit gives bridge arm resistance ratios  $(2R_2/R_s)$  of 1.4 to 2.4, depending on frequency. A resistance ratio of 1.0 indicates a crystal with all of its internal losses cancelled out, equivalent to an unobtainable infinite Q. These resistance ratios are converted to in-circuit Q improvement ratios by (ratio)/(ratio-1), giving electronic Q improvement factors of 1.7X to 3.5X.

The in-circuit Q can be calculated from the crystal's source resistance  $R_o$  and load resistance  $R_{load}$ , that add to the crystal's internal resistance  $R_s$  and decrease the crystal's internal Q by  $R_s/(R_s + R_o + R_{load})$ . This in-circuit Q (without electronic Q improvement) is then multiplied by the electronic Q improvement fadtor. For the Modified Meacham at 1 MHz (Fig. 10.13a), the source resistance  $R_o$  driving the crystal is 8 ohms and the load resistance  $R_{load}$  is approximately 290 + 51/2 or 315 ohms. This gives an in-circuit Q without electronic improvement of 240/(240 + 8 + 315) or .43 times the crystal's inter&l Q. The bridge resistance ratio is  $2R_2/R_s = 2(290)/240 = 2.4$ . The electronic Q improvement factor is ratio/(ratio -1) = 2.4/(2.4 -1) or 1.7. Multiplying the unimproved in-circuit Q by the electronic Q improvement factor gives the actual in-circuit Q of .43 x 1.7 or 0.7 times the crystal's internal Q (at 1 MHz).

Repeating the above calculation procedure, the Modified Meacham's incircuit Q is 0.9 times the crystal's internal Q at 100 kHz, and 1.5 times at 10 MHz. The in-circuit Q at 100 kHz and 1 MHz is low for a bridge circuit, and is due to the crystal's load resistor ( $R_2$ ) being too large. The in-circuit Q can be raised about 50% by increasing the bridge's voltage excitation ratio from the existing 2-to-1 up to 6-to-1 or so. This is done by changing the ratio of the emitter to collector resistances of transistor  $Q_1$ , which provides 180" phase inversion and drives the bridge. The crystal's load resistor (R,) will decrease proportionately with the bridge's voltage excitation ratio, thereby increasing the in-circuit Q and the short term stability.

Circuit	Schematic in Figure	Useful Frequency Range	<u>Measured</u> Does Circuit Oscillate Without Crystal?	Performance Frequency of Oscillation (MHz)
Feedback	c.2	100 kHz-10 MHz	No	1.000 000
Modified Meacham Modified Meacham Modified Meacham RLC Half-Bridge RLC Half-Bridge RLC Half-Bridge Meacham-ECL	lo. 13d 10. 13a 10. 13c A.4 A.3 A.5 11. 11a	1 kHz-20 MHz 1 kHz-20 MHz 1 kHz-20 MHz 1 kHz-10 MHz 1 kHz-10 MHz 1 kHz-10 MHz 1 kHz-10 MHz 100 kHz-20 MHz	No No No No No	0.100         002           1.000         000           10.000         019           0.100         002           0.999         993           10.000         121           10.000         055

 TABLE 12.3
 Performance of Bridge Oscillator Circuits

In the RLC half-bridge circuit (Figs. A.3, A.4, & A.5) the crystal is driven with a square wave, as compared to the sine wave drive in the Modified Meacham, but that had no apparent effect on performance, as both circuits give the same very good performance. The RLC half-bridge gives resistance ratios  $(2R_1/R_s)$  of 1.4 to 2.6, depending on frequency. These are converted to in-circuit Q improvement ratios by (ratio)/(ratio – 1), giving an electronic Q improvement factor of 1.6X to 3.5X. Crystal waveforms are good to very good.

Using the same calculation procedure as used previously for the Modified Meacham, the in-circuit Q of the RLC half-bridge is 1.5 times the crystal's internal Q at 100 kHz, 1.9 times at 1 MHz, and 0.6 times at 10 MHz. The high in-circuit Qs at 100 kHz and 1 MHz should provide extremely good short term stability. The in-circuit Q at 10 MHz is low for a bridge, because of low amplifier gain (17X). The low in-circuit Q can be increased about 50% by using the same technique proposed above for the Modified Meacham, which is to increase the bridge's voltage excitation ratio to 6-to-1 or so. This is done by increasing the ratio of the emitter resistance to the collector resistance in the transistor phase inverter driving the bride. Increasing the voltage excitation ratio will reduce the crystal's load resistor ( $R_1$ ), and raise the in-circuit Q and the short term stability.

In the Feedback bridge circuit (Fig. C.2) the crystal waveforms are good. The negative feedback through bridge arms  $R_1$  and  $R_2$  gives an electronic Q improvement factor of 2.8X. The in-circuit Q is high, at 1.9 times the crystal's internal Q. The Feedback bridge has only three fourths the number of component parts that the Modified Meacham and RLC half-bridge have, a prac-

		Measured	Performance		
Waveforms at Crystal	P. s. Sensitivity $(\Delta V_{c\epsilon} = 2V)$ $\Delta f (ppm)$	Electronic Improvement in In-circuit Q	Crystal In-circuit Q (x crystal's internal Q)	Overall Perform- ance	Remarks
Good	1.	2.8X	1.9	Very good	Simplest bridge, high Q
Good	1.	1.9x	.9	Very good	-
Good	0.1	1.7x	.7	Very good	
Fair	1.	3.5x	1.5	Very good	
Good	0.4	1.9x	1.5	Very good	
Very good	0.0	3.5x	1.9	Very good	High Q
Good	1.2	1.6X	.6	Very good	0
Fair	4.	2.6X	.6	Good	

tical advantage. On the negative side, its amplifier (21X) gain is less than that of the modified Meacham (28X) or the RLC half-bridge (50X) at 1 MHz, so its short term frequency stability should also be less.

The Meacham-IC bridge is discussed in the next section.

## 12.7. BRIDGE OSCILLATOR USING AN IC

The Meacham-ECL circuit (Fig. 11. lla) is a full-bridge circuit giving above average performance. The ECL output stage has a difficult task driving the low resistance  $R_s$  (5 ohms) of the crystal at 10 MHz, and this results in only fair waveforms at the crystal and increases the frequency sensitivity to power supply changes. Both crystal waveform and power supply sensitivity would improve at frequencies lower than 10 MHz, where the crystal's internal series resistance A, would be higher and easier to drive.

The crystal has a 5 ohm source resistance R, and a load resistance  $R_{\text{load}}$  of (8.2 + 5) or 13.2 ohms. The crystal's in-circuit Q without improvement by the bridge's negative feedback is  $R_s/(R_s + R_{,,} + R_{\text{load}}) = 5/(5 + 5 + 13.2)$  or .22 of the crystal's internal Q. The bridge's negative feedback reduces resistive losses in the crystal's bridge arms, and improves the in-circuit Q by means of the bridge's resistance ratio  $R_2/R_s$  (= 1.64) by (ratio)/(ratio - 1) = 1.64/(1.64 - 1) = 2.6. The in-circuit Q with negative feedback is then .22 x 2.6 or 0.6 times the crystal's internal Q. This is a relatively low in-circuit Q for a bridge circuit, due to the source and load resistances being too high for the crystal's low internal series resistance  $R_s$  (5 ohms) at

10 MHz. In spite of the low in-circuit Q, the short term stability measured 0.1 ppm. Performance data on the circuit is listed in Table 12.3.

The modified Meacham-ECL half-bridge (Fig. 11.11c) performs just as well as the full-bridge circuit. But since the full-bridge circuit uses only one more resistor and can cancel out drive-source variations, it has an advantage over the half-bridge circuit.

## 12.8. HARMONIC OSCILLATORS

Performance of the harmonic circuits ranges from outstanding to below average, and is summarized in the following paragraphs. Measured data on the circuits is listed in Table 12.4.

The Butler common base circuit (Figs. 10.15-10.19) gives below average performance. Crystal waveforms are good, but its frequency stability to power supply and temperature changes is only fair. The collector current must be held at a certain fixed value or the circuit will not oscillate. The circuit has a nasty parasitic oscillation problem if a capacitive tap is used on the LC tank, but it goes away if an inductive tap is used. With a capacitive tap, the circuit operates slightly above or at series resonance. With an inductive tap, the circuit operates slightly below series resonance.

The Butler emitter follower circuit (Figs. 10.20-10.24) gives above average performance. Crystal waveforms are good, and there are no **parasitics** of any kind. Its frequency is reasonably independent of power supply changes, but it does vary some with temperature changes. The circuit is easy to set up and tune. The inductive tap does not offer any advantage over a capacitive tap in this circuit. With a capacitive tap, the circuit operates slightly above or at series resonance. With an inductive tap, the circuit operates slightly below resonance. An ECL line receiver (10216 in Fig. 11.18) can be used for the amplifier in the Butler emitter follower circuit, and will give essentially the same performance as a discrete transistor amplifier.

Starting above 70 MHz or so, where an inductor must be put across the crystal to tune out the capacitive effect of the crystal's terminal capacitance C,,, the capacitive tap is easier to work with than the inductive tap. With the inductive tap, the crystal's shunt inductor introduces an inconvenient DC circuit connection which has to be broken by adding a series capacitor. Adding a series capacitor at these high frequencies is undesirable because the capacitor's leads add inductance to the circuit.

The Pierce harmonic circuit (Fig. 10.25), using a resonant LC tank in its amplifier, gives above average performance at 100 MHz. Crystal waveforms are very good, and the frequency is relatively insensitive to power supply voltage changes. The circuit's short-term frequency stability is very good. A drawback to this circuit is its high parts count.
The Colpitts harmonic circuit (Fig. 10.14), using an inductor for the emitter load, gives average performance at 20 MHz. Crystal waveform is good, but the frequency is somewhat sensitive to power supply changes. The circuit has a low parts count, a practical advantage.

The Emitter coupled harmonic circuit (Figs. B.2, B.6 & B.7) gives outstanding performance at 20 MHz to 100 MHz. Its short term stability of 0.1 ppm is better than that of any other harmonic circuit. The crystal waveform is good to very good, and the frequency is relatively insensitive to power supply voltage changes. 100 MHz is the circuit's upper frequency limit, because the transistor's collector load resistance has to increase with frequency to maintain a fixed stage gain. This conflicts with the need to reduce the same load resistance as the frequency increases, because of stray shunt capacitance effects.

### 12.9. WHICH IS THE BEST CIRCUIT?

Which is the best circuit? Among the fundamental circuits, there are two that stand out above the rest: the discrete transistor bridge circuits (as a group), and the Pierce circuit. The discrete transistor bridge circuits appear to have the best short term stability of any circuit type, due to their ability to electronically increase the crystal's in-circuit Q by subtracting out part of the resistive losses in the crystal's bridge arm (or arms).

The Modified Meacham's in-circuit Q is 0.7 to 1.5 times the crystal's internal Q, depending on frequency. The RLC half-bridge's in-circuit Q is 0.6 to 1.9 times the crystal's internal Q, depending on frequency. The incircuit Q of these two bridge types can be increased about 50% by raising the bridge voltage excitation ratio, as described in section 12.6. And the Feedback bridge's in-circuit Q is 1.9 times the crystal's internal Q.

Contrast these in-circuit Qs with those of non-bridge circuits, which are only 0.1 to 0.8 times the crystal's internal Q. The Meacham-ECL bridge, which uses an IC amplifier at 10 MHz, has a relatively low in-circuit Q of 0.6 times the crystal's internal Q. It's in-circuit Q will improve at lower frequencies, where the crystal's internal resistance  $R_s$  will be higher than the 5 ohm output resistance of the ECL amplifier driving the crystal. Below 5 MHz the Meacham-ECL's in-circuit Q will double to about 1.2 times the crystal's internal Q, a much better value for a bridge circuit.

The electronic Q improvement factor in the various bridge circuits varies from 1.6X to 3.5X. If desired, this Q improvement factor can be made larger by increasing the circuits' amplifier gain.

Experimentally, the bridges' short term stability measured 0.1 ppm, at the limit of the available measuring equipment. The Feedback bridge's stability measured 0.1 ppm without its electronic Q improvement factor, in-

				Measured	Performance
Circuit	Туре	Schematic in Figure	Useful Frequency Range	Harmonie	Does Circuit Oscillate Without c Crystal?
Colpitts	Discrete	10.14	200 kHz-100	3rd	No
Butler common base, C-tap	transistor Discrete transistor	10.15	MHz 15-100 MHz	3rd	No
Butler common	Discrete	10.16	15-50 MHz	3rd	No
base, L-tap Butler common base	transistor Discrete transistor	10.17	15-100 MHz	3rd	No
Butler common	Discrete	10.18	15-100 MHz	5th	N o
base, C-tap Butler common base, L-tap	transistor Discrete transistor	10.19	70-200 MHz	5th	-
Butler emitter follower, C-tap	Discrete transistor	10.20	15-200 MHz	3rd	No
Butler emitter follower, L-tap	Discrete transistor	10.21	15-200 MHz	3rd	No
Butler emitter	Discrete	10.22	15-200 MHz	3rd	No
Butler emitter follower, C-tap	Discrete transistor	10.23	15-200 MHz	5th	No
Butler emitter follower,	Discrete transistor	10.24	70-200 MHz	5th	-
Butler emitter	ECL	11.18	15-100 MHz	5th	No
Pierce	(10216) Discrete transistor	10.25	20-100 MHz	5th	No
Emitter	Discrete	B.2	I-100 MHz	3rd	No
Emitter	Discrete	B.6	I-100 MHz	3rd	No
Coupled Emitter Coupled	transistor Discrete transistor	B.7	l-100 MHz	5th	No

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			Measured P	erformance			
Frequer	юу	<b>11</b> 7 C	P.S.	Circuit Sen	Temperatur sitivity	e	-
o f Oscillati (MHz)	on	at Crystal	$\Delta f \text{ (ppm)}$	<sup>7</sup> ) Freeze Δf (ppm)	Heat $\Delta f$ (ppm)	Overall Performance	Remarks
20.000	706	Good	6.	- 4 .	+1.	Fair	
20.000	022	Good	3.	-0.1	- 4 .	Poor-fair	Parasitics
19.999	918	Fair	0.3	+0.3	- 4 .	Fair	
50.000	306	Good	0.5	-		Poor-fair	Parasitics
100.0012	281	Good	0.3		-	Poor-fair	Parasitics
100.000	937	Good	0.5	-	-	Poor	Not recom-
20.000	051	Very good	0.3	+0.6	- 4 .	Very good	mended Recom- mended
19.999	958 \	Very good	0.4	+0.8	- 3 .	Very good	Recom- mended
50.000	042	Good	2.			Very good	Recom-
100.0015	513	Good	2.	—	-	Very good	Recom- mended
99.996	603	Good	5.	—		Poor	Not recom-
100.000	847	Good	2.	-3.	- 3 .	Good	mended
99.999	171	Good	2.	_		Good	
20.000	038	Good	0.1			Very good	Recom-
49.999	500	Good	2.			Very good	mended Recom-
100.000	527	Good	2.1	_	-	Very good	mended Recom- mended

**dicating** its stability would be even better with it connected into the circuit. On the negative side, bridge circuits of any type are much more complex than other types of oscillator circuits, are more difficult to design, and have high parts counts.

Among the various bridge circuits, the RLC half-bridge should be the best circuit with the best performance. Its untuned amplifier and simpler half-bridge configuration make it easier to design than the Meacham. And its amplifier gain is higher than the Feedback bridge's, which should give it better short term stability. The Feedback bridge performs almost as well as the RLC half-bridge. It has less amplifier gain, so its short term stability should also be less. Its parts count is only three fourths that of the RLC halfbridge, a practical advantage. The word "should" rather than "will" is used here because such stability performance is beyond the measuring equipment available, and hasn't been verified.

Among the non-bridge fundamental circuits, the Pierce stands out on almost every count. It has good waveforms at the crystal, a frequency that is relatively independent of power supply and temperature changes, very good short-term frequency stability, high output voltage, low crystal dissipation, low cost, and it is usable at any frequency from the highest to the lowest. The only disadvantage of the Pierce is that its frequency stability appears to be less than that of the bridge circuits.

Above 20 MHz, where harmonic circuits are used, the Emitter coupled harmonic is the best circuit up to 100 MHz, and the Butler emitter follower is the best one above 100 MHz. The Emitter coupled harmonic is relatively independent of power supply changes, its crystal waveform is good, and it has the best short term stability of any of the harmonic circuits. Its upper frequency limit is 100 MHz. The Pierce harmonic circuit also works well as a harmonic oscillator, but it has a relatively high parts count.

Above 100 MHz, the very broad and flat frequency response of an emitter follower, due to its built-in feedback, makes the Butler emitter follower the best circuit at these frequencies. It is a simple low cost circuit, with good waveforms at the crystal. It has no **parasitics**, and its frequency is relatively immune to power supply changes.

Table 12.5 lists the relative performance of various circuit types. All of the bridge circuits, the Pierce, and the Emitter coupled harmonic are in the outstanding group, for the reasons just given.

In the above average group are the Butler emitter follower (harmonic), Pierce harmonic, common base amplifier (discrete transistors), and **series**resonant-ECL circuits. All of these circuits perform very well, with good frequency stability and very good waveforms at the crystal.

In the average group are the emitter coupled, Colpitts, Colpitts harmonic, TTL two-inverters, and low capacitance load circuits.

### WHICH IS THE BEST CIRCUIT?

Relative Performance	Fundamental Circuits	Harmonic Circuits Emitter coupled harmonic		
Outstanding	RLC half-bridge Feedback bridge Modified Meacham Pierce			
Above average	Common base amplifier- discrete transistors Series-resonant-ECL	Butler emitter follower Pierce harmonic		
Average	Emitter coupled Colpitts TTL two-inverters Low capacitance load	Colpitts harmonic		
Below average	High-resistance load CMOS two-invertera	Butler common base		
Poor	Special oscillator ICs Miller	Special oscillator ICs		

#### TABLE 12.5 Relative Performance of Circuit Types

In the below average group are the high resistance load, Butler common base (harmonic), and CMOS two-inverters circuits. The high resistance load circuit has the disadvantage of an oscillation frequency way above series resonance. The Butler common base (harmonic) circuit suffers from bad parasitics. And the CMOS two-inverters circuit has the disadvantage that its frequency is too sensitive to power supply changes.

In the poor performance group are the special oscillator ICs and the Miller circuit. The special oscillator ICs actually fall into more than one group, but the majority of them fall into the poor performance group because of poor crystal waveforms and a frequency that is too sensitive to power supply and temperature changes. The Miller circuit has bad crystal waveforms and an unstable frequency. To maintain perspective, labeling the performance of one circuit as poor with respect to another circuit is a relative matter. In this case, it means poor with respect to what can be done with a discrete transistor circuit. It is worth repeating that even the poorest crystal oscillator circuit.

# OPTIMIZING THE OSCILLATOR CIRCUIT

This chapter describes how to select an oscillator circuit for a particular application. It also summarizes the most important oscillator design characteristics to aid those who would like to design their own oscillator circuits.

### **13.1. SELECTING A CIRCUIT**

What circuit should be selected depends on the application. If the best short-term stability without regard to other circuit characteristics is needed, then the modified Meacham circuit is the best choice. But it will be necessary to put up with the Meacham's drawbacks of circuit complexity, the difficulty of designing a stable circuit, and a high parts count. (An alternative circuit that is easier to design and gives performance equal to the modified Meacham is the RLC half-bridge, which is described in the Appendix.) If very good short-term stability is required, but other circuit characteristics such as simplicity and ease of design are also important, then the Pierce is a good choice. The Pierce can be used at any frequency from the highest to the lowest, fundamental or harmonic, as shown by the assortment of Pierce schematics in this book.

Or, if harmonic operation above 20 MHz, with above average performance and reasonably few parts is needed, the Butler emitter follower circuit is the one to pick. If the bare minimum number of parts is a requisite and performance requirements can be relaxed a little, then the **Col**pitts, either fundamental or harmonic, is the one to pick,

A discrete transistor circuit will usually give better performance than an IC circuit. This is because it is easier to control the crystal's source and load resistances, the gain, and signal amplitude in a discrete transistor circuit. The discrete transistor amplifier usually has less time delay in it, as well, since it normally has only one or two transistors.

On the other hand, oscillators using **ICs** are frequently cheaper when assembly labor costs are included. They also interface more easily with digital circuitry. And although their performance is generally less than that of a discrete transistor circuit, it is still better than what is needed for many types of digital circuitry.

In CMOS, the Pierce inverter circuit works well over the 1  $\rm kHz-2$  MHz frequency range and requires only two inverters. From 4  $\rm kHz-10$  MHz, the 7209 special oscillator IC, which also uses the Pierce inverter circuit, can be used..

In TTL below 3 MHz, the series-resonant two-inverters circuit gives good performance over the 100  $\rm kHz-3$  MHz frequency range as long as the circuit's spurious oscillation problem with the crystal out of the circuit can be tolerated. In TTL above 3 MHz, either the series-resonant circuit using an ECL line receiver or the Pierce-ECL circuit would be a good choice. A TTL buffer circuit similar to those shown in the oscillator schematics is required for these above-3 MHz circuits.

In ECL below 20 MHz, the series-resonant line receiver circuit or the Pierce-ECL circuit would be a good selection, covering a frequency range of 100  $\rm kHz{-}20$  MHz. In ECL above 20 MHz, the Butler emitter follower circuit (harmonic) using the 10216 line receiver would be a good circuit to use.

#### **13.2. CIRCUIT DESIGN**

The design of a crystal oscillator circuit is dominated by the crystal's internal series resistance  $R_s$ , far more than by any other factor. For a typical quartz crystal in a gas-filled container, the crystal's internal series resistance varies from a high of 200K  $\Omega$  at 1 kHz to a low of 10  $\Omega$  at 20 MHz. For the best short-term frequency stability, the equivalent series load resistance seen by the crystal should be equal to or somewhat less than the crystal's internal series resistance  $R_s$ . To meet this crystal need, the circuit's impedance level has to vary over a wide range-high impedance at low frequencies, and low impedance at high frequencies. It is this characteristic that leads to such a wide variety of circuits over the frequency range.

In calculating the crystal's load, the crystal's shunt terminal capaci-

#### CIRCUIT DESIGN

tance  $C_0$  of about 5 pF should be included as part of that load rather than as part of the frequency determining  $L_x$  and  $C_x$  elements in the crystal. Since the terminal capacitance  $C_0$  is in parallel with the actual load resistance (or capacitance), a parallel-to-series network conversion is performed to find the equivalent series load resistance that is to be minimized. Good in-circuit Q can be obtained with either a high or low value of parallel load resistance across the crystal terminals. For the best Q, this parallel load resistance should be two to three orders of magnitude greater than or less than the impedance of the total shunt capacitance across the crystal terminals. Figure 6.4 shows graphically these minimum and maximum parallel load resistances that will give good incircuit Q as a function of frequency. The graph in Fig. 6.4 assumes that the crystal's total shunt capacitance is just the shunt capacitance  $C_0$  of the crystal itself (about 5 pF), which is the usual case.

The oscillator circuit should contain some means of ensuring that the amplifier is biased "on" at startup and is not in a biased "off" state, which would prevent oscillation from starting when power is applied. This is an essential element in any good oscillator circuit.

If the crystal is removed from the circuit or becomes defective, the circuit should not oscillate. Some circuits, like the TTL two-inverters circuit, continue to oscillate (spuriously) when the crystal is removed; this is poor design.

In general, the time delay in the oscillator's amplifier should be minimized, since it causes frequency shifts when the amplifier's temperature changes. The greater the amplifier's time delay as a percentage of the period of oscillation, the greater the frequency shifts with temperature changes. The square wave driving the crystal should be a good square wave, with a 50/50 on-off ratio and a rise time that is not too slow or too fast. The amplifier's frequency response and rise time should not be way beyond the oscillation frequency either. If they are, then multiple on-off switchings due to noise will occur in the amplifier at each zero crossing of the sine wave out of the crystal. A desirable delay and rise and fall time seems to be about 2 percent of the total period of oscillation.

It is worth repeating that both sine and square wave outputs are available from most oscillator circuits. The square wave is on the driving side of the crystal, and the sine wave is on the output side.

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# APPENDIXA

# RLC HALF-BRIDGE CIRCUIT

This circuit is a late improvement on the already outstanding modified Meacham, and since it performs equally well, it is included here as an Appendix.

The modified Meacham circuit described in Section 5.11 gives outstanding performance, but it is very difficult to design. Its design can be made easier by moving the amplifier's LC network over to the resistive arm of the half-bridge. All the frequency controlling elements are then in the bridge arms, and the amplifier can have a flat frequency response. A wide range of noninverting amplifier designs can be used with this new circuit arrangement.

A simplified schematic of the RLC half-bridge circuit is shown in Fig. A.l. The two bridge arms are driven out-of-phase, with the transistor operating as a split-load phase inverter. The operation of the bridge is described in detail in Sections 5.11 and 7.5, but in essence the **out-of**-phase signal through the resistive bridge arm  $R_1$  cancels out part of the crystal's internal resistance  $R_s$ . This effectively increases the crystal's in-circuit Q, which in turn increases the short-term frequency stability. And the higher the amplifier's gain, the more the crystal's in-circuit Q can be increased.

Figure A.2 shows the gain and phase shift characteristics of the halfbridge in the RLC half-bridge circuit.  $L_1$  and  $C_1$  are series resonant at the crystal's fundamental frequency. The overall broad peak of the gain curve is due to the series resonance of  $L_1$  and  $C_2$ , and the sharp "hole" or slot at the peak is due to the crystal's series resonance. The phase shift through the bridge changes from  $+270^{\circ}$  (lead) below the resonant frequency to  $-270^{\circ}$  (lag) above resonance.

The design of the RLC half-bridg e circuit is as follows. In Fig. A.1,  $R_1$  has the smallest possible value that will still let the circuit oscillate, and



Figure A.1. Simplified RLC half-bridge circuit.

allow the maximum crystal in-circuit Q to be obtained (the circuit will not oscillate if  $\mathbf{R}$ , is less than  $R_s$ , except spuriously). This requires the highest possible amplifier gain without the amplifier oscillating spuriously.  $C_1$  is tuned to resonance with  $L_1$  at the crystal's fundamental frequency.  $C_1$  can be varied slightly from its resonance value to trim the crystal's oscillation frequency.

A high  $L_1/C_1$  ratio is desirable. A low  $L_1/C_1$  ratio gives a broad frequency transmission band to the half-bridge, and the crystal then oscillates at its 3rd or 5th harmonic where the bridge gain is higher, rather than at its fundamental frequency. A high  $L_1/C_1$  ratio gives a narrow frequency transmission band, so that the bridge gain at the crystal's 3rd and



Figure A.2. Gain and phase characteristics of the half-bridge in Fig. A.1.

5th harmonics is too low for oscillation, and the crystal then has to oscillate at its fundamental frequency. The inductance  $L_1$  should be reasonably large, with its maximum value limited by its internal AC resistance. The internal AC resistance of  $L_1$  should be less than the crystal's internal resistance R, so as not to limit the maximum crystal Q obtainable in the circuit.

The bridge load resistance  $R_L$  in Fig. A.1 should not have too high a value.  $R_L$  should be about 2-10 times the crystal's internal series resistance R. If  $R_L$  is much larger than this, the circuit will not be stable when  $R_1$  is set less than  $R_s$  to check the amplifier's stability. And although it is not shown in Fig. A.l, a small capacitance equal to (or slightly greater than) the crystal's external terminal capacitance  $C_0$  is tied across the  $R_1L_1C_1$  bridge arm to balance out the crystal's terminal shunt capacitance  $C_0$ .

Figure A.3 shows a schematic of the RLC half-bridge at 1 MHz. The amplifier uses two transistors in an emitter coupled configuration, with an emitter follower at the output.  $Q_2$  provides a relatively high load resistance to the bridge at point A, so that the bridge load resistance  $R_L$  is primarily determined by the emitter biasing resistor  $R_2$ . Two diodes in parallel  $(D_1 - D_2)$  with reversed polarity provide an amplitude clamp to drive the crystal with a low-excitation, constant-amplitude signal. The amplifier has a gain of 50 X from point A to point B in Fig. A.3. The bridge operates with a 2 : 1 voltage excitation ratio between the two bridge arms. With a 2: 1 half-bridge, the theoretical minimum value for  $R_1$  is  $R_s/2$ , or 120  $\Omega$ . The effective value of  $R_1$  has to include the AC resistance of  $L_1$  (60  $\Omega$ ). This gives a ratio of the practical to theoretical minimum values for  $R_1$  of (110 + 60)/120 = 1.4, a desirably low ratio (1.0 is the unattainable minimum, corresponding to infinite Q).

The frequency changes 0.0 ppm when the power supply voltage is changed from 4 to 6 V, but this is dependent on the tuning of  $C_1$ . The short-term frequency stability measured 0.1 ppm, at the limit of the measuring equipment available. An oddity of the circuit is that  $C_2$  has to be greater than 17 pF, much more than the required bridge balancing value of  $2C_0$  (6 pF), to make the circuit stable and prevent spurious oscillation when  $R_1$  is set less than the minimum value for fundamental oscillation.

Figure A.4 shows a schematic of the RLC half-bridge at 100 kHz. This circuit is similar to the 1 MHz circuit in Fig. A.3. The frequency changes 0.4 ppm when the power supply voltage is changed from 4 to 6 V, but this is dependent on the tuning of  $C_1$ . The short-term frequency stability measured 0.1 ppm, at the limit of the measuring equipment available. The amplifier gain from point A to point *B* in Fig. A.4 is 57 X. The theoretical minimum value of  $R_1$  in this circuit is  $R_s/2$ , or 200  $\Omega$ . This



0.2 µsec/div

Figure A.3. RLC half-bridge at 1 MHz.

gives a ratio of the practical to theoretical minimum values for  $R_1$ , including the AC resistance of  $L_1$ , of (420 + 11)/200 = 2.1.  $R_3C_3$  prevents parasitic oscillation in the circuit.  $C_2$  has to be at least 19 pF, slightly greater than the required bridge balancing value of  $2C_0$  (16 pF), to make the circuit stable and prevent spurious oscillation when  $R_1$  is set less than the minimum value for fundamental oscillation.

Figure A.5 shows a schematic of the RLC half-bridge at 10 MHz. The



Figure A.4. RLC half-bridge at 100 kHz.

WAT TANKS





base input resistance of the **npn** phase inverter  $Q_1$  is very low and is best driven by an **npn** type of emitter follower. The emitter coupled amplifier  $Q_2$ - $Q_3$  uses pnp transistors, so that an npn transistor can be used for the emitter follower  $Q_4$ . The amplifier gain from point A to point B in Fig. A.5 is only 17× and is limited by the low gain of the high-frequency **pnp** transistors available and the loss in gain from  $C_3$ 's phase lead correction. The amplifier has a phase lag of 29°, which is compensated to zero by 29" of phase lead from  $C_3$ . The frequency changes 1.2 ppm when the power supply voltage is changed from 4 to 6 V. The short-term frequency stability measured 0.1 ppm, at the limit of the measuring equipment available. The theoretical minimum value of  $R_1$  in this circuit is  $R_s/2$ , or 2.5  $\Omega$ . This gives a ratio of the practical to theoretical minimum values for  $R_1$ , including the AC resistance of  $L_1$ , of (4 + 2.5)/2.5 = 2.6. A heat sink is required on  $Q_1$  in Fig. A.5.

The crystal waveforms vary from good to very good in the three circuits. All three circuits are stable and do not oscillate spuriously when the resistance  $R_1$  is set at 0  $\Omega$ , that is, at less than the minimum value for oscillation,  $R_s/2$ . The stability margin is somewhat small in the 100-kHz and 10-MHz circuits, but the test shows that the amplifier circuits are stable. In addition, the three circuits are stable and do not oscillate when the crystals are removed from the circuits. No temperature tests have been made on the circuits.

As can be seen from the above data, the RLC half-bridge gives the same outstanding performance as the modified Meacham. It does this with a reasonably simple "flat amplifier" design, compared to the much more difficult tuned amplifier circuit that's used in the modified Meacham. Adding  $L_1C_1$  to the bridge arm makes the half-bridge part of the circuit a little more complex, but the impact is not nearly as great as the elimination of the tuned amplifier. Because it gives the same performance with a simpler circuit, the RLC half-bridge is an improvement on the modified Meacham circuit.

# APPENDIXB

# EMITTER COUPLED HARMONIC CIRCUIT

Appendix B was originally published [21] in RF Design, Mar. 1987 0. With permission, Cardiff Publishing Co.

The Emitter coupled harmonic circuit has the best short term stability of any harmonic circuit tested by the author to date. Originally described by Driscoll [22], the circuit has been simplified and improved by eliminating a transistor stage and a transformer, and adding an RC phase lag network. The basic schematic of the improved Emitter coupled harmonic circuit is shown in Fig. B.I. It uses only one transistor, and operates at frequencies up to 100 MHz. The oscillator's output is a clean sine wave.

The crystal is connected as the transistor's emitter load impedance, and controls the oscillation frequency by controlling the transistor's gain and phase shift. The circuit's very good short term frequency stability comes from the high capacitance load shunted across the crystal by the transistor's emitter output, which keeps the crystal's in-circuit Q high. The large capacitive loading on the crystal means the resistive loading losses that reduce in-circuit Q will be low. In addition, the crystal has direct emitter control of the transistor's gain. This is almost an optimum crystal oscillator **circuit**—the crystal is located at the lowest power point in the circuit (minimum crystal heating), and the output signal is taken at the highest amplitude point in the circuit (maximum signal/noise ratio and minimum external amplification).



Figure B. 1. Basic circuit of Emitter coupled harmonic oscillator.

### B.I. HOW IT OPERATES

The basic circuit is shown in Fig. B. 1. It has positive feedback and oscillates at a frequency of 0" (or **360**") phase shift, presuming the loop gain is greater than one. The  $L_1C_1$  network normally operates just above resonance, and provides about 120° of phase lag. The  $R_2C_2$  network provides an additional phase lag of about 60". The transistor provides 180" of phase reversal, giving a total of 0" (or **360**") around the circuit's feedback loop.

The inductor  $L_2$  can be any value larger (2X - 20X) than what will resonate with the crystal's terminal-to-terminal capacitance  $C_o$ . The purpose of  $L_2$  in the circuit is not understood, but the circuit will not oscillate if  $L_2$  is equal to or less than this resonance value. The circuit also will not oscillate if a resistor is substituted for inductor  $L_2$ .

In practice, the crystal's internal impedance, which is lowest at series resonance, controls the transistor gain. It can also vary the normal 180" phase shift through the transistor stage by  $\pm 50^{\circ}$ . The crystal uses these gain and phase shift mechanisms to control the oscillation frequency.

### **B.2.** TYPICAL CIRCUITS

A typical circuit at 20 MHz is shown in Fig. B.2. The crystal, which has an internal series resistance  $R_s$  of 14 ohms, oscillates at a third harmonic. The diode clamp  $D_1 - D_2$  limits the oscillation amplitude, to avoid overdriving the crystal. The transistor operates continuously in a linear mode over a



Figure **B.2**. Emitter coupled harmonic circuit at 20 MHz.

complete cycle of oscillation, and reflects a reasonably constant load across the crystal at all instants of time. Fig. B.3 shows the oscillation waveforms at various points in the circuit. The calculated gain and phase characteristics for the oscillator's entire closed loop in Fig. B.2 are shown in Fig. B.4. Note the steep phase change with frequency, an indication of good frequency stability.

The circuit values in Fig. B.2 are derived as follows. The transistor's gain is proportional to the ratio of the collector's load impedance to the emitter's load impedance. At the crystal's series resonant frequency, the gain is approximated by the ratio  $R_1/R_s$ , where  $R_1$  is the collector's load resistance and  $R_s$  is the crystal's internal resistance.  $R_s$  is fixed by the crystal and the operating frequency.  $R_1$  is selected as a ratio to  $R_s$  so as to provide enough gain for the circuit to oscillate.  $L_1$  is selected to have a high shunt impedance with respect to  $R_1$  and still resonate at or just below the oscillation frequency with a reasonable-sized variable capacitor  $C_1$ .  $R_2$  is selected to provide a relatively high load resistance to  $C_1$ .

The capacitive impedance of  $C_2$  is reflected across the crystal by the transistor's emitter, multiplied by the transistor's current gain  $H_{FE}$ . To provide a low impedance load and high Q for the crystal,  $C_2$  should be as large as possible, consistent with  $R_2C_2$  providing a large phase lag without too much gain loss.  $R_3$  controls the transistor's DC current, which is conveniently adjusted to set the transistor's DC collector voltage at half the power supply voltage. At low frequencies, the **2N5179** transistor in Fig. B.2 is a good selection. At 50 MHz and above, the higher gain of the MMT3960 is needed.



Figure **B.3.** Waveforms for 20 MHz oscillator circuit in Fig. B.2.

The actual external load network seen by the crystal's resonant elements is shown in Fig. **B.5a**. This load network needs to be simplified down to an equivalent series RC network, such as is shown in Fig. **B.5b** for calculating the crystal's in-circuit Q. The crystal's electrode capacitance  $C_o$  is included as part of the load on the crystal's resonant elements in Fig. **B.5a**. The transistor's current gain  $H_{FE}$  is 30 (minimum), and reflects the 22 pf capacitance of  $C_2$  as 660 pf across the crystal, in series with the transistor's internal emitter resistance  $r_e$ . The transistor's emitter resistance  $r_e$  (4 ohms) is calculated in the traditional way of dividing the nominally constant internal emitter voltage drop of 30 mV by the actual emitter current, 7.5 ma. Fig. **B.5b** shows the equivalent series RC values of the total load on the 20 MHz crystal in Fig. B.2 is 3.9 ohms and 665 pf.

Fig. B.6 shows a 50 MHz circuit, also operating on the third harmonic. To maintain the transistor's gain, note that the collector's load resistance  $R_1$  has been increased to compensate for the increase in the crystal's internal series resistance  $R_s$ . The crystal's internal series resistance  $R_s$  is 30 ohms, and its electrode shunt capacitance  $C_o$  is 4.2 pf. The transistor's current gain



Figure B.4. Calculated loop gain and phase characteristics for circuit in Fig. B.2.



Figure B.5. External load seen by crystal's resonant elements in 20 MHz circuit: (a) actual load, (b) equivalent series RC load.

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Figure **B.6.** Emitter coupled harmonic oscillator at 50 MHz.

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 $H_{FE}$  is 100 (minimum), and reflects the 10 pf capacitance of  $C_2$  as 1000 pf across the crystal, in series with the transistor's internal emitter resistance  $r_e$ . The transistor's internal emitter resistance  $r_e$  is 30 mV/5.3 ma = 5.6 ohms. Using the same technique as shown in Figs. B.5a & b for the 20 MHz circuit, the equivalent series RC load seen-by the 50 MHz crystal in Fig. B.6 is 5.55 ohms  $(R_s)_{\text{load}}$  and 991 pf  $(C_s)_{\text{load}}$ .

Fig. B.7 shows a 100 MHz oscillator, operating on the fifth harmonic.



Figure B. 7. Emitter coupled harmonic oscillator at 100 MHz.

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Again to maintain the transistor's gain, the collector's load resistance  $R_1$  has been increased, to compensate for the increase in the crystal's internal series resistance  $R_1$ . This undesirable increase in  $R_1$  as the frequency increases is a design drawback to the Emitter coupled harmonic circuit, and forms an upper frequency limit of about 100 MHz for good circuit operation. From shunt capacitance considerations, it would be better to reduce  $R_1$  as the frequency is increased.

An extra capacitor  $C_3$  has been added to the 100 MHz circuit in Fig. B.7, from the transistor's collector to ground. Capacitor  $C_3$  is needed at frequencies above 50 MHz to tune out the shunting effect of inductor  $L_1$  on load resistor  $R_1$ , so as to maintain a high load resistance for the transistor and get enough gain for oscillation.

The 100 MHz crystal's internal series resistance  $R_s$  is 40 ohms, and its electrode shunt capacitance  $C_o$  is 5.7 pf. The transistor's current gain  $H_{FE}$  is 100 (minimum), and reflects the 2 pf capacitance of  $C_2$  as 200 pf across the crystal, in series with the transistor's internal emitter resistance  $r_e$ . The transistor's internal emitter resistance  $r_e$  is 30 mv/3.7 ma = 8.2 ohms. Using the same parallel to equivalent series load technique as shown in Fig. B.5, the equivalent series load across the 100 MHz crystal in Fig. B. 7 is 7.7 ohms  $(R_s)_{\text{load}}$  and 199.9 pf  $(C_s)_{\text{load}}$ . The power dissipated in the crystal is less than 0.3 milliwatts.

#### B. 3. PERFORMANCE

The three Emitter coupled harmonic circuits all perform very well. The waveform at the crystal is good. The circuits are relatively independent of changes in the 5V power supply, changing 2 ppm or less for a 2 volt supply



Figure B.8. Alternate digital buffer amplifier for driving TTL.

change (4V to 6V). There are no parasitic effects when a good circuit layout is used.

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A crystal's in-circuit Q is less than the crystal's internal Q by the ratio of the crystal's internal resistance  $R_s$  to the sum of the crystal's internal resistance  $R_s$  plus its equivalent series load resistance  $(R_s)_{load}$ , ie,  $R_s/(R_s + [R_s]_{load})$ . At 20 MHz, the crystal's in-circuit Q is 14/(14 + 3.9) or 78% of the crystal's internal Q. At 50 MHz, the crystal's in-circuit Q is 30/(30 + 5.5) or 85% of the crystal's internal Q. And at 100 MHz, the crystal's in-circuit Q is 40/(40 + 7.7) or 84% of the crystal's internal Q. These are relatively high in-circuit Qs, which should give good short term frequency stability, and they do. The short term stability of the three circuits measured 0.1 ppm, at the limit of available measuring equipment. This stability is better than that of any other harmonic circuit tested.

### **B.4. APPLICATIONS**

The isolation buffer amplifiers shown with the oscillators in Figs. B.2, B.6, & B. 7 are intended for sine wave output. An alternate digital buffer amplifier for driving CMOS or TTL circuitry at frequencies up to 100 MHz is shown in Fig. B.8. At frequencies below 50 MHz, a 2N5179 transistor can be substituted for the MRF904 in Fig. B.8.

In general, harmonic oscillator circuits do not have a wide frequency trimming range. The frequency can be trimmed by changing any of the phase leads or lags in an oscillator circuit. The frequency in Figs. B.2, B.6, & B.7 is trimmed by adjusting  $C_1$ , and is limited to 5-15 ppm maximum adjustment. This can be increased to 25-60 ppm by putting a 35 pf variable capacitor in series with the crystal, and using it to trim the frequency. Above about 70 MHz, putting a variable frequency trimming capacitor in series with the crystal to get a wider trimming range also requires putting a small inductor directly across the crystal to resonate with the crystal's electrode capacitance  $C_{\varrho}$  and tune  $C_{\varrho}$  out of the circuit.

One side of the crystal is tied to ground in the Emitter coupled harmonic circuit. This makes it easy to put a varactor in series with the crystal, if desired, and operate the circuit as a voltage controlled oscillator (VCO). The maximum amount (in ppm) that a harmonic crystal oscillator can be pulled away from its normal oscillation frequency is limited, being inversely proportional to the order of the harmonic used.

## APPENDIXC

# FEEDBACK BRIDGE CIRCUIT

### C.I. CONCEPT

The Feedback bridge is a simplified version of a circuit first described by Benjaminson [23]. The basic simplified circuit is shown in Fig. C.1. The crystal's internal series resistance  $R_s$  and resistors  $R_1$ ,  $R_2 \& R_{load}$  form the four arms of a bridge. The  $L_1C_1$  tank is series resonant at the frequency of oscillation, and converts the square wave output of transistor amplifier  $Q_1$ back into a sine wave, just as the resonant spring-mass elements within the crystal do. The  $L_1C_1$  tank deliberately has a much lower Q than that of the crystal. At series resonance, the phase of the crystal's output voltage at point D is in-phase with the crystal's input drive voltage at point C. If the oscillation frequency moves away from series resonance, the phase of the output voltage at point D will either lead or lag the input drive voltage at point C, depending on whether the frequency moves down or up.

In Fig. C.l, the crystal and  $R_{\text{load}}$  form a voltage divider across the amplifier's output, and provide positive feedback to one of the amplifier's input terminals, the emitter of transistor  $Q_1$ . Resistor  $R_{\text{load}}$  is also the crystal's load resistor, and for maximum in-circuit Q it should be kept small with respect to the crystal's internal series resistance  $R_{\text{i}}$ .

Bridge arms  $R_1 \& R_2$  form a second voltage divider that provides negative feedback to the amplifier's other input terminal, the base of transistor  $Q_1$ . The negative feedback at point *B* is always in-phase with the amplifier's output square wave at point *C*, because the crystal's high *Q* holds the oscillation frequency at the center of  $L_1C_1$ 's passband, where the phase shift through  $L_1C_1$  is zero.

The advantage of a bridge circuit is that it can make the crystal's in-circuit Q higher than the crystal's own internal Q, thereby increasing the short



Figure C. 1. Basic circuit of simplified Feedback bridge oscillator.  $L_1C_1$  is resonant at frequency of oscillation.

term frequency stability. It does this by operating the crystal at series resonance, and subtracting out part of the crystal's resistive in-phase signal at the amplifier's input. The effect electronically increases the crystal's internal Q, which also reduces the short term frequency drift.

The crystal's in-circuit Q increases as more and more of the crystal's resistive in-phase signal is cancelled out. The subtraction of the two signals also reduces the net amplifier gain, so that the increase in in-circuit Q is limited by the amplifier gain available, which still has to exceed one around the amplifier loop for oscillation to occur. The characteristics of bridge circuits are discussed further in the sections on the Meacham and RLC half-bridge circuits.

### C.2. DESIGN

A Feedback bridge circuit at 1 MHz is shown in Fig. C.2. Fig. C.3 shows the waveforms at various points in the circuit of Fig. C.2. As Fig. C.2 shows, two emitter followers ( $Q_2$  and  $Q_3$ ) have been added to the basic circuit.  $Q_3$ lowers the source resistance  $R_o$  driving the crystal to 18 ohms. And  $Q_2$  isolates the crystal and its load resistor  $R_{\text{load}}$  from the negative feedback signal at point **B**, which also shows up by transistor action at  $Q_1$ 's emitter. The output impedance of emitter follower  $Q_2$  is made much lower than that of  $Q_1$ , so that the AC voltage on  $Q_1$ 's emitter is primarily controlled by the crystal's output voltage.

Amplifier stage  $Q_1$  has a 40" phase lag in it, partly because of the two collector to base capacitances (3.5 pf/each) across its collector load resistor  $R_3$ , and partly because of the large resistance value used for  $R_3$  to get a large

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Figure C.2. Feedback bridge at 1 MHz.

amplifier gain. To let the crystal operate exactly at series resonance, the amplifier's 40" phase lag is reduced to zero by putting a small capacitor  $C_2$  across bridge resistor  $R_2$ . The amplifier's phase lag could also have been eliminated by detuning C, slightly off series resonance with  $L_1$ , but this sometimes generates a parasitic oscillation.

### C.3. PERFORMANCE

The Feedback bridge gives outstanding performance. The crystal waveforms are good, and the frequency changes only 1 ppm when the power supply voltage is changed by 2 volts (4V to 6V). Its short term stability measured **0.1** ppm (or better), at the limit of available measuring equipment.



Figure C.3.

Transistor  $Q_1$  provides an in-phase gain of  $28(\cos 40^\circ)$  or 21X from emitter to collector. At series resonance, the amplifier's in-phase loop gain through the positive feedback bridge arms from point A to point **D** and back to point A is 5.9X. This is reduced by the amplifier's in-phase loop gain of 2.8X through the negative feedback bridge arms from point A to point B and back to point A, leaving a net positive loop gain for oscillation of 3.1X. The 2.8X gain reduction indicates how much of the crystal's total in-circuit resistance is being cancelled out, and therefore indicates how much the in-circuit Q is being improved. Without negative feedback, the circuit's short term stability

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measures 0.1 ppm. Dividing this by the 2.8 gain reduction of the negative feedback indicates that the short term stability with negative feedback should be .04 ppm, which is beyond the 0.1 ppm limit of the available test equipment.

To experimentally determine whether the electronic Q improvement is really there, the crystal's in-circuit Q was decreased by 10X, so as to reduce the circuit's short term stability down to something measurable with the available test equipment. The in-circuit Q was reduced in Fig. C.2 by inserting a 9 x (240 + 18) = 2322 ohm resistor in series with the crystal to increase its resistive losses 10 times, and by increasing the crystal's load resistor  $R_{load}$  from 100 ohms to 1000 ohms. With the negative feedback loop open (bridge arm  $R_1$  disconnected at  $L_1$ ), the short term stability measured 0.3 ppm. With the negative feedback loop closed, the short term stability improves to 0.1 ppm. This 3X improvement in in-circuit Q by electronic means agrees reasonably well with the calculated 2.8X improvement, and shows that the concept of electronically subtracting out part of the crystal's in-circuit resistance does improve the in-circuit Q.

The improvement in short term stability is limited by the amplifier gain. Adding a second amplifier stage would improve the circuit's short term stability considerably, but at the cost of increasing the parts count.

To calculate the crystal's in-circuit Q, the series equivalent of the parallel load on the crystal is needed, as shown in Figs. C.4a & b. From Fig. C.2, the external load seen by the crystal's internal resonant elements  $L_x$  and  $C_x$ 



Figure C.4. (a) actual circuit load on the crystal's resonant elements, and (b) the equivalent series RC load on the crystal.

is approximated in Fig. C.4a by the parallel RC combination of the crystal's electrode shunt capacitance  $C_o$  (5 pf) with the sum of the crystal's load resistor  $R_{\text{load}}$  (100 ohms) and the crystal's driving source resistance  $R_o$  (18 ohms). Fig. C.4b shows that the equivalent series RC load on the crystal is 117.9 ohms and .364 mfd. This gives an in-circuit Q without negative feedback of  $R_s/(R_s + [R_s]_{\text{load}}) = 240/(240 + 117.9)$  or .67 of the crystal's internal Q. Multiplying this by the 2.8X gain reduction of the circuit's negative feedback gives an in-circuit Q with negative feedback of .67 × 2.8 or 1.9 times the crystal's internal Q.

The .364 mfd of equivalent series load capacitance  $(C_s)_{\text{load}}$  is in series with the crystal's internal capacitance  $C_x$  of .00603 pf, and changes the crystal's resonant frequency proportionately. The crystal's resonant frequency will increase as the square root of the ratio of the original capacitance  $C_x$  to the two capacitances combined in series, or equivalently, to the square root of one plus the ratio of the two capacitances, which is  $(1 \text{ MHz})[1 + (.00603 \times 10^{-12})/(.364 \times 10^{-6})]^{1/2} = .008 \text{ Hz}$ . This is a negligible increase in the crystal's series resonant frequency.

The Feedback bridge can of course be used at other frequencies, assuming appropriate circuit changes are made. At a higher frequency such as 10 MHz, for example, an emitter follower would need to be added after  $Q_3$  to lower the crystal's drive resistance  $R_o$  to a value less than the crystal's 5 to 10 ohm internal series resistance  $R_s$  at 10 MHz. And something would have to be done to reduce amplifier  $Q_1$ 's phase shift, like using an LC tank (detuned off resonance) for the collector load on amplifier  $Q_1$ . At a lower frequency such as 100 kHz, the phase correcting capacitor  $C_2$  probably would not be needed, which would usefully increase the amplifier's in-phase gain.

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